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DEPARTMENT OF ELECTRONICS AND TELECOMMUNICATION ENGINEERING

LECTURE NOTES

Year & Semester: 3RD Year, V Semester

Subject Code/Name: TH-2, VLSI & EMBEDDED SYSTEM

UNIT-1 INTRODUCTION TO VLSI & MOS TRANSISTOR

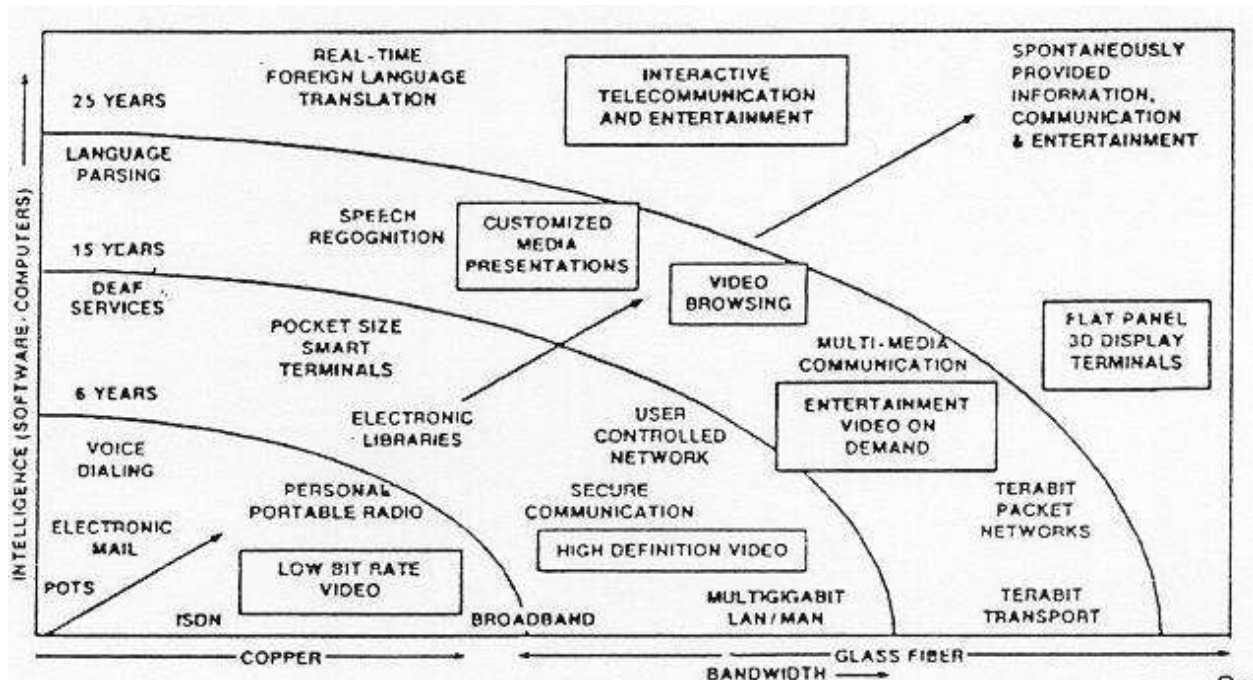
HISTORICAL PERSPECTIVE- INTRODUCTION-

The electronics industry has achieved a phenomenal growth over the last two decades, mainly due to the rapid advances in integration technologies, large-scale systems design - in short, due to the advent of VLSI. The number of applications of integrated circuits in high-performance computing, telecommunications, and consumer electronics has been rising steadily, and at a very fast pace.

The current leading-edge technologies (such as low bit-rate video and cellular communications) already provide the end-users a certain amount of processing power and portability. This trend is expected to continue, with very important implications on VLSI and systems design.

One of the most important characteristics of information services is their increasing need for very high processing power and bandwidth (in order to handle real-time video, for example).

The other important characteristic is that the information services tend to become more and more personalized (as opposed to collective services such as broadcasting), which means that the devices must be more intelligent to answer individual demands, and at the same time they must be portable to allow more flexibility/mobility.



As more and more complex functions are required in various data processing and telecommunications devices, the need to integrate these functions in a small system/package is also increasing. The level of integration as measured by the number of logic gates in a monolithic chip has been steadily rising for almost three decades, mainly due to the rapid progress in processing technology and interconnect technology.

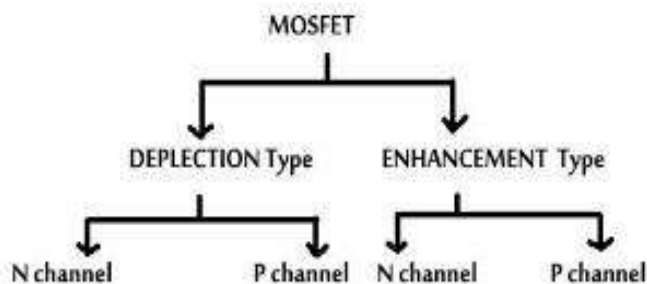
	YEAR	COMPLEXITY (number of logic blocks per chip)
Single transistor	1959	less than 1
Unit logic (one gate)	1960	1
Multi-function	1962	2 - 4
Complex function	1964	5 - 20
Medium Scale Integration (MSI)	1967	20 - 200
Large Scale Integration (LSI)	1972	200 - 2000 Very Large Scale
Integration (VLSI)	1978	2000 - 20000 Ultra Large Scale Integration
(ULSI)	1989	20000 - ?

The logic complexity per chip has been (and still is) increasing exponentially. The monolithic integration of a large number of functions on a single chip usually provides:

- Less area/volume and therefore, compactness
- Less power consumption
- Less testing requirements at system level
- Higher reliability, mainly due to improve on-chip interconnects
- Higher speed, due to significantly reduced interconnection length □ Significant cost savings

INTRODUCTION TO MOS TRANSISTOR & BASIC OPERATION OF MOSFET-

- The MOSFET transistor is a semiconductor device is used for switching and amplifying signals in the electronic devices.
- The full form of MOSFET is Metal Oxide Semiconductor Field Effect Transistor. The MOSFET is a four terminal device with Source (S), Gate (G), Drain (D) and Body (B) terminals.
- The body of the MOSFET is frequently connected to the source terminal. So, making it a three terminal device.
- The MOSFET works by applying voltage at gate terminal, which is used to control the flow of current within the device.
- Types of MOSFET-



- Enhancement type MOSFET- When there is no channel present at zero gate bias is known as enhancement type MOSFET.

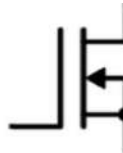


MOSFET: N-Channel
Enhancement Type



MOSFET: P-Channel
Enhancement Type

- Depletion type MOSFET- When there is a channel present in a MOSFET at zero gate bias is known as depletion type MOSFET.



MOSFET: N-Channel
Depletion Type

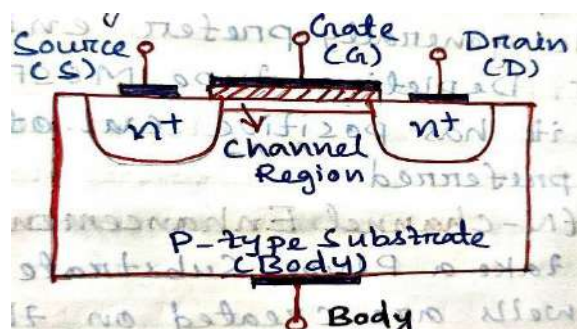


MOSFET: P-Channel
Depletion Type

- We generally prefer enhancement type MOSFET. Depletion type MOSFET conducts at 0V and it has positive cut off gate voltage so less preferred.

NMOS-

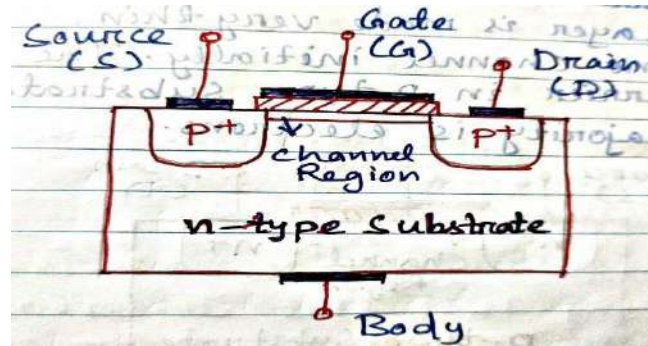
- First take a P-type substrate. After this two n-type wells are created on the p-type substrate. Out of two n wells one act as source and the other act as drain.
- The gate terminal formed between source and drain. A SiO_2 layer is exist between gate terminal and substrate.
- Initially V_{GS} is kept 0V. Whenever we apply +ve voltage at the gate terminal, then the holes which are near this oxide layer will be pushed away and at the same time, the electrons will get attracted towards the gate terminal.
- As we keep increasing this voltage V_{GS} means gate voltage, then the holes will be pushed more and more deep in the substrate. The electrons will start accumulating near this oxide layer.
- The inversion layer of free electrons will get created near this oxide. This inversion layer will act as a channel between this drain and the source.
- If we apply the voltage between this drain and the source terminal, then the current can flow through this channel.



PMOS-

- First take a n-type substrate. After this two p-type wells are created on the n-type substrate. Out of two p wells one act as source and the other act as drain.
- The gate terminal formed between source and drain. An oxide layer will be formed between gate terminal and substrate.

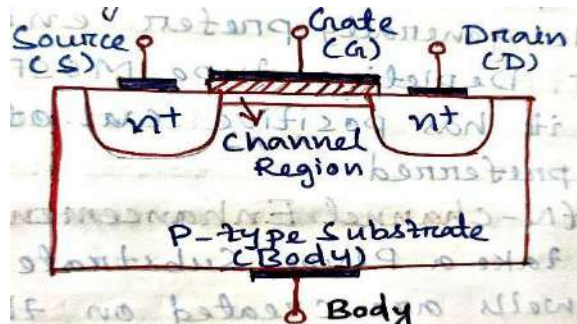
- In PMOS we apply $-ve$ voltage at the gate terminal, because of that the electrons which are near this oxide layer will be pushed away and at the same time the holes will get attracted towards the gate terminal.
- As we keep increasing this voltage V_{GS} , then the electrons will be pushed more and more deep in the substrate. The holes will start accumulating near this oxide layer.
- The inversion layer of holes will get created near this oxide. This inversion layer will act as a channel between this drain and source.
- If we apply the voltage between the drain and the source terminal, then current can flow through this channel.



STRUCTURE AND OPERATION OF MOSFET (NMOS ENHANCEMENT TYPE)-

Structure-

- First take a P-type substrate. After this two n-type wells are created on the P-type substrate. Hence here two junctions formed between P and N type semiconductor. So, depletion layer formed at these junctions.
- Out of two n wells, one act as source and the other act as drain. The gate terminal formed between source and drain. A silicon oxide layer is present between gate terminal and substrate. So, there is no direct contact between gate and substrate.
- SiO_2 layer is very thin. This is known as gate oxide. Gate controls the movement of charge carrier near the surface of substrate. So, that the oxide layer is made very thin.
- There is no channel initially. The majority charge carrier in P-type substrate is holes and the majority is electrons.

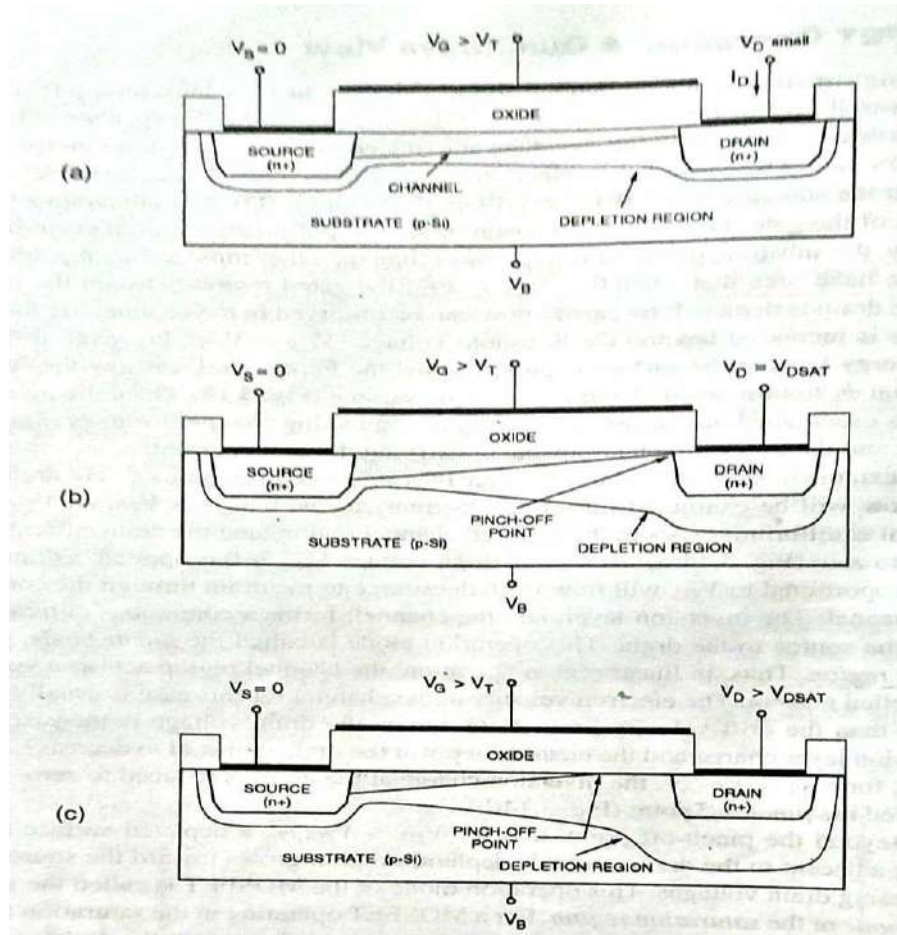


Operation-

Initially V_{GS} is kept 0V. The substrate and the source terminals are connected together and they are connected to the ground terminal.

Assume that $V_{ds} = 0$.

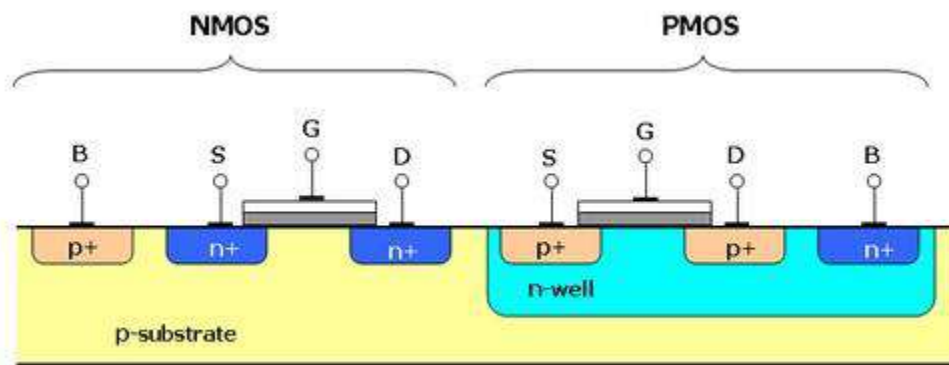
- Whenever we apply the +ve voltage at this gate terminal, then the holes which are near this oxide layer will be pushed away from this gate and at the same time, the electrons get attracted towards this gate terminal.
- As we keep on increasing this voltage V_{gs} , then the holes will be pushed more and more deeper in the substrate and the electrons will be accumulated near the substrate surface of gate terminal.
- The inversion layer of free electrons will get created near the oxide. This inversion layer will act as a channel between this drain and source.
- If we apply the voltage between this drain and source terminal, then the current can flow through this channel.
- The value of the V_{gs} at which this inversion layer is created is known as the threshold voltage. Below this threshold voltage, there will not be any flow of current through the MOSFET.
- Whenever the V_{gs} is greater than this threshold voltage, then the width of the channel increases. Along with this channel, there will also be a depletion layer around this channel. When we apply the voltage V_{ds} , then through the channel electrons get attracted towards this positive terminal and in this way, the current will establish in this way, the current will establish in this circuit.
- As we keep on increasing V_{ds} , then at one particular voltage, the pinch off condition will occur. At that particular voltage, the drain current which is flowing through the circuit will get saturated.
- The voltage V_{ds} , at which this pinch off condition occurs is known as the saturation voltage and this saturation voltage can be expressed as $V_{gs} - V_t$.
- For the fixed value of V_{gs} , if we further increase the value of V_{ds} the voltage difference between the gate and drain terminal will be even lesser than this threshold voltage and due to that, the channel will not get formed towards the drain terminal. So, it appears that the current through the channel should become zero.
- But actually still the current will flow through this channel and this current I_d will get saturated. Because the electrons which are passing through this channel can still be able to cross this depletion layer due to the electric force.
- Even if we increase the drain voltage, the current through this circuit will remain almost constant.



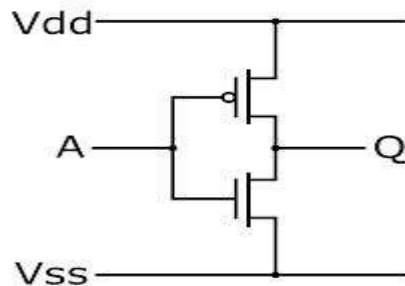
a) Operating in the linear region, b) operating at the edge of saturation and c) operating beyond saturation

CMOS-

- CMOS stands for Complementary Metal Oxide Semiconductor. CMOS transistor consists of PMOS and NMOS. NMOS consists of N-type source and drain on a P type substrate. When a high voltage is applied to the gate, the NMOS will conduct and when a low voltage is applied to the gate, NMOS will not conduct.



- PMOS consists of P-type source and drain on an N-type substrate. When a high voltage is applied to the gate, the PMOS will not conduct. When a low voltage is applied to the gate, the PMOS will conduct.
- CMOS use same signal which turns on a transistor of one type and turn off a transistor of the other type.
- Lets see a simple CMOS inverter.

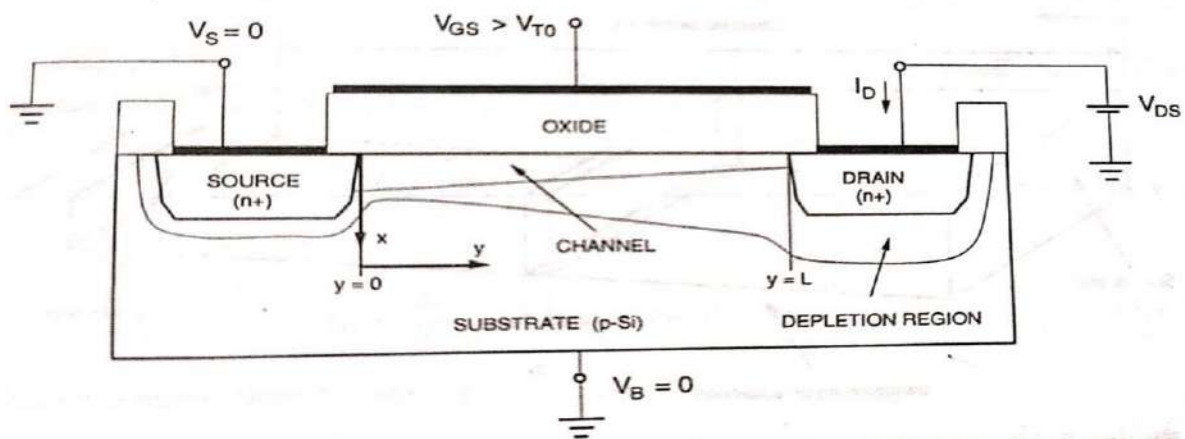


- In CMOS inverter PMOS is connected to V_{DD} and the NMOS is connected to ground. The gate terminals of both NMOS and PMOS are connected together and act as the input terminal.
- The drains of both are connected together and act as the output terminal. The inverter has only two states. For a high input, the output is low and for a low input, the output is high.
- There is never a short circuit between V_{DD} and ground because in either state only one MOS transistor is conducting while the other is off.

MOSFET V-I CHARACTERISTICS-

Gradual Channel Approximation-

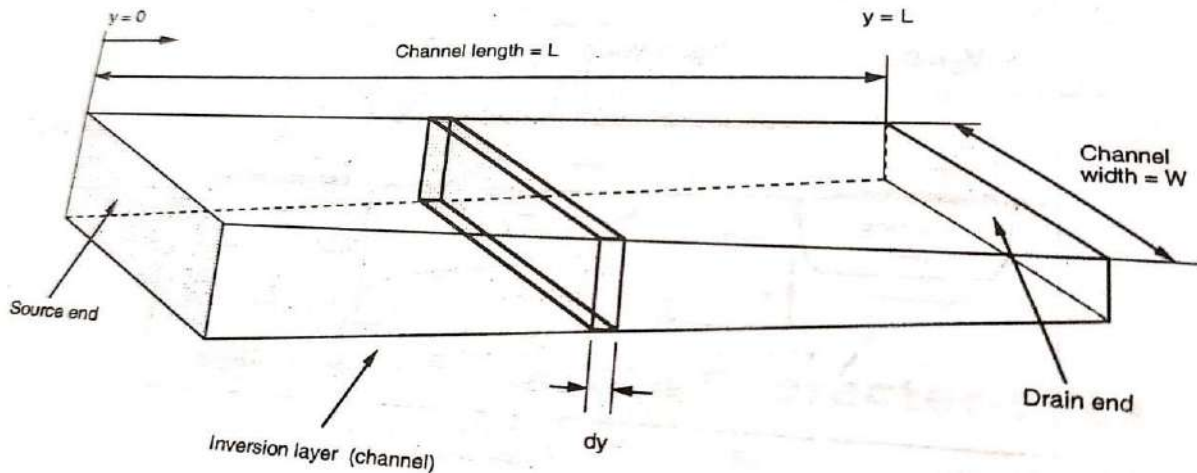
- We use the gradual channel approximation for establishing the MOSFET current voltage relationship.
- Using this method we find out the drain current I_D in linear region and saturation region.
- When gradually V_{DS} increases than V_{DSAT} the channel length in MOSFET starts to decrease. So another method named channel length modulation is used to find out the drain current with this new channel length.
- Consider the cross sectional view of the n-channel MOSFET operating in linear mode.



- $V_S = V_B = 0$

- $V_{GS} > V_{TO}$
- Assume the coordinate system such that x -direction is perpendicular to the surface and the y-direction is parallel to the surface.
- Assume that electric field component in y-direction is dominant compared to x direction.
- The channel voltage is denoted by $V_c(y)$.
- At $y=0$, the $V_c(y = 0) = V_s = 0$.
- At $y=L$, the $V_c(y = L) = V_{DS}$.
- Let $Q(y)$ is the mobile electron charge in channel-

$$Q(y) = -C_{ox}[V_{GS} - V_c(y) - V_{TO}]$$



- Net voltage is

$$Y=0, V = V_{GS} - V_{TO}$$

$$Y=L, V = V_{GS} - V_{DS} - V_{TO}$$

- Calculate the incremental resistance dR

$$dR = - \frac{dY}{W\mu_n Q(y)}$$

The above equation derived from a Basic resistance formula is-

$$R = \rho \frac{L}{A} = \frac{1}{\sigma} \frac{L}{wt} = \frac{L}{w[q(n\mu_n + p\mu_p)]} = \frac{L}{Wq n \mu_n} = \frac{L}{W\mu_n Q(y)}$$

Calculate the drain current by using the ohm's law

$$I_D dR = -W \frac{dV_c}{\mu_n Q(y) dy}$$

$$\Rightarrow I_D dy = -W\mu_n q(y) dV_c$$

Then integrate the both side

$$\int_0^L I_D dy = -W\mu_n q \int_0^{V_{DS}} dV_c$$

$$\Rightarrow \int_0^L I_D dy = - \int_0^{V_{DS}} W \mu_n Q(y) dV_c$$

$$\Rightarrow I_D [L - 0] = -W \mu_n \int_0^{V_{DS}} Q(y) dV_c$$

$$\Rightarrow I_D L = -W \mu_n \int_0^{V_{DS}} -C_{OX} (V_{GS} - V_c(y) - V_{TO}) dV_c$$

$$\Rightarrow I_D L = W \mu_n C_{OX} \int_0^{V_{DS}} (V_{GS} - V_c(y) - V_{TO}) dV_c$$

$$\Rightarrow I_D = \frac{1}{L} \frac{n_{ox}}{2} [2(V_{GS} - V_{TO})V_{DS} - \frac{1}{2} V_{DS}^2]$$

If we take $\mu_n C_{OX} = K'$

$$\text{Then } I_D = \frac{K' W}{2L} [2(V_{GS} - V_{TO})V_{DS} - \frac{1}{2} V_{DS}^2]$$

➤ Again if we take $K'^W = K_L$

$$\text{Then } I_D = \frac{K_L}{2} [2(V_{GS} - V_{TO})V_{DS} - \frac{1}{2} V_{DS}^2]$$

➤ But when $V_{DS} = V_{DSAT}$,

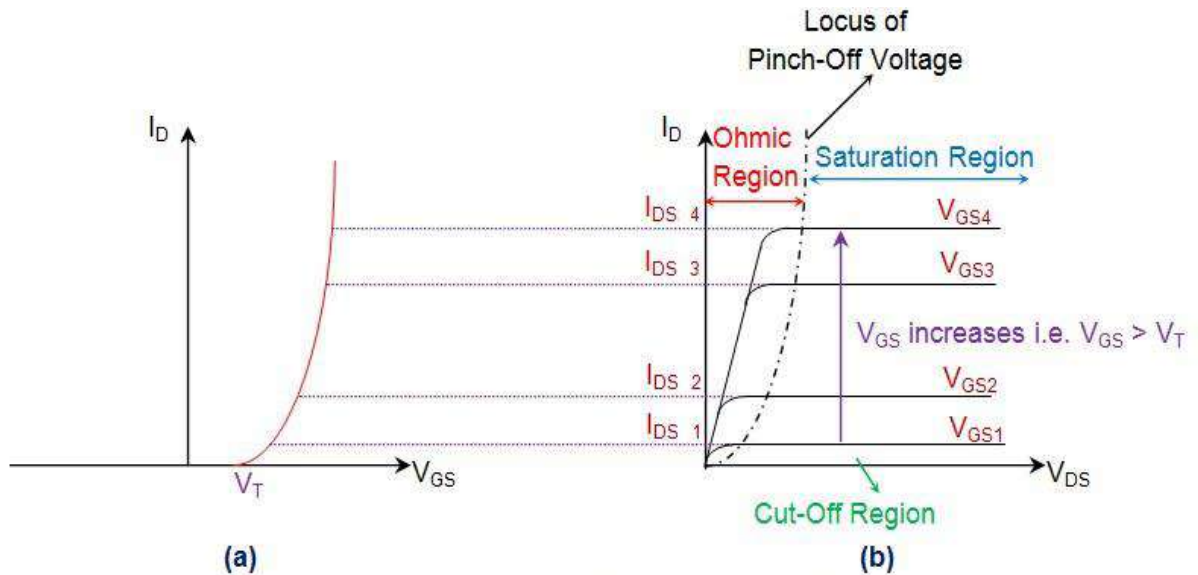
$$V_{DS} = V_{GS} - V_{TO}$$

After substituting the value of V_{DS} in drain current equation, we get

$$I_D = \frac{W}{L} \frac{\mu_n C_{OX}}{2} [2(V_{GS} - V_{TO})(V_{GS} - V_{TO}) - (V_{GS} - V_{TO})^2]$$

$$= \frac{W}{L} \frac{\mu_n C_{OX}}{2} [2(V_{GS} - V_{TO})^2 - (V_{GS} - V_{TO})^2]$$

$$= \frac{W}{L} \frac{\mu_n C_{OX}}{2} (V_{GS} - V_{TO})^2$$



n-Channel Enhancement type MOSFET (a) Transfer Characteristics (b) Output Characteristics

Channel Length Modulation-

- Channel Length Modulation happens in saturation region.
- Channel length will change with respect to drain voltage of MOSFET.
- Charge density in channel is given by

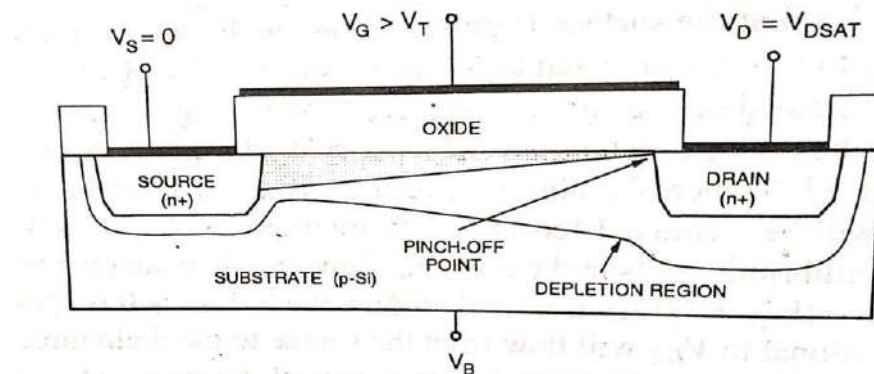
$$Q(y) = -C_{OX}(V_{GS} - V_C(y) - V_{TO})$$

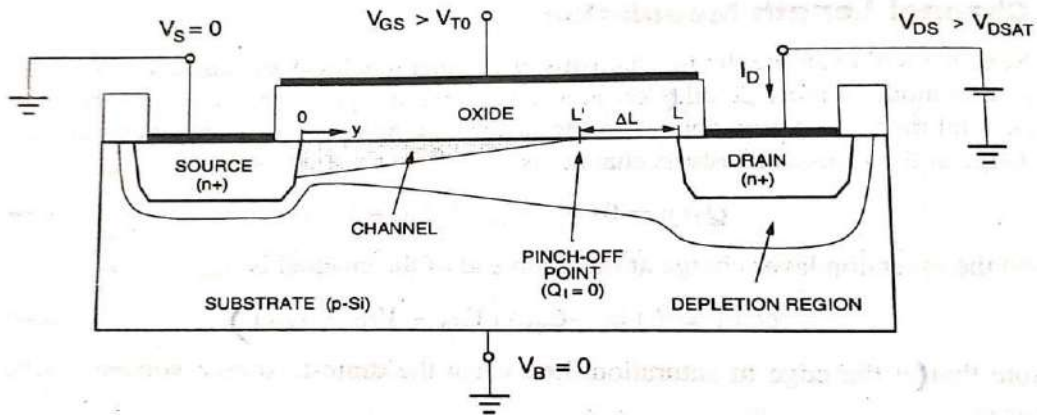
- Inversion layer charge at source $y=0$ end is given by-

$$Q(y=0) = -C_{OX}(V_{GS} - V_{TO})$$

- Inversion layer charge at drain end $y=L$ is given by-

$$Q(y) = -C_{OX}(V_{GS} - V_{DS} - V_{TO})$$





- At the edge of saturation $V_{DS} = V_{DSAT}$

$$V_{DS} = V_{DSAT} = V_{GS} - V_{T0}$$

- Inversion layer charge at drain end ($y=L$) in saturation region is given by-

$$Q(y=L)=0$$

- If we further increase drain voltage beyond this saturation voltage then length of channel will decrease to L' .

- Effective channel length in saturation region will become

$$L' = L - \Delta L$$

- At pinch off point of channel, channel voltage will be V_{DSAT} .

- The $\frac{W}{L'} (V_{GS} - V_{T0})^2$ drain current equation in saturation region with change in channel length is given by- $I_{D(sat)} = \mu_n C_{OX} \frac{W}{L} (V_{GS} - V_{T0})^2$

$$\Rightarrow I_{D(sat)} = \frac{\mu_n C_{OX}}{2} \frac{W}{L - \Delta L} (V_{GS} - V_{T0})^2$$

$$\Rightarrow I_{D(sat)} = \frac{\mu_n C_{OX}}{2} \frac{W}{L} \left(V_{GS} - V_{T0} \right)^2 \left(1 - \frac{\Delta L}{L} \right)$$

Here $\Delta L \propto \sqrt{V_{DS} - V_{DSAT}}$

- To simplify this drain current equation we will take-

$$1 - \frac{\Delta L}{L} = 1 - \lambda V_{DS}$$

λ = Channel length modulation coefficient

➤ So, drain current is given by

$$I_{D(sat)} = \left(\frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TO})^2 (1 - \lambda V_{DS}) \right)$$

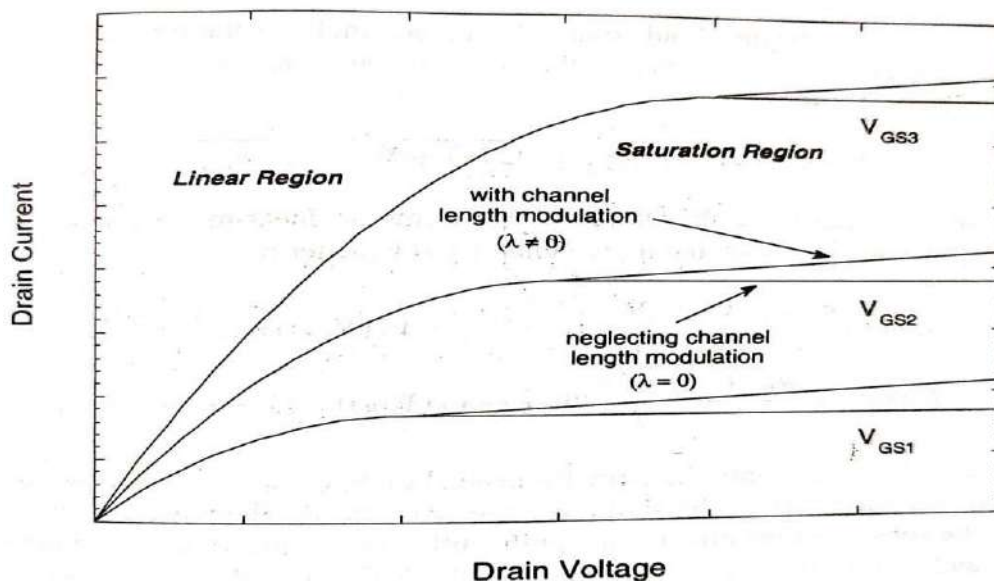
$$\Rightarrow I_{D(sat)} = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TO})^2 (1 + \lambda V_{DS})$$

$$\Rightarrow I_{D(sat)} = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TO})^2 (1 + \lambda V_{DS})$$

➤ Assuming that $\lambda V_{DS} \ll 1$

➤ Hence the equation is -

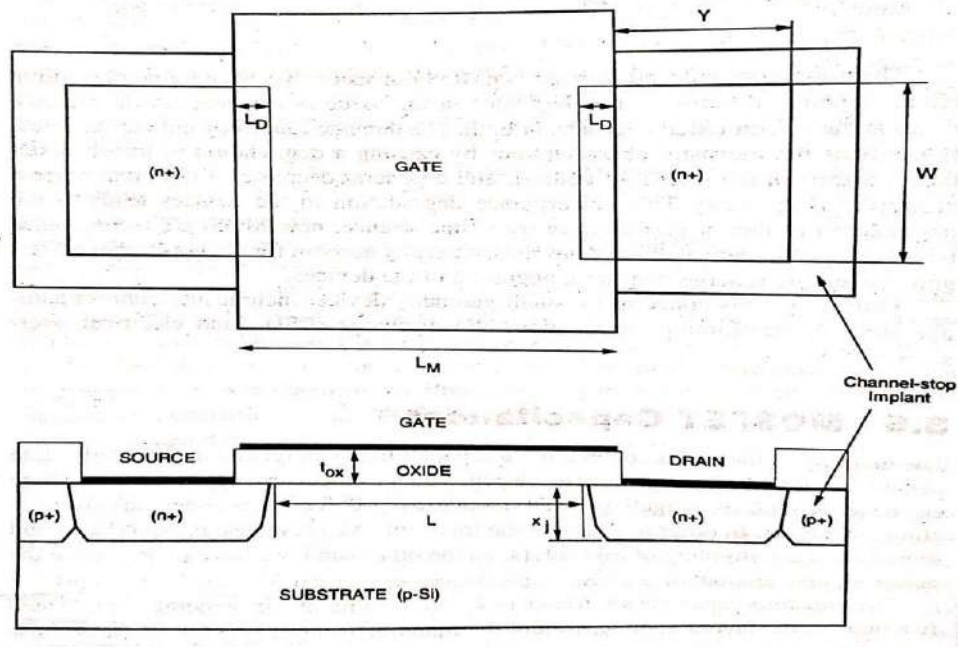
$$I_{D(sat)} = \frac{\mu_n C_{ox} W}{2 L} (V_{GS} - V_{TO})^2 (1 + \lambda V_{DS})$$



MOSFET CAPACITANCES-

The on chip capacitances found in MOS circuits are known as parasitic capacitance. These are unavoidable and unwanted capacitances exists in MOSFET due to its layout geometries and the manufacturing processes.

Most of these capacitances are distributed. Let's take the cross sectional and top view of MOSFET.



The overlap areas in both source and drain side denoted as L_D , they are symmetrical. Both source and drain diffusion regions have a width of W . the diffusion region length is denoted by 'y'.

The both source and drain diffusion region are surrounded by a P doped region, also called the channel stop implant. This channel stop implant region provides the electrical isolation from neighboring devices.

The total length of gate means the mask length is indicated by L_M and the actual length of the channel is denoted by L .

$$L = L_M - 2 \cdot L_D$$

Based on their physical origins, the parasitic device capacitances can be classified into two types-

- 2) Oxide related capacitance
- 3) Junction related capacitance

Oxide related capacitance-

A MOS transistor consists of a gate conductor and a semiconductor (substrate) separated by a gate dielectric.

So, it act as a parallel plate capacitance. Hence the gate oxide capacitance per unit area is given by-

$$C_{ox} = \frac{\epsilon_{ox}}{t_{ox}}$$

$$\text{Where } \epsilon_{ox} = \epsilon_0 \epsilon_r$$

$$\text{Hence } C_{ox} = \frac{\epsilon_0 \epsilon_r}{t_{ox}}$$

$$\epsilon_0 = 8.85 \times 10^{-12} \text{ Fm}^{-1} \quad \epsilon_r =$$

3.9

The two overlap capacitances that arise as a result of this structural arrangement are called $C_{GS(\text{overlap})}$ and $C_{GD(\text{overlap})}$.

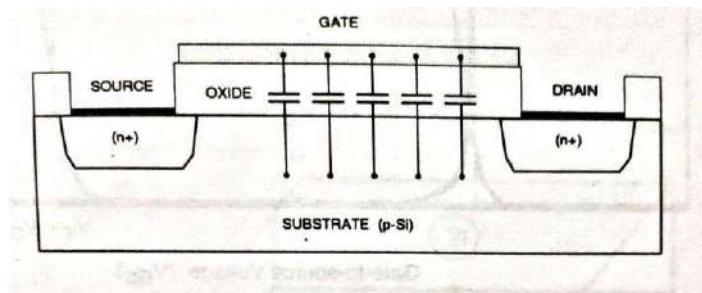
$$C_{GS(\text{overlap})} = C_{ox} W L_D$$

$$C_{GD(\text{overlap})} = C_{ox} W L_D$$

The channel region is connected to the source, drain and substrate. Depending on biasing condition the MOSFET operates in 3 regions i.e, cut off, linear and saturation.

Cut-off Mode-

In this mode there is no channel formed because of that there is no connection present between source and drain. Therefore gate to source and gate to drain capacitances are both equal to zero.



$$C_{gs} = C_{gd} = 0$$

So, the total capacitance is-

$$C_{gs(\text{total})} = C_{gs} + C_{GS(\text{overlap})} = 0 + C_{ox} \cdot W \cdot L_D = C_{ox} \cdot W \cdot L_D$$

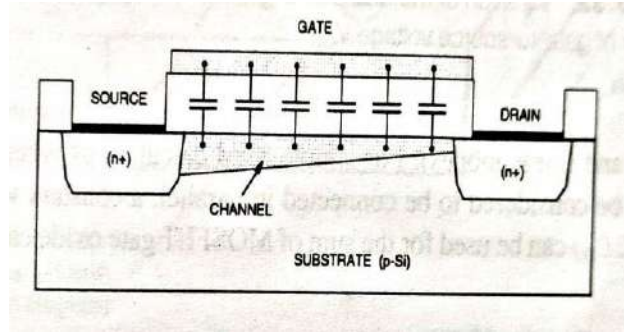
$$C_{gd(\text{total})} = C_{gd} + C_{GD(\text{overlap})} = 0 + C_{ox} \cdot W \cdot L_D = C_{ox} \cdot W \cdot L_D$$

Due to absence of channel there is a direct contact between gate and body.

$$\text{So, } C_{gb} = C_{ox} \cdot W \cdot L$$

Linear Mode-

In this mode there is channel present between source and drain. This inversion layer on the surface cover the substrate and there is no connection between substrate and gate. Thus $C_{gb} = 0$.



$$C_{gb} = C_{gb(total)} = 0$$

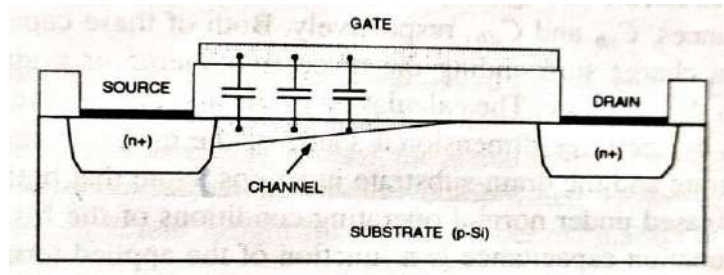
C_{gs} and C_{gb} both are gate to channel capacitance between the source and drain. Hence $C_{gs} \cong C_{gd} \cong \frac{1}{2} C_{ox} \cdot W \cdot L$

$$\text{So, } C_{gs(total)} = C_{gs} + C_{GS(overlap)} = \frac{1}{2} C_{ox} W L + C_{ox} W L_D$$

$$C_{gd(total)} = C_{gd} + C_{GD(overlap)} = \frac{1}{2} C_{ox} W L + C_{ox} W L_D$$

Saturation Mode-

In this mode the inversion layer on the surface does not extend to the drain means it is pinched off.



$$\text{So, } C_{gd} = 0$$

$$C_{gd(total)} = C_{gd} + C_{GD(overlap)} = C_{ox} \cdot W \cdot L_D$$

Since the source is still connected to the conducting channel. So, the $C_{gb} = 0$.

$$C_{gb} = C_{gb(total)} = 0$$

As the channel is present near the source only. So, this part approximated as two-third part of the channel.

$$\text{So, } C_{gs} \cong \frac{2}{3} C_{ox} \cdot W \cdot L$$

$$C_{gs(total)} = C_{gs} + C_{GS(overlap)} = \frac{2}{3} C_{ox} \cdot W \cdot L + C_{ox} \cdot W \cdot L_D$$

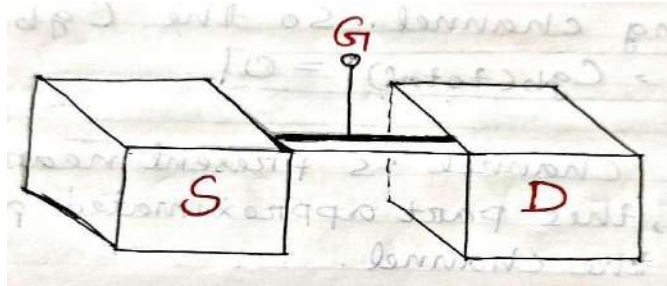
JUNCTION CAPACITANCE-

Whenever we have a PN junction whether or not we apply any voltage across the junction, we always get a depletion region across the junction.

Because of that the n region and P region act as two plates and the depletion region act as dielectric. So, this is the capacitance of the PN junction.

C_{sb} and C_{db} are function of V_{sb} and V_{db} because it modulating the depth of the junction.

Capacitance depends on the depth of the junction, as junction depth increases further and further, as we give reverse bias.



All of these surfaces contribute to the source to body capacitance. The height of the region is 'h', the area of the source is ' A_s ', area of the drain is ' A_D ', the perimeter of the drain is ' P_D ' and the perimeter of the source is ' P_s '.

The area of the junction for the source side is- $A_s + P_s h$

The area of the junction for the drain side is- $A_D + P_D h$

Junction capacitance of source is $C_{js} = (\text{---} A_s + P_s h) \epsilon_{si}$

Junction capacitance of drain is $C_{jd} = (\text{---} A_D + P_D h) \epsilon_{si}$

Where d_j = depth of the junction

ϵ_{si} = Permittivity of the junction

MODELLING OF MOS TRANSISTORS INCLUDING BASIC CONCEPT OF THE SPICE LEVEL MODEL-

- Modeling of MOS device consist of writing a set of equations that link voltages and currents, in order to simulate and predict the behavior of a single device and hence the complete circuit.
- Main aim of the model is to evaluate the current I_p which flows between drain and source, depending on the supply voltages V_D , V_G , V_S & V_B .
- The most popular circuit simulator is SPICE (simulation program with IC emphasis).

- SPICE describes the device with a set of equations that represent the equivalent circuit.
- The basic drain current models are level-1, level-2 & level-3.

Level-1 model equations:-

1. it is the simplest I-V description of MOS which is basically the GCA based model originally concerned by Sah in early 1960s and later developed by Shichman and Hodges.
2. The equation used in level-1 n-channel MOS model in SPICE are –

$$I_D (\text{Linear}) = \mu_n C_{ox} w/L [2(V_{GS} - V_{th})V_{DS} - V_{DS}^2] [1 + \lambda V_{DS}]$$

$$\text{For } V_{GS} \geq V_{TH} \text{ \& } V_{DS} < V_{GS} - V_{TH}.$$

$$I_D (\text{saturation}) = \mu_n C_{ox} w/2L (V_{GS} - V_{th})^2 (1 + \lambda V_{DS})$$

$$\text{For } V_{GS} \geq V_{th} \text{ \& } V_{DS} \geq V_{GS} - V_{th}$$

Where, L is the effective length i.e., $L = L_M - 2L_D$

Where L_m = total length of gate oxide

L_D = length of source & drain extended below oxide & $(1 + \lambda V_{DS})$ is the empirical channel length modulation which is sorting of the length of the inverted channel region with increase in drain voltage. It increases the drain current.

& λ = channel length modulation parameter.

- Thus, level-1 model offers a useful estimate of the circuit performance without using a large no. of device model parameter.

Level-2 model equations:-

- To obtain a more accurate model for drain current, it is necessary to eliminate some of the simplifying assumption in GCA analysis.
- Considering depletion charge and its dependence on channel voltage, the drain current-

$$I_D = \frac{\mu_n C_{ox} W}{(1 - \lambda V_{DS}) L} \left\{ (V_{GS} - V_{FB} - (2\phi_F) - V_{DS}/2) V_{DS} - \frac{2}{3} Y [V_{DS} - V_{BS} + |2\phi_F|] \right\}^{3/2}$$

Where, V_{FB} = Flat band voltage (ie; flat energy band in the semiconductor when a voltage is applied at gate).

ϕ_F = Fermi potential describes the carrier concentration in the semiconductor.

V_{BS} = Substrate to Source Voltage .

Y = Substrate bias coefficient.

- The saturation is reached when the channel charge at the drain end is Zero.
- The saturation voltage:-

$V_{DSAT} = V_{GS} - V_{FB} - |2\phi_F| + Y^2[1 - \sqrt{1 - 2/Y^2(V_{GS} - V_{FB})}]$ &
saturation mode current is :-

$$I_D = I_{DSAT} / (1 - \lambda V_{DS})$$

Where I_{DSAT} is saturated using $V_{DS} = V_{DSAT}$.

- Level 2 model generates more accurate results than Level 1, but its accuracy is still not sufficient to achieve good experimental data for short & narrow channel MOS.

Level 3 model equations:-

- Level 3 has been developed for simulation of short channel MOS.
- It can represent the characteristics of MOS for channel length $> 2\mu m$.
- The I-V equation are calculated same as Level 2.
- However the Current equation in linear region has been simplified using Taylor Series expansion which is more approx than level 2 model.
- Level 3 model equation are mainly empirical bias it improves the accuracy of model & limit the complexity of calculation and also the amount of required simulation time.
- The drain current in linear region is:-

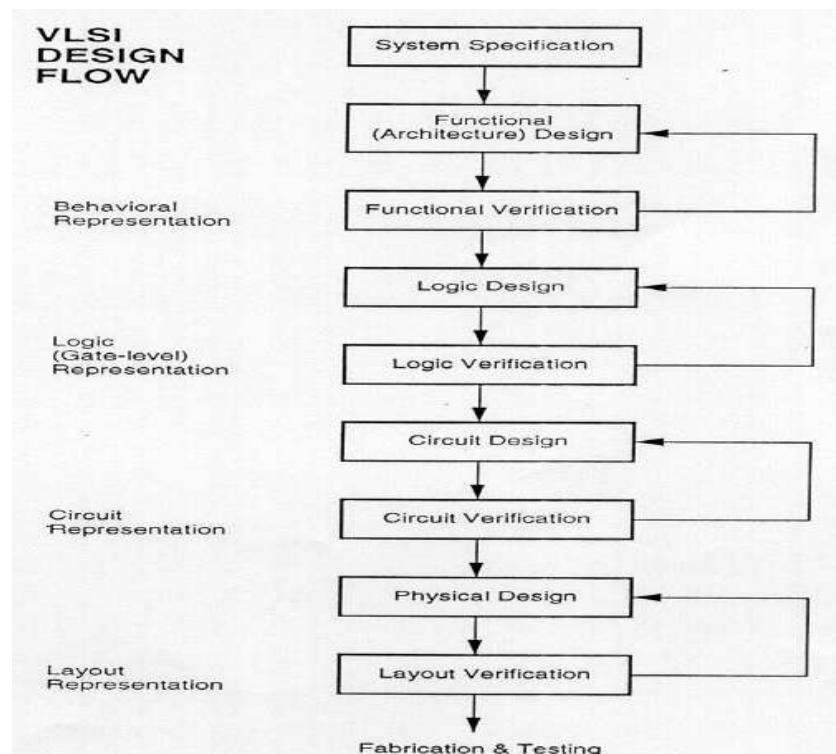
$$I_D = \mu_s C_{ox} \frac{W}{L} (V_{GS} - V_{TH} - \frac{1 + F_B}{2} V_{DS}) V_{DS}, \text{ Where, } F_B = \frac{Y F_S}{4 \sqrt{|2\phi_F| + V_{SB}}} + F_n$$

Where F_B express the dependence of depletion charge on the 3-D geometry of MOS.

F_s = specifies short channel effect; F_n = Specifies narrow width effect

M_s = Surface mobility = $\mu / (1 + \theta(V_{GS} - V_{th}))$

VLSI DESIGN FLOW-



The VLSI design flow starts with a formal specification of a VLSI chip, follows a series of steps and eventually produced a packaged chip.

1) System specification-

It is a high level representation of the system. The factors to be considered in this process include: performance, functionality, size, speed and power. The specification of a system is a compromise between market requirements, technology and economic viability.

2) Functional design-

With the help of specification, design engineers decide the architecture. This includes decisions like type of processor, no. of ALUs, floating point units, number and structure of pipelines etc.

In this step these functional units of the system are identified and also identifies the interconnect requirements between the units. It is a Register Transfer Level(RTL) description is done using Hardware Description Language (HDL) such as VHDL or Verilog.

3) Functional verification-

In this step the functional design is tested to verify its correctness.

4) Logic design-

The functional design can be refined into logic level design using gates, flip-flop etc. The RTL design is decomposed into gate level netlist.

5) Logic verification-

In this step the logic design of the system is simulated and tested to verify its correctness.

6) Circuit design-

The purpose of circuit design is to develop a circuit representation based on the logic design. This is the transistor level design. The every logic design realized into typical CMOS transistors. Then define the interconnection between the transistors.

7) Circuit verification-

Circuit verification is used to verify the correctness of each components.

8) Physical design-

In this step the circuit representation is converted into a geometric representation. The geometric representation of a circuit is called a layout.

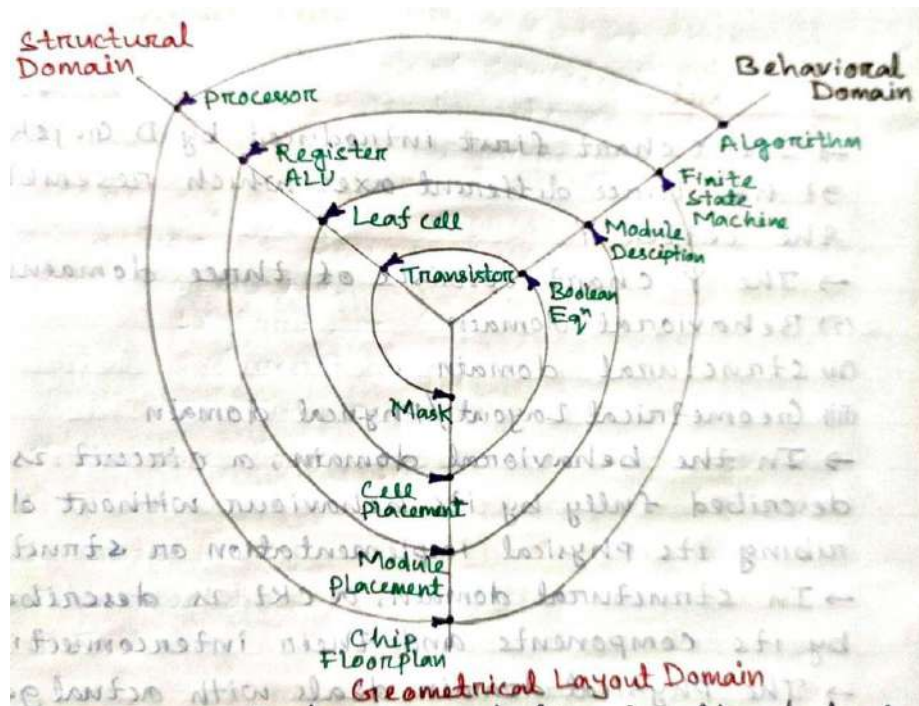
9) Layout verification-

In this step various verification and validation checks are performed on the layout.

10) Fabrication and testing-

After layout verification, the design is ready for fabrication. Then the entire layout is fabricated on wafer. Each chip is then packaged and tested to ensure that it meets all the design specification and function properly.

Y CHART-



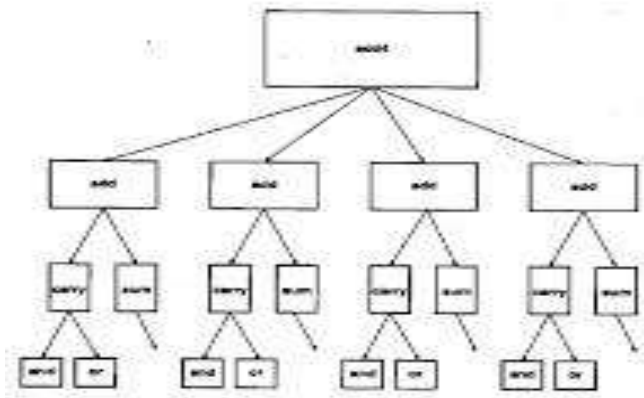
The Y-chart consists of three major domains, namely:

- behavioral domain
- structural domain
- Geometrical layout domain

- The design flow starts from the algorithm that describes the behavior of the target chip. The corresponding architecture of the processor is first defined.
- It is mapped onto the chip surface by floor planning.
- The next design evolution in the behavioral domain defines finite state machines (FSMs) which are structurally implemented with functional modules such as registers and arithmetic logic units (ALUs).
- These modules are then geometrically placed onto the chip surface using CAD tools for automatic module placement followed by routing, with a goal of minimizing the interconnects area and signal delays.
- The third evolution starts with a behavioral module description. Individual modules are then implemented with leaf cells.
- At this stage the chip is described in terms of logic gates (leaf cells), which can be placed and interconnected by using a cell placement & routing program.
- The last evolution involves a detailed Boolean description of leaf cells followed by a transistor level implementation of leaf cells and mask generation.
- In standard-cell based design, leaf cells are already pre-designed and stored in a library for logic design use.

DESIGN HIERARCHY-

- The use of hierarchy, or “divide and conquer” technique involves dividing a module into sub-modules and then repeating this operation on the sub-modules until the complexity of the smaller parts becomes manageable.
- This approach is very similar to the software case where large programs are split into smaller and smaller sections until simple subroutines, with well-defined functions and interfaces, can be written.

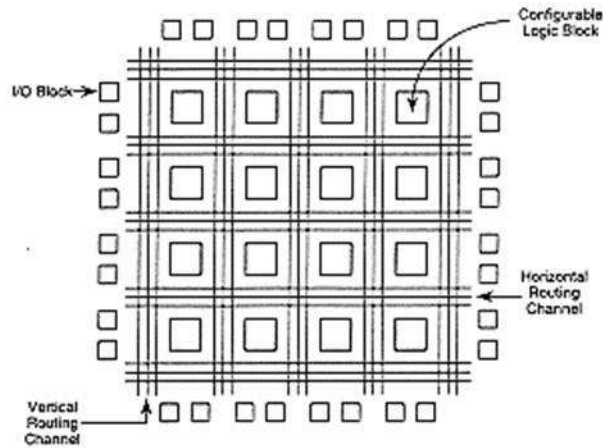


- In the above diagram The adder can be decomposed progressively into one- bit adders, separate carry and sum circuits, and finally, into individual logic gates. At this lower level of the hierarchy, the design of a simple circuit realizing a well-defined Boolean function is much easier to handle than at the higher levels of the hierarchy.
- In the physical domain, partitioning a complex system into its various functional blocks will provide a valuable guidance for the actual realization of these blocks on chip.

VLSI DESIGN STYLES-

Field Programmable Gate Array (FPGA)

- Fully fabricated FPGA chips containing thousands of logic gates or even more, with programmable interconnects, are available to users for their custom hardware programming to realize desired functionality.
- This design style provides a means for fast prototyping and also for cost-effective chip design, especially for low-volume applications.
- A typical field programmable gate array (FPGA) chip consists of I/O buffers, an array of configurable logic blocks (CLBs), and programmable interconnect structures. The programming of the interconnects is implemented by programming of RAM cells whose output terminals are connected to the gates of MOS pass transistors.



- The CLB is configured such that many different logic functions can be realized by programming its array.
- The typical design flow of an FPGA chip starts with the behavioral description of its functionality, using a hardware description language such as VHDL. The synthesized architecture is then technology-mapped (or partitioned) into circuits or logic cells.
- At this stage, the chip design is completely described in terms of available logic cells. Next, the placement and routing step assigns individual logic cells to FPGA sites (CLBs) and determines the routing patterns among the cells in accordance with the netlist.
- After routing is completed, performance of the design can be simulated and verified before downloading the design for programming of the FPGA chip. The programming of the chip remains valid as long as the chip is powered-on, or until new programming is done. In most cases, full utilization of the FPGA chip area is not possible - many cell sites may remain unused.

Gate Array Design

- In view of the fast prototyping capability, the gate array (GA) comes after the FPGA. While the design implementation of the FPGA chip is done with user programming, that of the gate array is done with metal mask design and processing.
- Gate array implementation requires a two-step manufacturing process: The first phase, which is based on generic (standard) masks, results in an array of uncommitted transistors on each GA chip.
- In the second phase these uncommitted chips can be stored for later customization, which is completed by defining the metal interconnects between the transistors of the array.
- Since the patterning of metallic interconnects is done at the end of the chip fabrication, the turnaround time can be still short, a few days to a few weeks.

Standard-Cells Based Design

- The standard-cells based design is one of the most prevalent full custom design styles which require development of a full custom mask set. The standard cell is also called the poly cell.
- In this design style, all of the commonly used logic cells are developed, characterized, and stored in a standard cell library. A typical library may contain a few hundred cells including inverters, NAND gates, NOR gates, complex AOI, OAI gates, D-latches, and flip-flops.
- Each gate type can have multiple implementations to provide adequate driving capability for different fan outs. For instance, the inverter gate can have standard size transistors, double size

transistors, and quadruple size transistors so that the chip designer can choose the proper size to achieve high circuit speed and layout density.

- To enable automated placement of the cells and routing of inter-cell connections, each cell layout is designed with a fixed height, so that a number of cells can be abutted side-by-side to form rows. The power and ground rails typically run parallel to the upper and lower boundaries of the cell, thus, neighboring cells share a common power and ground bus.

Full Custom Design

- Although the standard-cells based design is often called full custom design, in a strict sense, it is somewhat less than fully custom since the cells are pre-designed for general use and the same cells are utilized in many different chip designs.
- In a full custom design, the entire mask design is done anew without use of any library. However, the development cost of such a design style is becoming prohibitively high. Thus, the concept of design reuse is becoming popular in order to reduce design cycle time and development cost.
- The most rigorous full custom design can be the design of a memory cell, be it static or dynamic. Since the same layout design is replicated, there would not be any alternative to high density memory chip design.
- For logic chip design, a good compromise can be achieved by using a combination of different design styles on the same chip, such as standard cells, data-path cells and PLAs. In real full-custom layout in which the geometry, orientation and placement of every transistor is done individually by the designer, design productivity is usually very low - typically 10 to 20 transistors per day, per designer.
- In digital CMOS VLSI, full-custom design is rarely used due to the high labor cost. Exceptions to this include the design of high-volume products such as memory chips, high- performance microprocessors and FPGA masters.

Semi-Custom Design

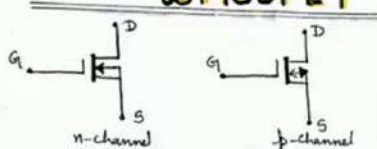
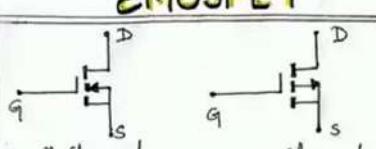
Semicustom technique is used for the design of [integrated circuits](#) that is based on the use of fully characterized libraries of circuit elements produced by the manufacturer of the device. The designer is therefore not concerned with low-level details of semiconductor material electrical properties, and can instead concentrate on the functional behaviour of the design. Most [ASIC](#) circuit designs (for instance [gate arrays](#)) are produced by this method.

COMPARISON BETWEEN FULL CUSTOM AND SEMI-CUSTOM DESIGN IN VLSI.



FULL CUSTOM DESIGN	SEMI CUSTOM DESIGN
All mask layers are customised in full custom design	It uses pre-designed logic cell (and gates, OR gate, multiplexers) known as standard cells.
In full custom design, all logic cells, circuits or layouts are designed specifically. Design doesn't use pretested or pre-characterized cells.	Designer used pre-tested or pre-characterized cell.
This approach is considered only when there is no suitable existing	Widely used
Offers high performance lower cost as compared to semi.	More cost. Low performance.
Design time and complexity is more.	Design time and complexity is less
Eg: Microprocessor	Eg. Digital logics

Difference between enhancement and depletion type nMOS transistor.

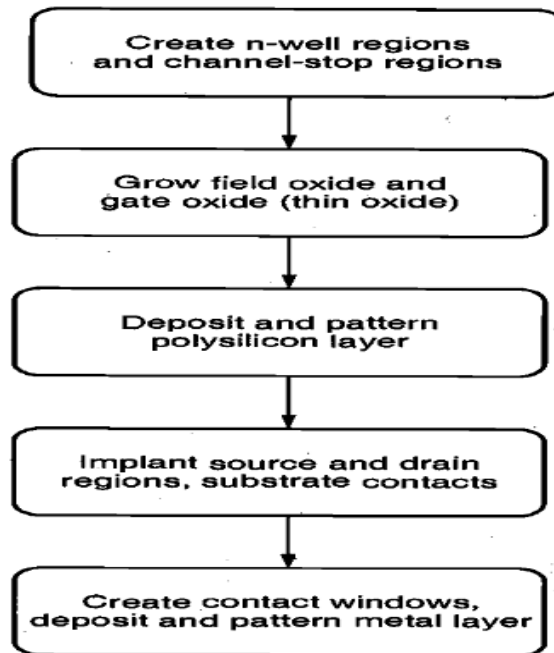
B MOSFET	E MOSFET
 <ul style="list-style-type: none"> An insulating oxide layer (SiO₂) is present between gate & channel n or p type channel is present (For n channel MOSFET) $V_{GS} = -ve$ (for depletion mode) $V_{GS} = +ve$ (for enhancement mode) (For n-channel MOSFET) If $V_{GS} = \text{more } -ve$ $I_D \downarrow \downarrow$ 	 <p>The Insulating oxide layer is present between gate & substrate.</p> <p>Channel is not present. At the time of operation, an induced channel gets created.</p> <p>V_{GS} only +ve (for n-channel MOSFET)</p> <p>$V_{GS} = \text{more } +ve$ $I_D \uparrow \uparrow$</p>

UNIT -2

FABRICATION OF MOSFET

SIMPLIFIED PROCESS SEQUENCE FOR FABRICATION-

- CMOS fabrication technology requires both NMOS and PMOS transistor to be built on the same chip substrate.
- To accommodate both NMOS & PMOS devices, special regions must be created in which the semiconductor type is opposite to the substrate type. These special regions are called wells or tubs.
- So, a n well is formed in a P substrate and a P well is formed in a n substrate.
The simplified process sequence for the fabrication of CMOS-
- The process starts with the creation of the n well regions for PMOS and p well regions for NMOS by ion implantation into the substrate.
- Ion implantation is the process of adding impurities to a silicon wafer.
- Then a thick oxide is grown in the regions surrounding the NMOS and PMOS active regions. The thin gate oxide is subsequently grown on the surface through thermal oxidation.
- Again a polysilicon layer is deposited on the surface of the oxide layers and selectively removed to form the gate.
- These steps are followed by the creation of n+ and P+ regions.
- At last metallization is done means creation of metal interconnects.
- Metallization is the process by which the components of IC's are interconnected by aluminum conductor.
- Channel stop implant is used to prevent the formation of any unwanted channels between two neighboring regions. Hence channel stop implants act to electrically isolate neighboring devices built on the same substrate.

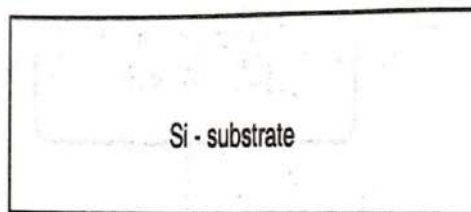


BASIC STEPS OF FABRICATION-

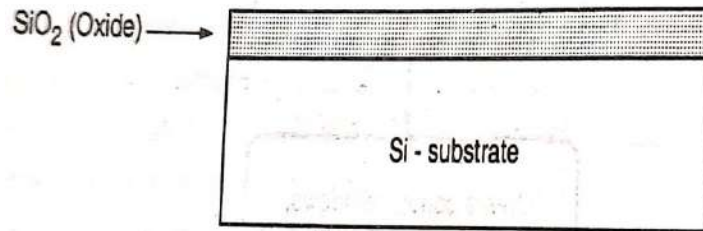
- The fabrication cycle of VLSI chips consists of a sequential set of basic steps which are wafer preparation, oxidation, lithography and etching.
- During fabrication process, the devices are created on the chip. So, IC may be viewed as a set of patterned layers.
- A layer must be patterned before the next layer of material is applied on the chip.
- Patterning uses the process of lithography. The process used to transfer a pattern to a layer on the chip is called lithography.
- The lithography sequence must be repeated for every layer.

Steps:

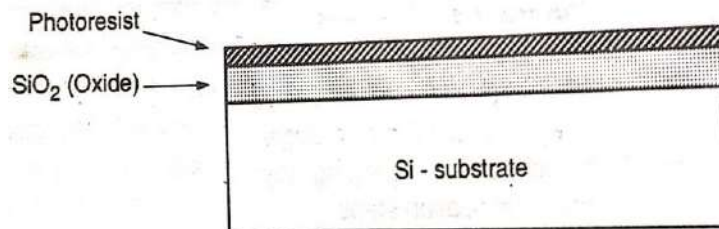
- First we take a Si substrate.



- The sequence starts with the thermal oxidation of the silicon surface. Due to which oxide layer formed of 1mm thickness.



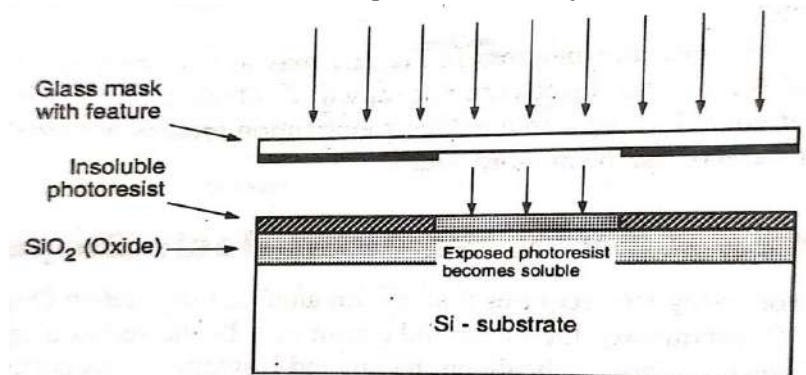
- The entire oxide surface is then covered with a layer of photoresist.



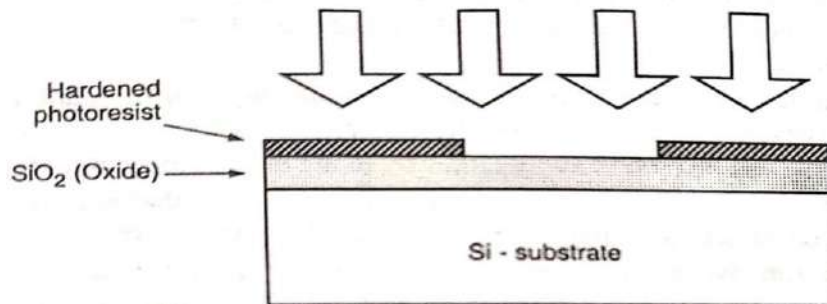
- Photoresist is a light sensitive material. It is of 2 types.

- 1) Positive photoresist
- 2) Negative photoresist

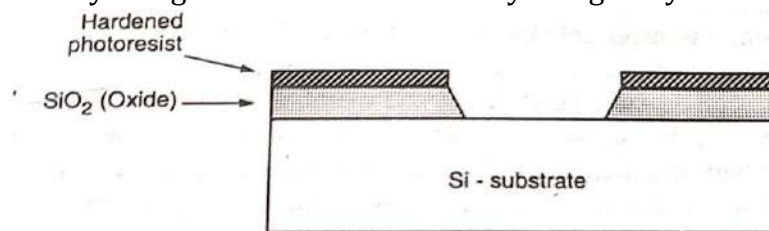
- Positive photoresist is initially insoluble and becomes soluble after exposure to UV light.
- Negative photoresist is initially soluble and becomes insoluble after exposure to UV light.
- Here we use positive photoresist. So, we have to cover some of the areas on the surface and selectively expose the photoresist.
- The areas becomes soluble, which are exposed to UV rays.



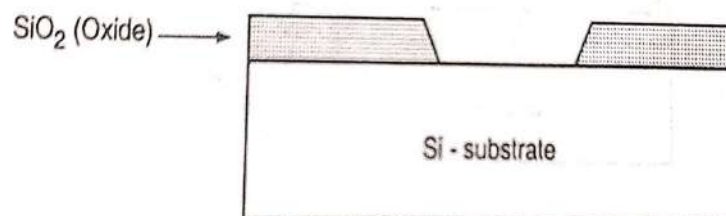
- Then the soluble areas can be etched away. Etching is the process of material being removed from the surface.



- The two major types of etching are wet etching and dry etching.
- The etching process that involves using liquid chemicals to take off the substrate material is called wet etching. Ex- Hydrofluoric Acid, Nitric acid, Acetic acid
- The dry etching is known as plasma etching. Etchant gases are used to remove the substrate material. Ex. Tetra fluoromethane, sulfur hexafluoride, Nitrogen trifluoride, Chlorine gas, Fluorine gas
- **Negative photoresists are more sensitive to light, but their photolithographic resolution is not as high as that of the positive photoresists. Therefore, negative photoresists are used less commonly.**
- The silicon dioxide regions which are not covered by hardened photoresist can be etched away either by using a chemical solvent or by using a dry etching process.

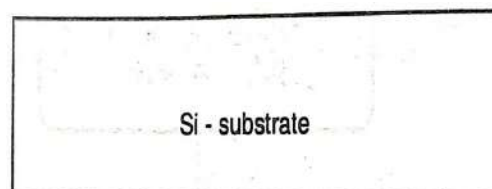


- After that the unexposed portions of the photoresist can be removed by a chemical leaving the patterned SiO₂.

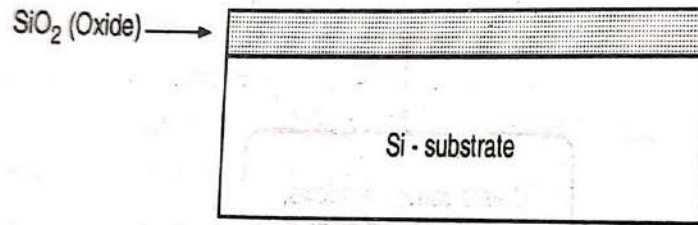


FABRICATION PROCESS OF NMOS TRANSISTOR-

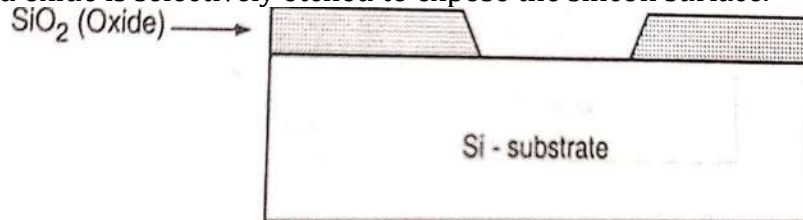
- First we take a p type silicon substrate.



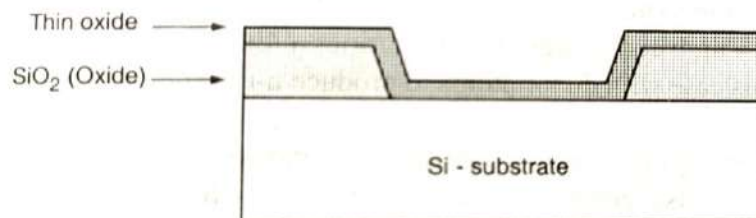
- The process starts with the oxidation of the silicon substrate



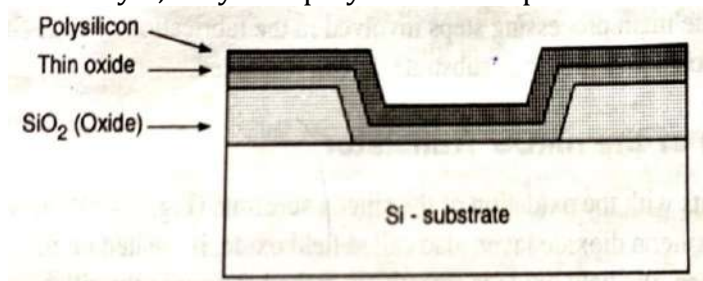
- Then the field oxide is selectively etched to expose the silicon surface.



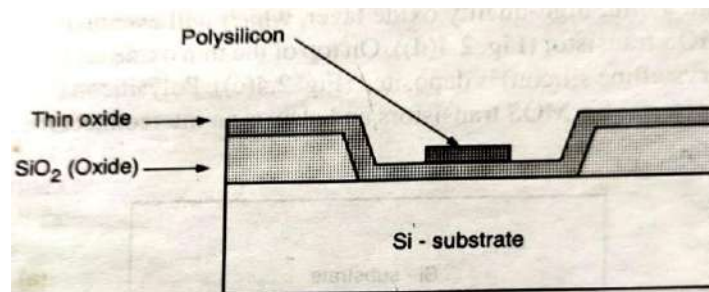
- Again the surface is covered with a thin oxide layer.



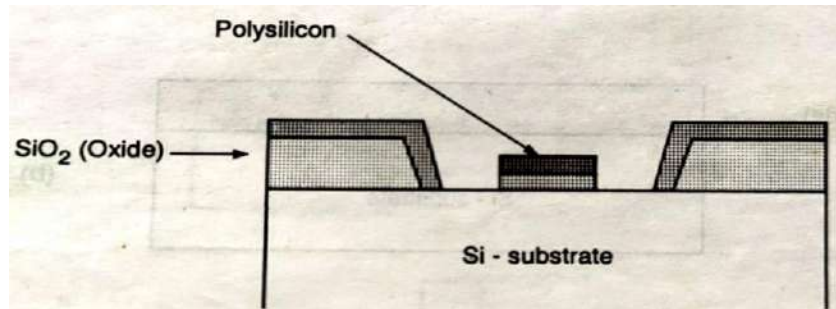
- On top of the thin oxide layer, a layer of polysilicon is deposited.



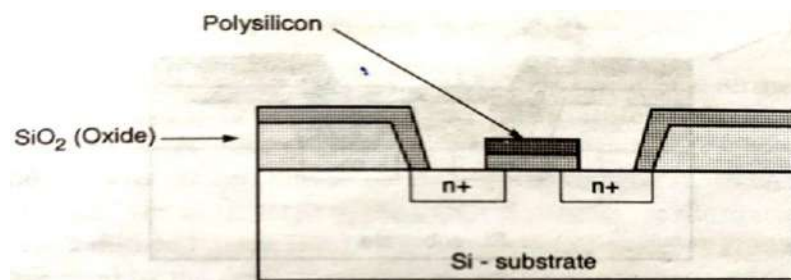
- After deposition, the polysilicon layer is patterned and etched to form gate of the MOSFET.



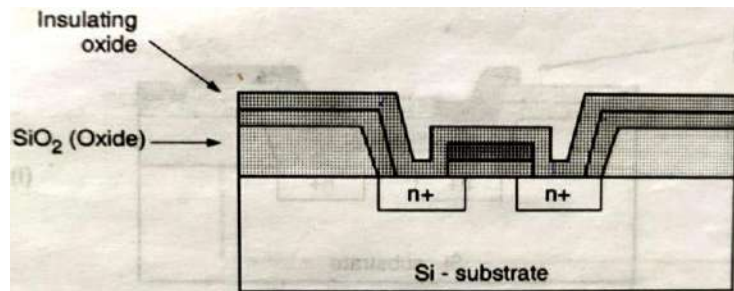
- The thin gate oxide not covered by polysilicon is also etched away, which exposes the silicon surface on which the source and drain junctions are to be formed.



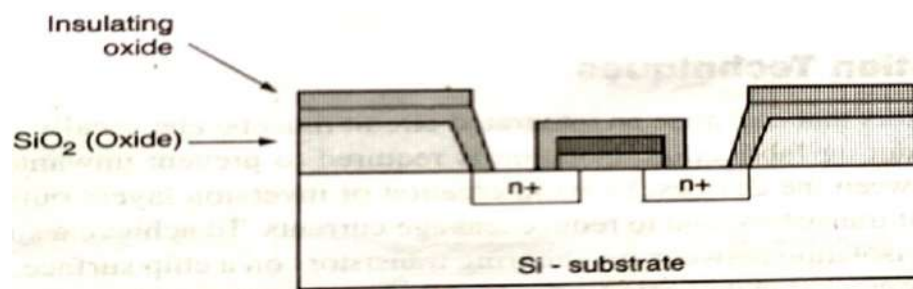
- The entire silicon surface is then doped with a high concentration of impurities, ultimately creating two n type regions.



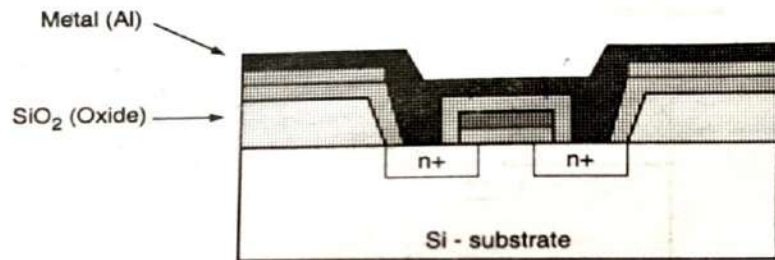
- Once the source and drain regions are completed, the entire surface is again covered with an insulating layer of silicon dioxide.



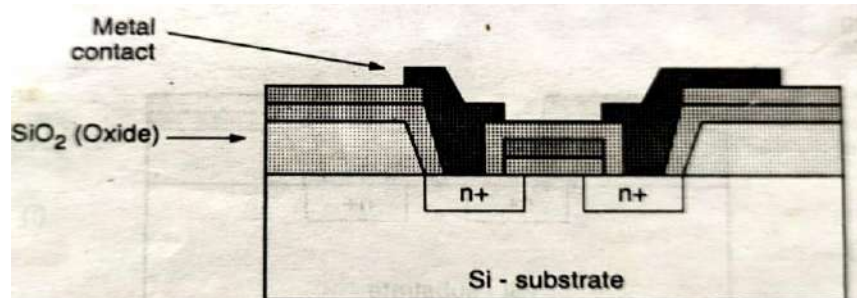
- The insulating oxide layer is then patterned in order to provide contact windows for the drain and source.



- Then the surface is covered with evaporated aluminum which will form the interconnects.



- Finally the metal layer is patterned and etched, completing the interconnection of the MOS transistors on the surface.

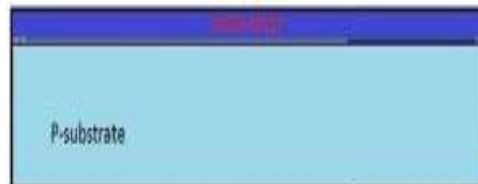


CMOS N-WELL FABRICATION PROCESS FLOW-

- For less power dissipation requirement CMOS technology is used for implementing transistor.
- The n-well technology and p-well technologies are used for fabrication of CMOS.
Now let's discuss the steps of CMOS n-well fabrication.
- First we select a substrate as a base for fabrication. So, here we select a p-type substrate.



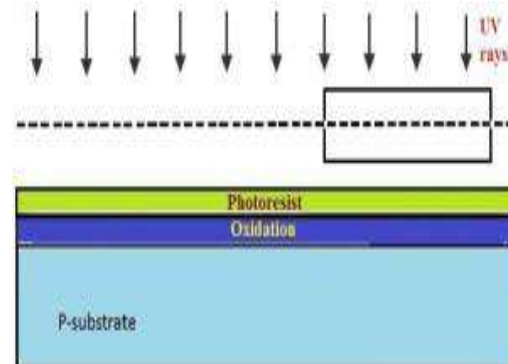
- Silicon dioxide layer formed by oxidation process on the Si substrate.



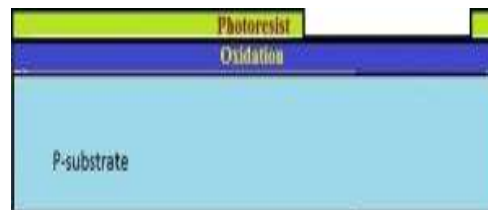
- For selective etching the SiO_2 layer is subjected to photolithography process. In this process, the wafer is coated with a uniform film of a photosensitive material known as photoresist.



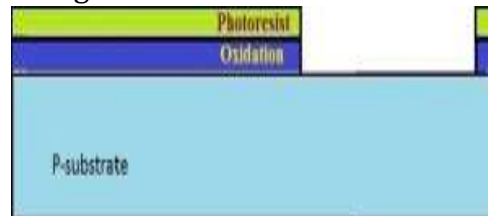
- The photoresist layer selectively exposed to UV rays.



- The soluble photoresist is removed.



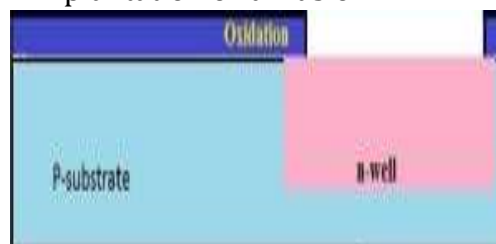
- The exposed silicon dioxide region is removed.



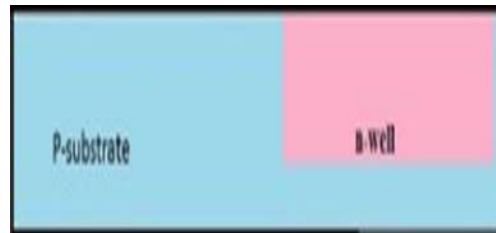
- The remaining photoresist layer is removed.



- N well is formed using ion implantation or diffusion.



- The remaining silicon dioxide is removed.

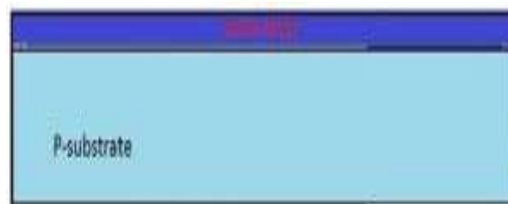


CMOS FABRICATION PROCESS BY N-WELL ON P SUBSTRATE-

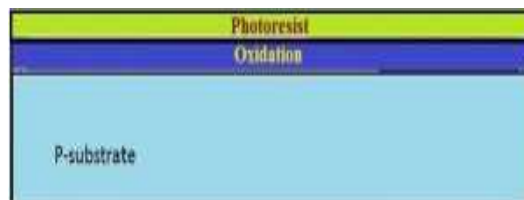
- For N well process first we take a P type substrate.



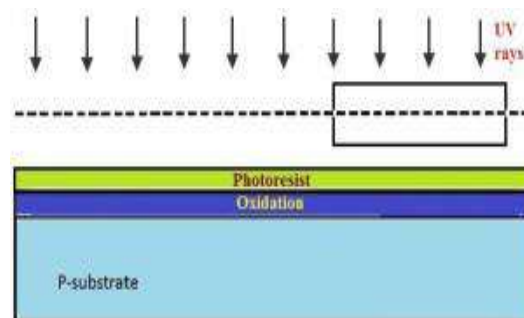
- Substrate is oxidized in high temperature.



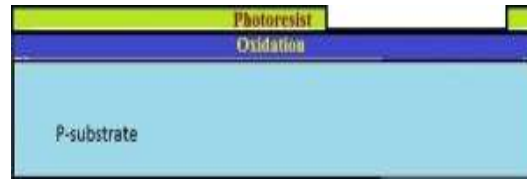
- Apply photoresist on the surface of the silicon dioxide.



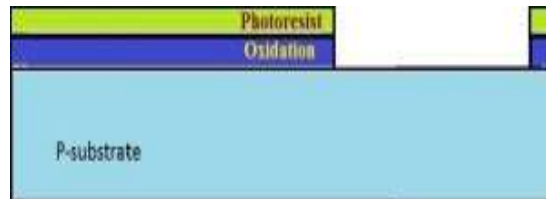
- Selectively expose the photoresist to the UV rays.



- The soluble photoresist is removed.



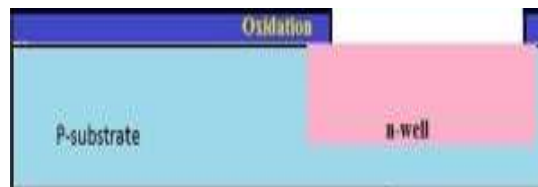
- The exposed Silicon dioxide region is removed.



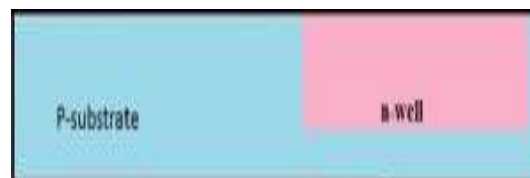
- The entire photoresist layer is stripped off.



- By using ion implantation or diffusion process N-well is formed.



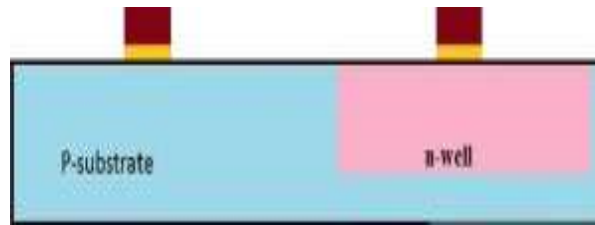
- The remaining silicon dioxide is removed.



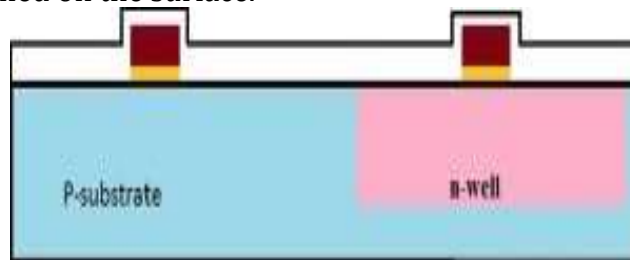
- A thin layer of gate oxide is deposited on the surface of the substrate. Then apply the polysilicon on the surface.



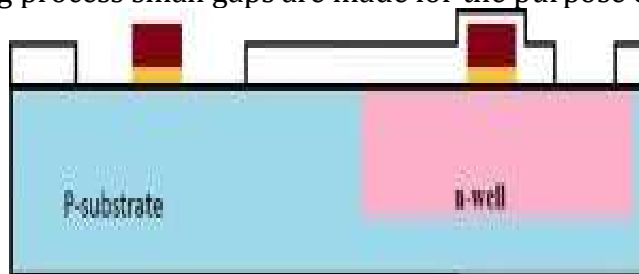
- Gate oxide and polysilicon layers are selectively removed.



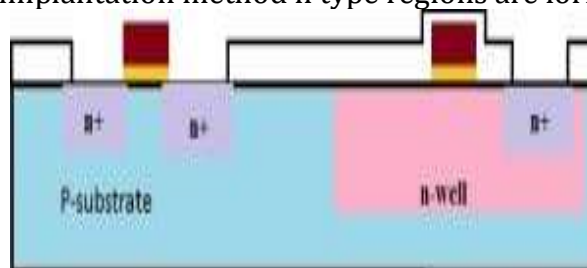
- An oxide layer is formed on the surface.



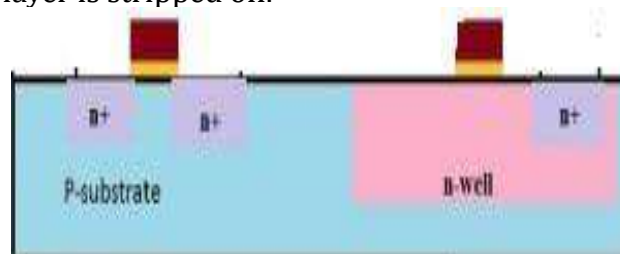
- By using the masking process small gaps are made for the purpose of N-diffusion.



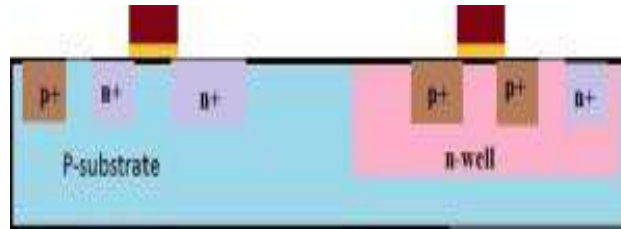
- Using diffusion or ion implantation method n type regions are formed.



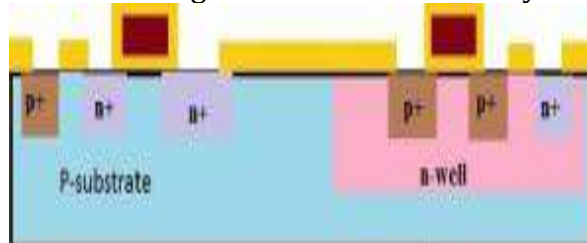
- The remaining oxide layer is stripped off.



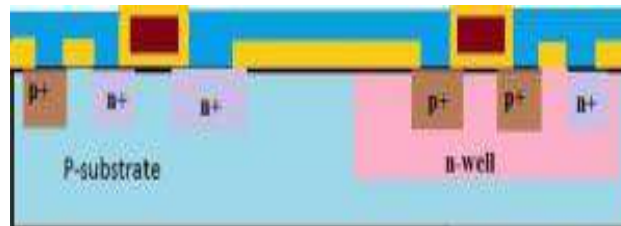
- Similar to the above process, the p type regions are formed.



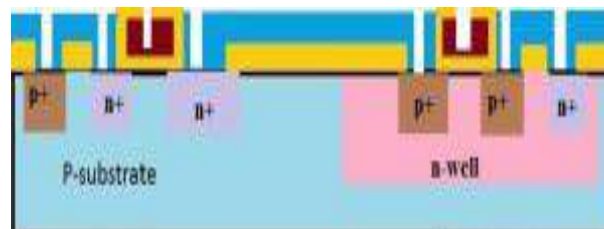
- A thick-field oxide is formed in all regions and then selectively removed.



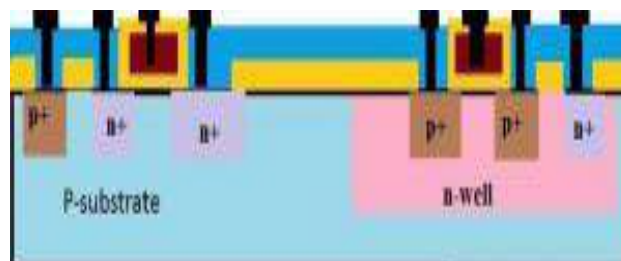
- Then the surface is covered with evaporated aluminum.



- The excess metal is removed from the surface.

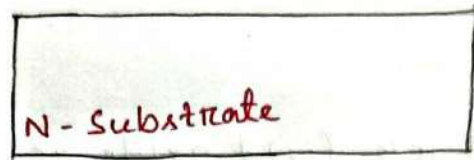


- The terminals of the PMOS and NMOS are made from respective gaps.

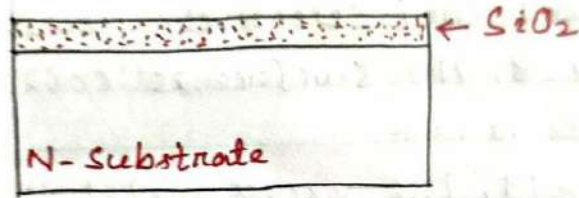


CMOS FABRICATION PROCESS BY P-WELL ON N SUBSTRATE-

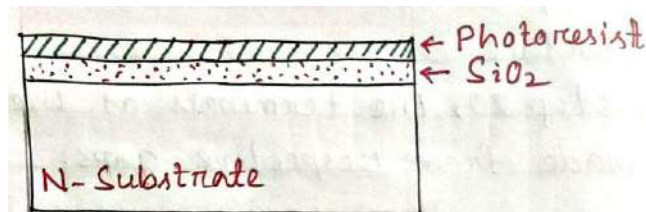
- For P well process first we take an N type substrate.



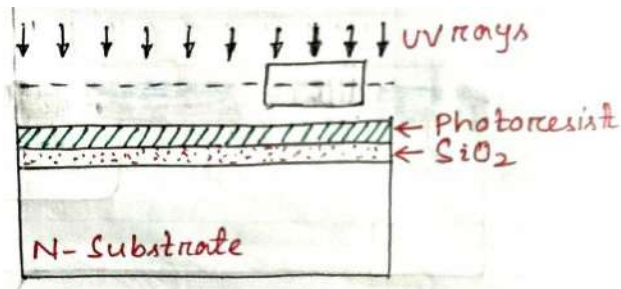
- Substrate is oxidized in high temperature.



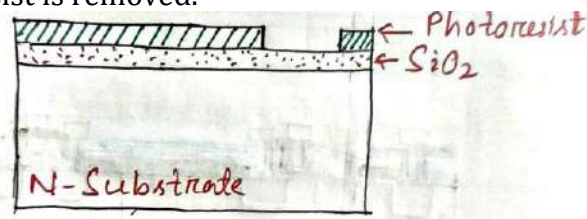
- Apply photoresist on the surface of the silicon dioxide.



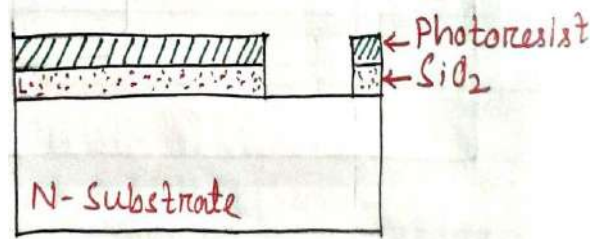
- Selectively expose the photoresist to the UV rays.



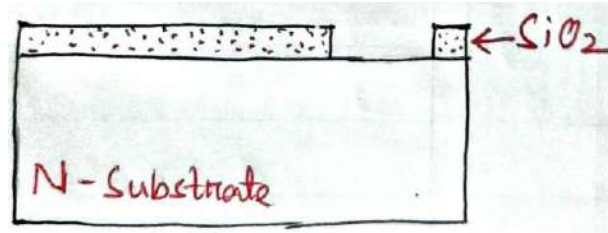
- The soluble photoresist is removed.



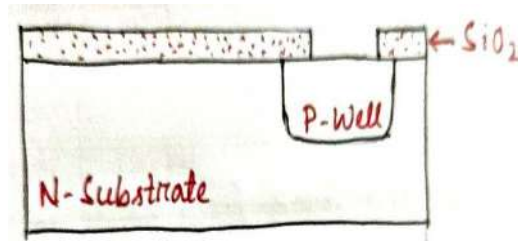
- The exposed Silicon dioxide region is removed.



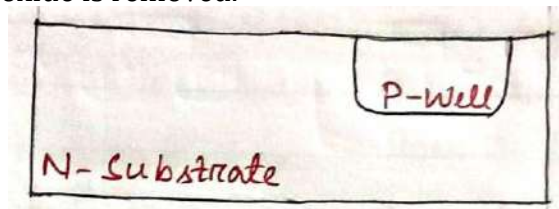
- The entire photoresist layer is stripped off.



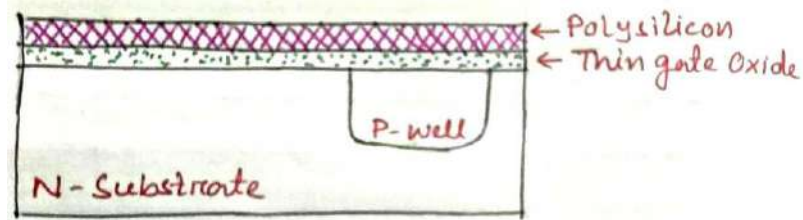
- By using ion implantation or diffusion process P-well is formed.



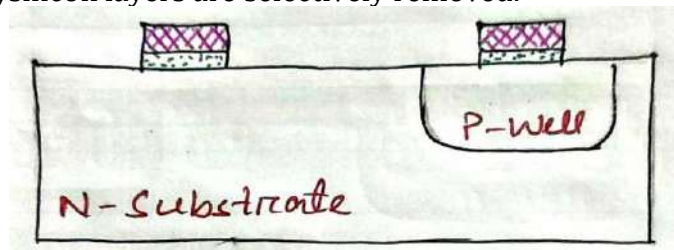
- The remaining silicon dioxide is removed.



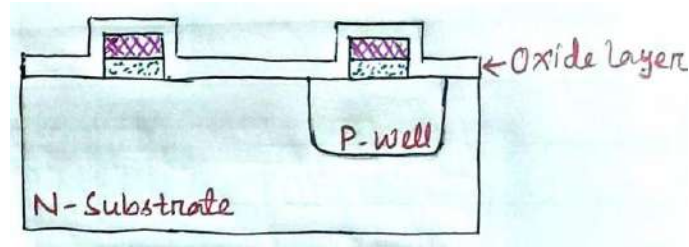
- A thin layer of gate oxide is deposited on the surface of the substrate. Then apply the polysilicon on the surface.



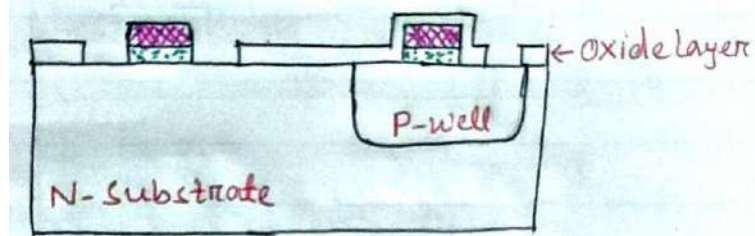
- Gate oxide and polysilicon layers are selectively removed.



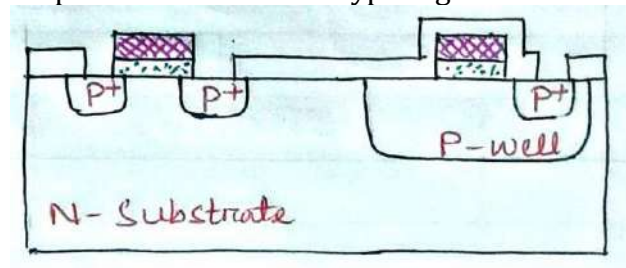
- An oxide layer is formed on the surface.



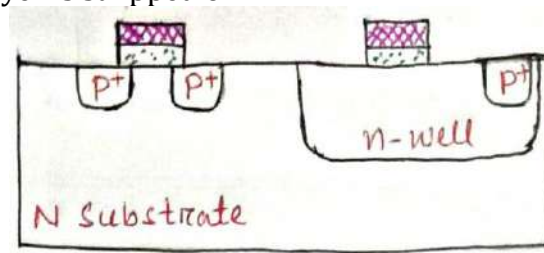
- By using the masking process small gaps are made for the purpose of P-diffusion.



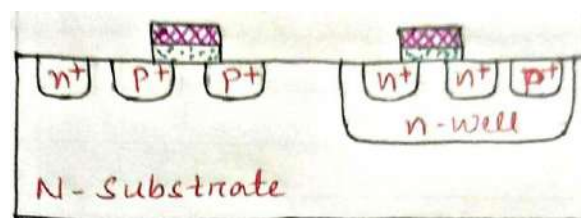
- Using diffusion or ion implantation method P type regions are formed.



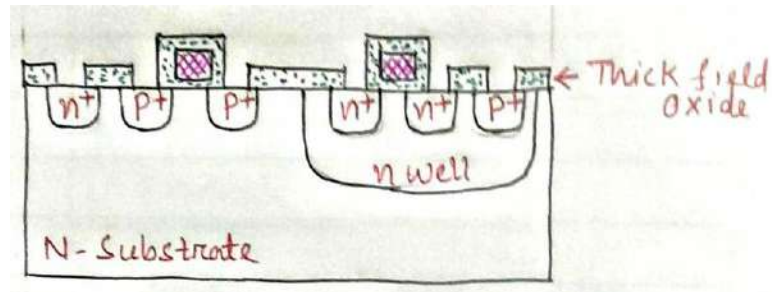
- The remaining oxide layer is stripped off.



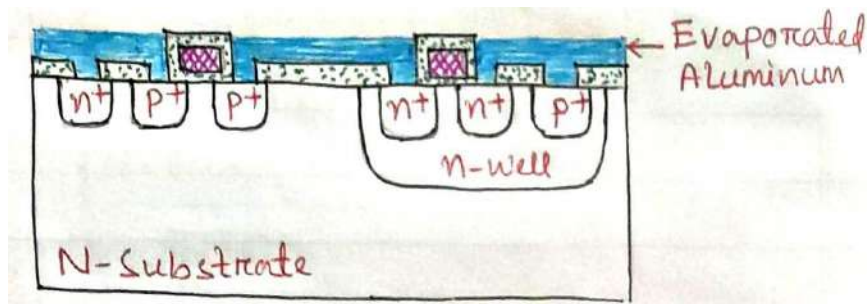
- Similar to the above process, the n type regions are formed.



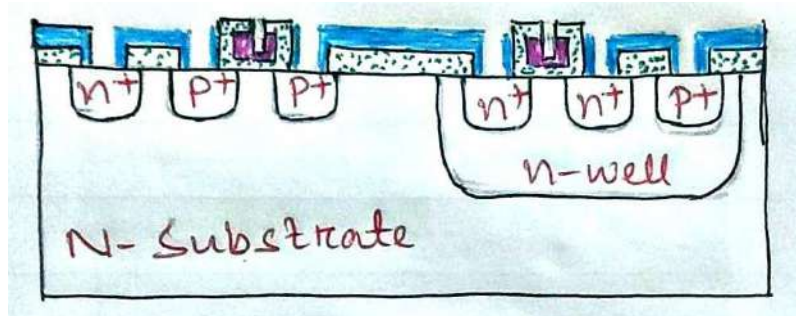
- A thick-field oxide is formed in all regions and then selectively removed.



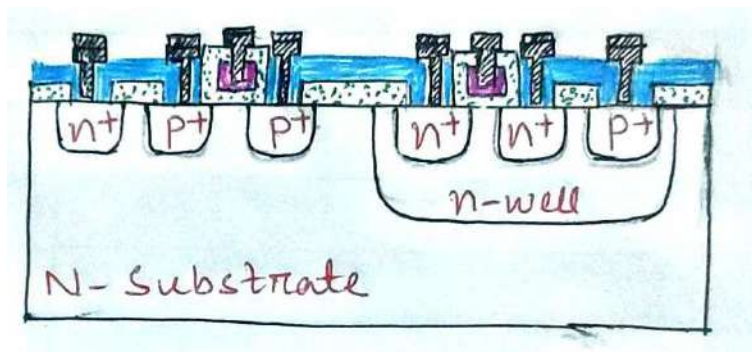
- Then the surface is covered with evaporated aluminum.



- The excess metal is removed from the surface.



- The terminals of the PMOS and NMOS are made from respective gaps.



LAYOUT DESIGN RULES-

The physical mask layout of any circuit to be manufactured using a particular process must confirm to set of geometric constraints or rules, which are generally called layout design rules.

The design rules are described in two ways-

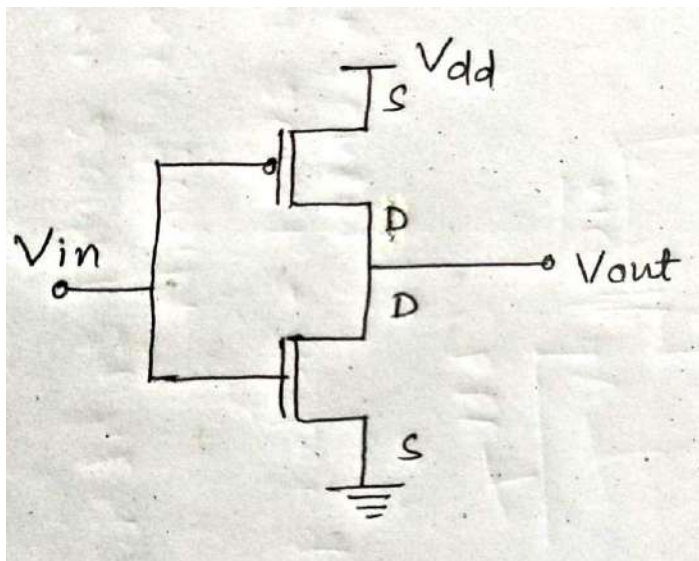
1) Micron rules-

Micron rules, in which the layout constraints such as minimum feature sizes and minimum allowable feature separations are stated in terms of absolute dimensions in micrometers.

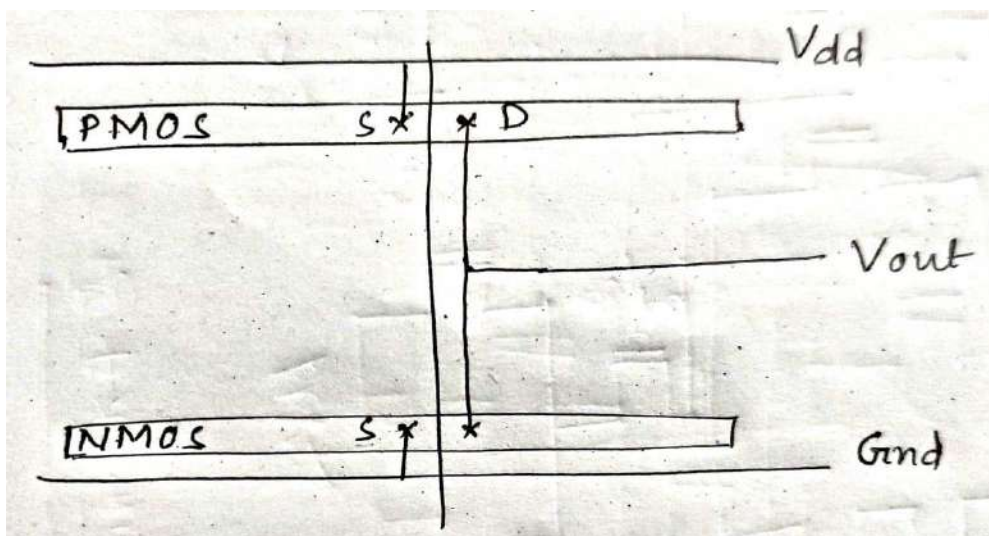
2) Lambda rules-

Lambda rules specify the layout constraints in terms of a single parameter (λ) and thus allow linear, proportional scaling of all geometrical constraints.

STICK DIAGRAM OF CMOS INVERTER-



Stick Diagram-

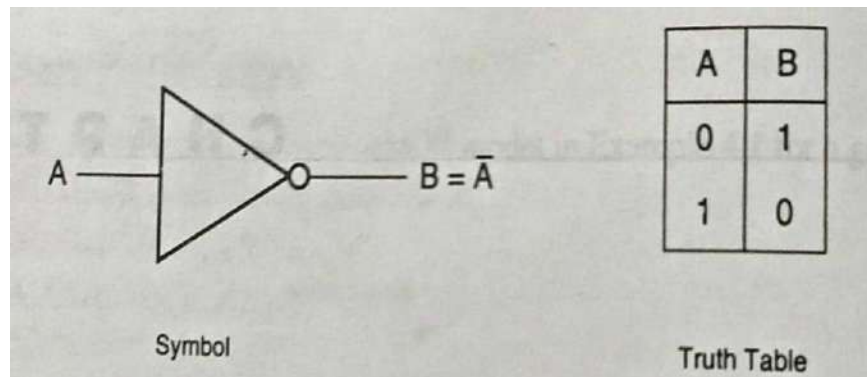


UNIT-3

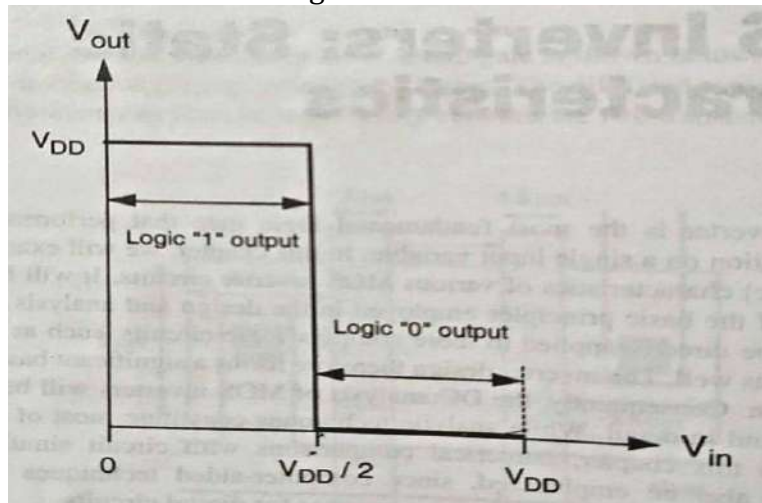
MOS INVERTER

BASIC NMOS INVERTER-

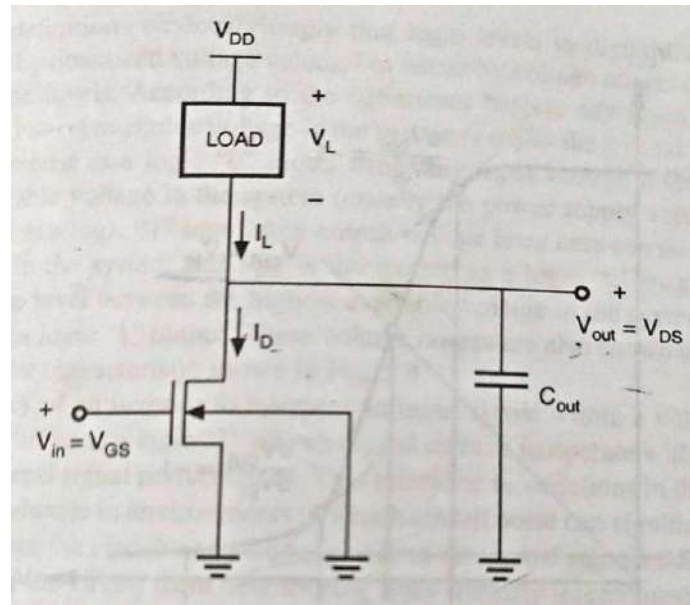
- In ideal inverter circuits, both the input variable A and the output variable B are represented by node voltages.



- Here the Boolean value of '1' means logic 1 can be represented by a high voltage of V_{DD} and the Boolean value of '0' means logic '0' can be represented by a low voltage of '0'. The voltage V_{th} is called the inverter threshold voltage.

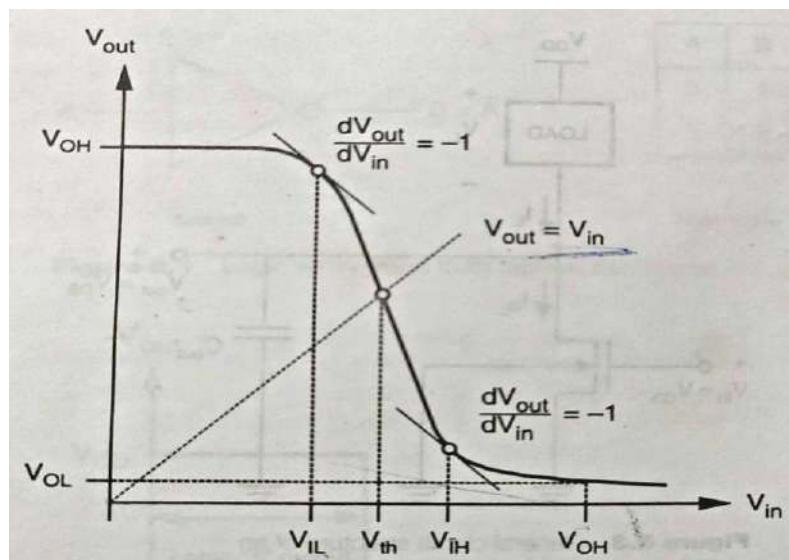


- For any input voltage between 0 to V_{th} the output voltage is equal to V_{DD} . The output switches from V_{DD} to 0 when the input is equal to V_{th} .
- For any input voltage between V_{th} and V_{DD} , the output voltage is equal to '0'. Thus an input voltage $0 \leq V_{in} < V_{th}$ is interpreted by this ideal inverter as a logic '0'. While an input voltage $V_{th} < V_{in} \leq V_{DD}$ is interpreted as a logic '1'.



- The input voltage of the inverter circuit is the gate to source voltage of the NMOS transistor. While the output voltage of the circuit is equal to the drain to source voltage.
- The source and the substrate terminals of the NMOS transistor are connected to ground potential. Hence $V_{SB} = 0$. The NMOS transistor is used as a driver transistor.
- The drain of NMOS is connected to the output terminal. The load device is represented as a two terminal circuit element with terminal current I_L and terminal voltage V_L .
- One terminal of the load device is connected to the drain of the NMOS, while the other terminal is connected to V_{DD} .

VTC Curve-



- VTC curve, which is a plot of input vs output voltage. The VTC indicates that for low input voltage the circuit output is high and for high input, the output decreases towards 0 volt.
- Applying Kirchhoff's current law, the load current is always equal to the NMOS drain current.

$$I_D = I_L$$

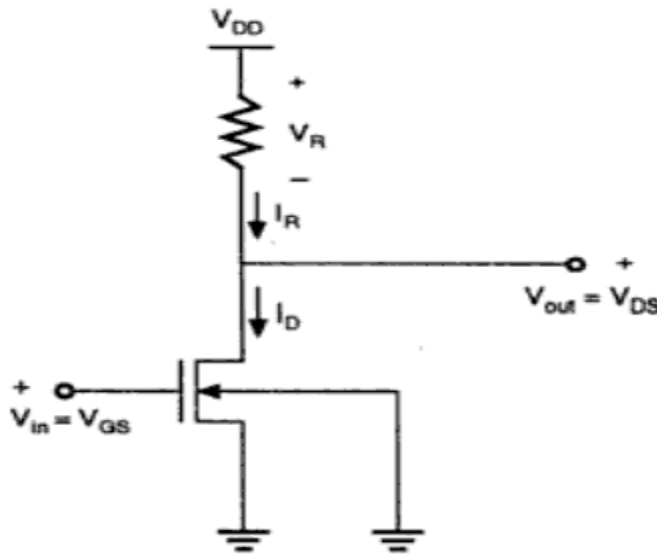
- For very low input voltage levels the output voltage V_{out} is equal to the high value of V_{OH} . The driver NMOS transistor is in cut off and hence does not conduct any current. The voltage drop across the load device is very small in magnitude and the output voltage is high.
- As the input voltage V_{in} increases, the driver transistor starts conducting a drain current and the output voltage starts to decrease. This drop in the output voltage level does not occur abruptly but in an ideal inverter it occurs abruptly.
- In this curve two critical voltage points are present, where the slope becomes equal to -1.

$$\frac{dV_{out}}{dV_{in}} = -1$$

- The smaller input voltage at which first slope occurs is called the input low voltage ' V_{IL} ' and the larger input voltage at which second slope occurs is called the input high voltage ' V_{IH} '.
- As the input voltage is further increased, the output voltage continues to drop and reaches a value of ' V_{OL} ', when the input voltage is equal to ' V_{OH} '. The inverter threshold voltage V_{th} which is considered as the transition voltage is defined as the point where $V_{OUT} = V_{in}$.

RESISTIVE LOAD INVERTER- IMPORTANT

Here, enhancement type nMOS acts as the driver transistor. The load consists of a simple linear resistor R_L . The power supply of the circuit is V_{DD} and the drain current I_D is equal to the load current I_R .



Circuit Operation

- When the input of the driver transistor is less than threshold voltage, driver transistor is in cut off region and does not conduct any current. So, the voltage drop across the load resistor is zero and output voltage is equal to the V_{DD} .
- Here $I_R = I_D$.
- So, output voltage V_{out} is

$$V_{out} = V_{DD} - I_R R$$

$$V_{out} = V_{DD} - I_D R$$

- So, Drain current equation will be

$$I_D = \frac{V_{DD} - V_{out}}{R}$$

- When the input voltage increases further, driver transistor will start conducting the non-zero current and NMOS goes in saturation region.
- if MOSFET is there in saturation region then

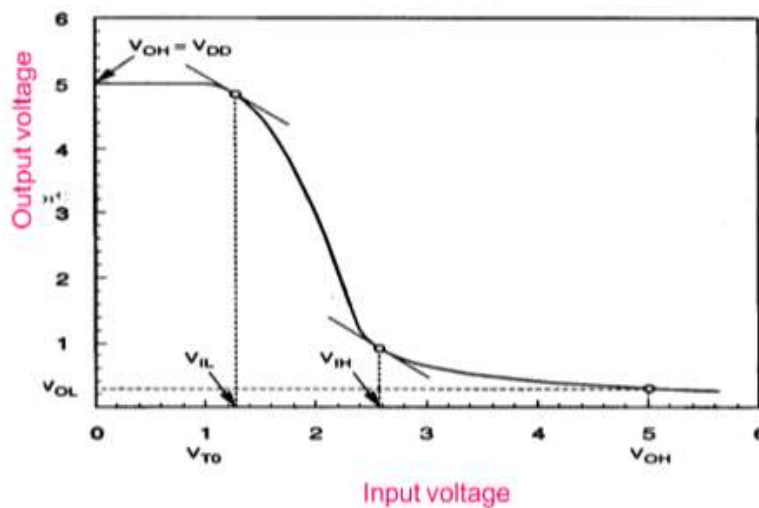
$$V_{in} - V_{To} < V_{out} \text{ and } I_D = \frac{K}{2} (V_{GS} - V_{To})^2$$

- If MOSFET is there in linear region then

$$V_{in} - V_{To} > V_{out} \text{ and } I_D = \frac{K}{2} [2(V_{GS} - V_{To})V_{DS} - V_{DS}^2]$$

VTC curve-

- Initially when input is at lower voltage, the NMOS is at cut off region, the V_{out} is equal to V_{DD} until the NMOS is not turned ON.
- Once the NMOS turned ON, slow decrease in output voltage starts.



V_{OH} -

- Output voltage V_{out} is

$$V_{out} = V_{DD} - I_D R$$

$$\Rightarrow V_{out} = V_{DD}$$

$$\Rightarrow V_{OH} = V_{DD}$$

V_{OL} -

- When $V_{in} - V_{To} > V_{out}$, MOSFET is there in linear region, so, drain current will be

$$I_D = \frac{K}{2} [2(V_{in} - V_{TO})V_{out} - V_{out}^2]$$

- According to kirchoff's law in the drain current is

$$I_D = \frac{V_{DD} - V_{out}}{R}$$

- If we compare these two equations

$$\frac{V_{DD} - V_{out}}{R} = \frac{K}{2} [2(V_{in} - V_{TO})V_{out} - V_{out}^2]$$

$$\Rightarrow \frac{V_{DD} - V_{OL}}{R} = \frac{K}{2} [2(V_{DD} - V_{TO})V_{OL} - V_{OL}^2]$$

$$\Rightarrow V_{OL}^2 - 2(V_{DD} - V_{TO} + 1/KR)V_{OL} + 2/KR V_{DD} = 0$$

- If we solve the above equation, we get

$$V_{OL} = V_{DD} - V_{TO} + 1/KR - \sqrt{(V_{DD} - V_{TO} + \frac{1}{KR})^2 - \frac{2V_{DD}}{KR}}$$

V_{IL}-

- When $V_{in} - V_{TO} < V_{out}$ MOSFET is there in saturation region, so drain current will be

$$I_D = \frac{K}{2} (V_{in} - V_{TO})^2$$

- Again compare the equation with circuit drain current equation

$$\frac{V_{DD} - V_{out}}{R} = \frac{K}{2} (V_{in} - V_{TO})^2$$

- We have to differentiate it with respect to V_{in}

$$\left(\frac{V_{DD} - V_{out}}{R} \right) \frac{dV_{out}}{dV_{in}} = \left[\frac{K}{2} (V_{in} - V_{TO})^2 \right] \frac{dV_{out}}{dV_{in}}$$

$$\Rightarrow -\frac{1}{R} \frac{dV_{out}}{dV_{in}} = K (V_{in} - V_{TO})$$

$$\Rightarrow \frac{1}{R} = K (V_{IL} - V_{TO})$$

$$\Rightarrow V_{IL} = V_{TO} + 1/KR$$

V_{IH}-

- When $V_{in} - V_{TO} > V_{out}$ MOSFET is there in linear region, so drain current will be

$$I_D = \frac{K}{2} [2(V_{in} - V_{TO})V_{out} - V_{out}^2]$$

Compare the equation with circuit drain current equation

$$\frac{V_{DD} - V_{out}}{R} = \frac{K}{2} [2(V_{in} - V_{TO})V_{out} - V_{out}^2]$$

- We have to differentiate it with respect to V_{in}

$$-\frac{1}{R} \frac{dV_{out}}{dV_{in}} = K/2 [2(V_{in} - V_{TO}) \frac{dV_{out}}{dV_{in}} + 2V_{out} - 2V_{out} \frac{dV_{out}}{dV_{in}}]$$

$$\Rightarrow \frac{1}{R} = K/2 [-2(V_{IH} - V_{TO}) + 4V_{out}]$$

$$\Rightarrow \frac{1}{KR} = -(V_{IH} - V_{TO}) + 2V_{out}$$

$$\Rightarrow \frac{1}{KR} = -V_{IH} + V_{TO} + 2V_{out}$$

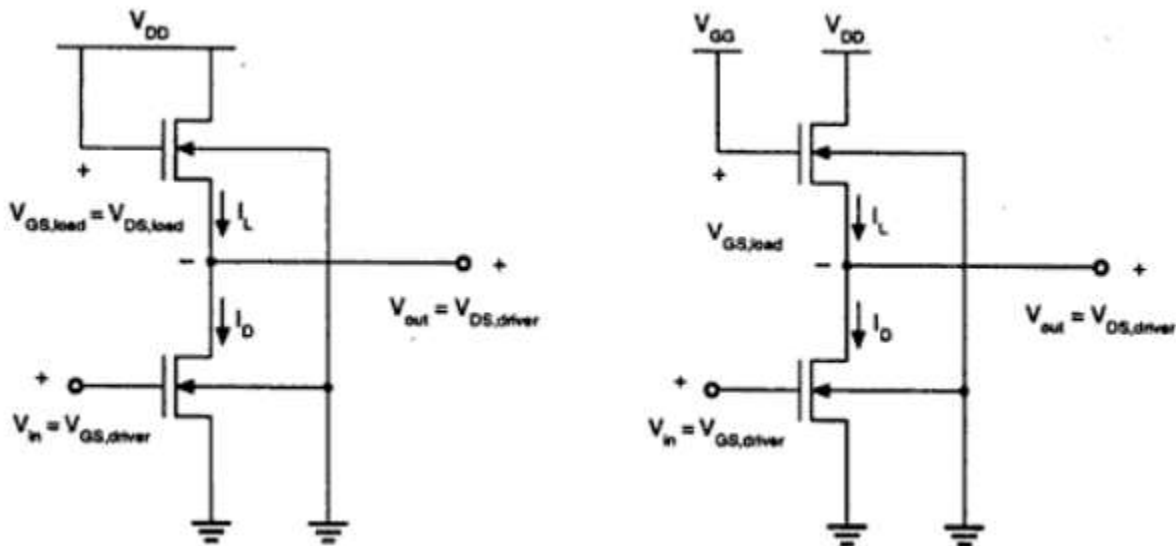
$$\Rightarrow V_{IH} = V_{TO} + 2V_{out} - \frac{1}{KR}$$

INVERTER WITH N-TYPE MOSFET LOAD-

The main advantage of using MOSFET as load device is that the silicon area occupied by the transistor is smaller than the area occupied by the resistive load. Here, MOSFET is active load and inverter with active load gives a better performance than the inverter with resistive load.

Enhancement load-

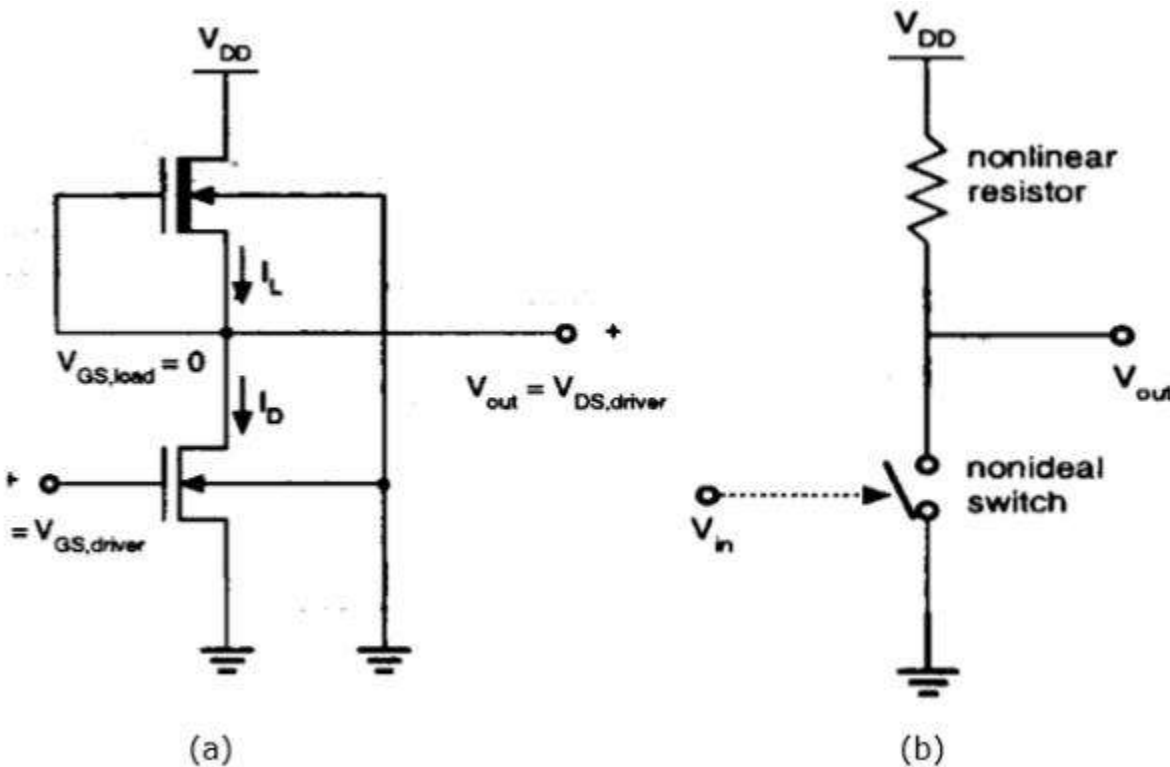
Load transistor can be operated either, in saturation region or in linear region, depending on the bias voltage applied to its gate terminal. The saturated enhancement load inverter is shown in the first figure. It requires a single voltage supply and simple fabrication process and so V_{OH} is limited to the $V_{DD} - V_T$.



The linear enhancement load inverter is shown in the second figure. It always operates in linear region; so V_{OH} level is equal to V_{DD} .

Linear load inverter has higher noise margin compared to the saturated enhancement inverter. But, the disadvantage of linear enhancement inverter is, it requires two separate power supply and both the circuits suffer from high power dissipation. Therefore, enhancement inverters are not used in any large-scale digital applications.

Depletion load NMOS-



- Drawbacks of the enhancement load inverter can be overcome by using depletion load inverter. Compared to enhancement load inverter, depletion load inverter requires few more fabrication steps for channel implant to adjust the threshold voltage of load.
- The advantages of the depletion load inverter are - sharp VTC transition, better noise margin, single power supply and smaller overall layout area.
- The gate and source terminal of load are connected; So, $V_{GS} = 0$. Thus, the threshold voltage of the load is negative. Hence,

$$V_{GS,load} > V_{T,load}$$

Therefore, load device always has a conduction channel regardless of input and output voltage level.

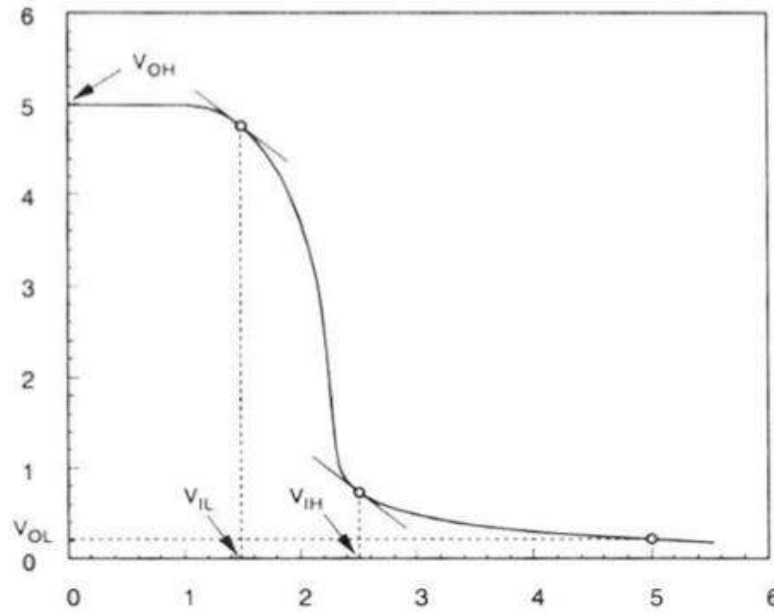
- When the load transistor is in saturation region, the load current is given by

$$I_{D,load} = \frac{K_{n,load}}{2} [-V_{T,load}(V_{out})]$$

- When the load transistor is in linear region, the load current is given by

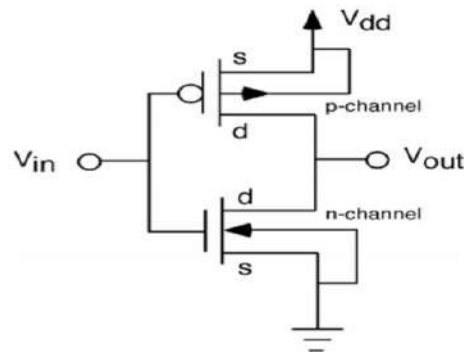
$$I_{D,load} = \frac{K_{n,load}}{2} [2|V_{T,load}(V_{out})| \cdot (V_{DD} - V_{out}) - (V_{DD} - V_{out})^2]$$

The voltage transfer characteristics of the depletion load inverter is shown in the figure given below –



CMOS INVERTER- IMPORTANT

In CMOS inverter NMOS work as driver and PMOS transistors work as load and always one transistor is ON, other is OFF.



This configuration is called **complementary MOS (CMOS)**. The input is connected to the gate terminal of both the transistors such that both can be driven directly with input voltages. Substrate of the NMOS is connected to the ground and substrate of the PMOS is connected to the power supply, V_{DD} .

So $V_{SB} = 0$ for both the transistors.

$$V_{GS,n} = V_{in}$$

$$V_{DS,n} = V_{OUT}$$

And,

$$V_{GS,n} = V_{in} - V_{DD}$$

$$V_{DS,n} = V_{out} - V_{DD}$$

When the input of nMOS is smaller than the threshold voltage ($V_{in} < V_{TO,n}$), the nMOS is cut – off and pMOS is in linear region. So, the drain current of both the transistors is zero.

$$I_{D,n} = I_{D,p} = 0$$

Therefore, the output voltage V_{OH} is equal to the supply voltage.

$$V_{out} = V_{OH} = V_{DD}$$

When the input voltage is greater than the $V_{DD} + V_{TO,p}$, the pMOS transistor is in the cutoff region and the nMOS is in the linear region, so the drain current of both the transistors is zero.

$$I_{D,n} = I_{D,p} = 0$$

Therefore, the output voltage V_{OL} is equal to zero.

$$V_{out} = V_{OL} = 0$$

The nMOS operates in the saturation region if $V_{in} > V_{TO}$ and if following conditions are satisfied.

$$V_{DS,n} \geq V_{GS,n} - V_{TO,n}$$

$$V_{out} \geq V_{in} - V_{TO,n}$$

The pMOS operates in the saturation region if $V_{in} < V_{DD} + V_{TO,p}$ and if following conditions are satisfied.

$$V_{DS,p} \leq V_{GS,p} - V_{TO,p}$$

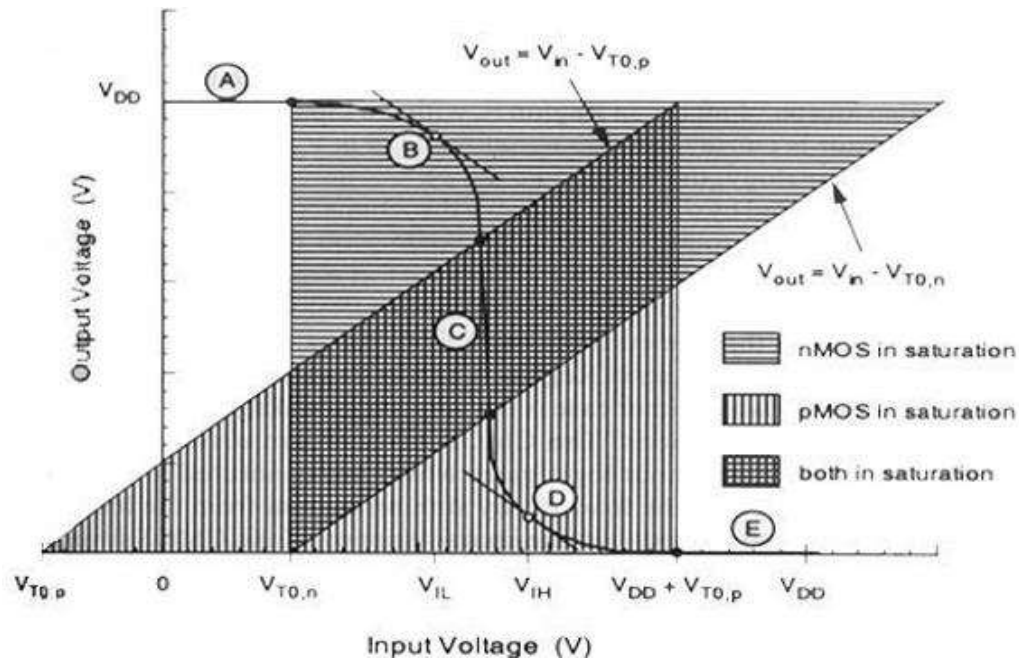
$$V_{out} \geq V_{in} - V_{TO,p}$$

For different value of input voltages, the operating regions are listed below for both transistors.

Region	V_{in}	V_{out}	nMOS	pMOS
A	$< V_{TO,n}$	V_{OH}	Cut – off	Linear
B	V_{IL}	High $\approx V_{OH}$	Saturation	Linear
C	V_{th}	V_{th}	Saturation	Saturation

D	V_{IH}	Low $\approx V_{OL}$	Linear	Saturation
E	$> (V_{DD} + V_{T0,p})$	V_{OL}	Linear	Cut – off

The VTC of CMOS is shown in the figure below –



INTERCONNECT EFFECTS-

DELAY TIME DEFINATION- IMPORTANT

The propagation delay times τ_{PHL} and τ_{PLH} determine the input to output signal delay during the high to low and low to high transitions of the output, respectively.

Definition-

τ_{PHL} is the time delay between the $V_{50\%}$ transition of the rising input voltage and the $V_{50\%}$ transition of the falling output voltage.

τ_{PLH} is the time delay between the $V_{50\%}$ transition of the falling input voltage and the $V_{50\%}$ transition of the rising output voltage.

τ_{PHL} becomes the time required for the output voltage to fall from V_{OH} to the $V_{50\%}$ level and

τ_{PLH} becomes the time required for the output voltage to rise from V_{OL} to the $V_{50\%}$ level.

$$V_{50\%} = V_{OL} + \frac{1}{2}(V_{OH} - V_{OL})$$

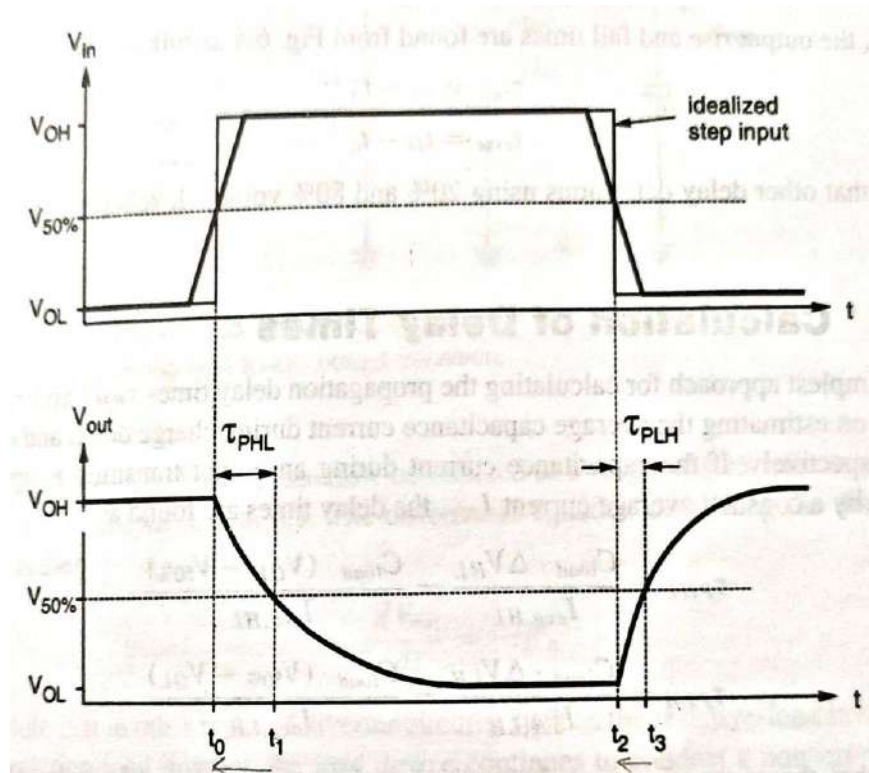
$$= \frac{1}{2} (V_{OL} + V_{OH})$$

$$\tau_{PHL} = t_1 - t_0$$

$$\tau_{PLH} = t_3 - t_2$$

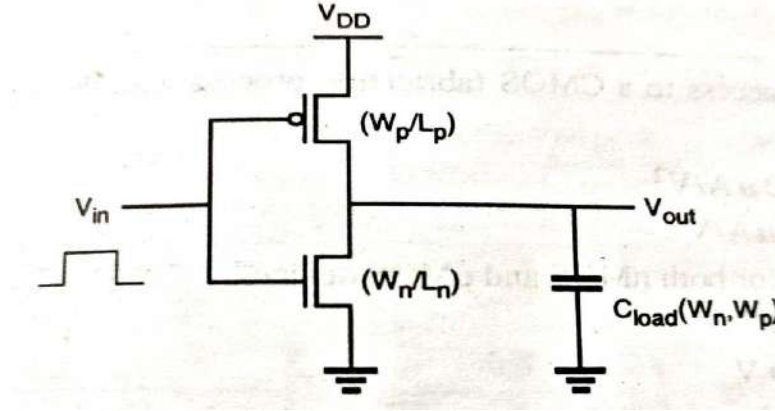
Average propagation delay is

$$\tau_p = \frac{\tau_{PHL} + \tau_{PLH}}{2}$$



INVERTER DESIGN WITH DELAY CONSTRAINTS-

The design of CMOS inverters based on timing specifications is one of the most fundamental issues in digital circuit design which ultimately determine the overall performance of complex systems.



The load capacitance C_{load} consists of intrinsic components and extrinsic components.

If C_{load} consists of extrinsic components and if this overall load capacitance can be estimated accurately and independently of the transistor dimensions, then the problem of inverter design can be reduced. Given a required delay value of τ_{PHL} , the (W/L) ratio of the NMOS transistor can be found as

$$\frac{W_n}{L_n} = \frac{C_{load}}{\tau_{PHL} \mu_n C_{ox} (V_{DD} - V_{T,n})} \left[\frac{2V_{T,n}}{V_{DD} - V_{T,n}} + \ln \left(\frac{4(V_{DD} - V_{T,n})}{V_{DD}} - 1 \right) \right]$$

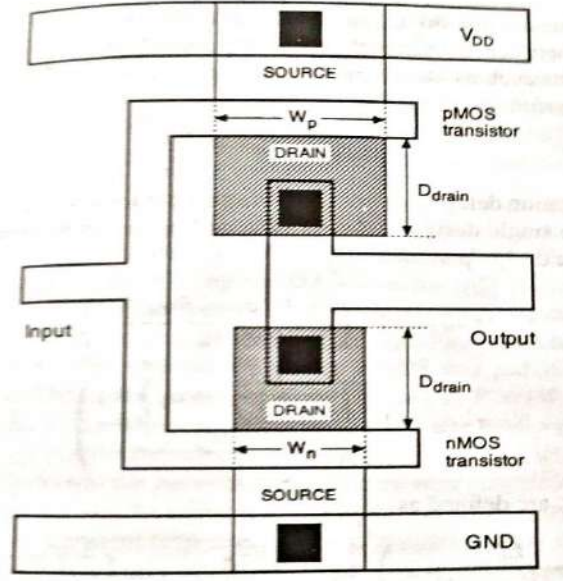
Similarly, the (W/L) ratio of the PMOS transistor to satisfy a given target value of τ_{PLH} can be calculated as

$$\frac{W_p}{L_p} = \frac{C_{load}}{\tau_{PLH} \mu_p C_{ox} (V_{DD} - |V_{T,p}|)} \left[\frac{2|V_{T,p}|}{V_{DD} - |V_{T,p}|} + \ln \left(\frac{4(V_{DD} - |V_{T,p}|)}{V_{DD}} - 1 \right) \right]$$

Assumed that the combined output load capacitance is mainly dominated by its extrinsic components, and hence, that is not very sensitive to device dimensions.

$$\begin{aligned} C_{load} &= C_{gd,n}(W_n) + C_{gd,p}(W_p) + C_{db,n}(W_n) + C_{db,p}(W_p) + C_{int} + C_g \\ &= f(W_n, W_p) \end{aligned}$$

The fan out capacitance C_g is also a function of the device dimensions in the next stage gate.



Simplified CMOS inverter mask layout used for delay analysis

Here the diffusion areas of both NMOS and PMOS transistors have a simple rectangular geometry and the drain region length is assumed to be same for both devices. The relatively small gate to drain capacitances $C_{gd,n}$ and $C_{gd,p}$ will be neglected. The drain parasitic capacitances can be found as

$$C_{db,n} = W_n D_{drain} C_{j0,n} K_{eq,n} + 2(W_n + D_{drain}) C_{jsw,n} K_{eq,n}$$

$$C_{db,p} = W_p D_{drain} C_{j0,p} K_{eq,p} + 2(W_p + D_{drain}) C_{jsw,p} K_{eq,p}$$

Where $C_{j0,n}$ and $C_{j0,p}$ denote the zero bias junction capacitances for n-type and p-type diffusion regions, $C_{jsw,n}$ and $C_{jsw,p}$ denote the zero bias sidewall junction capacitances and $K_{eq,n}$ and $K_{eq,p}$ denote the voltage equivalence factors. The combined output load capacitance then becomes

$$C_{load} = (W_n C_{j0,n} K_{eq,n} + W_p C_{j0,p} K_{eq,p}) D_{drain} + 2(W_n + D_{drain}) C_{jsw,n} K_{eq,n} + 2(W_p + D_{drain}) C_{jsw,p} K_{eq,p} + C_{int} + C_g$$

Thus the total capacitive load of the inverter can be expressed as

$$C_{load} = \alpha_0 + \alpha_n W_n + \alpha_p W_p$$

Where $\alpha_0 = 2D_{drain}(C_{jsw,n} K_{eq,n} + C_{jsw,p} K_{eq,p}) + C_{int} + C_g$

$$\alpha_n = K_{eq,n}(C_{j0,n} D_{drain} + 2C_{jsw,n})$$

$$\alpha_p = K_{eq,p}(C_{j0,p} D_{drain} + 2C_{jsw,p})$$

UNIT-4

STATIC COMBINATIONAL, SEQUENTIAL, DYNAMICS LOGIC CIRCUITS & MEMORIES

STATIC CMOS LOGIC CIRCUITS-

Static CMOS is a [logic](#) circuit design technique whereby the output is always strongly driven due to it always being connected to either [VCC](#) or [GND](#) (except when switching). This design is in contrast to [Dynamic CMOS](#) which relies on the temporary storage of signal using various load capacitances.

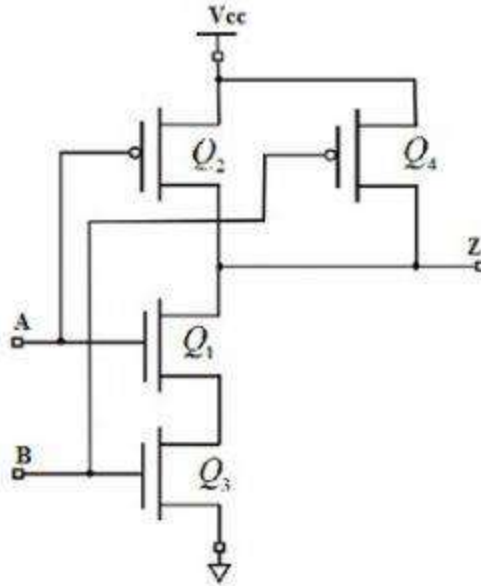
A static CMOS circuit is composed of two networks:

- pull-up network (PUN) - a set of PMOS transistors connected between V_{cc} and the output line
- pull-down network (PDN) - a set of NMOS transistors connected between GND and the output line

Components designed out pull-up and pull-down networks operate in a mutually exclusive way; in a steady state there is never a direct path between V_{cc} and GND. Devices that are made up of PUN/PDN are always strongly driven and therefore offers strong immunity from noise. When both the pull-up and pull-down networks are OFF, the result is high impedance. That state is important for memory elements, tristate bus drives, and various other components such as some multiplexers and buffers. When both the pull-up and pull-down networks are ON, the result is a crowbarred level. This result is typically an unwanted condition

CMOS NAND2 Gate-

- The below figure shows a 2-input Complementary MOS NAND gate. It consists of two series NMOS transistors between Y and Ground and two parallel PMOS transistors between Y and VDD.
- If either input A or B is logic 0, at least one of the NMOS transistors will be OFF, breaking the path from Y to Ground. But at least one of the PMOS transistors will be ON, creating a path from Y to VDD.



Two Input NAND Gate

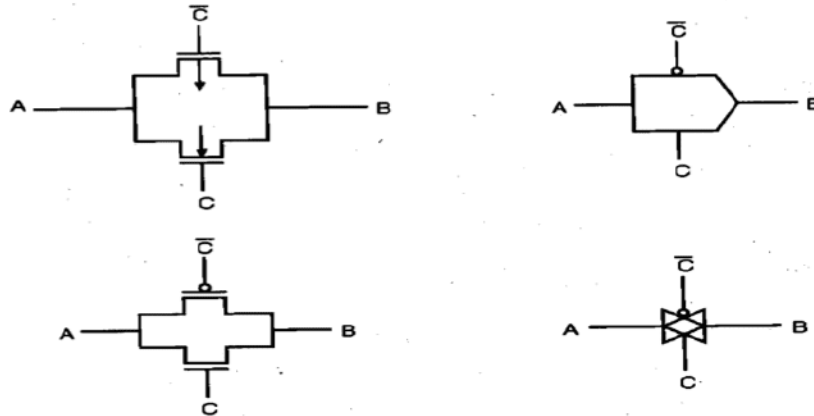
Hence, the output Y will be high. If both inputs are high, both of the nMOS transistors will be ON and both of the pMOS transistors will be OFF. Hence, the output will be logic low. The truth table of the NAND logic gate given in the below table.

A	B	Pull-Down Network	Pull-up Network	OUTPUT Y
0	0	OFF	ON	1
0	1	OFF	ON	1
1	0	OFF	ON	1
1	1	ON	OFF	0

CMOS TRANSMISSION GATES-

CMOS transmission gate consists of one NMOS and one PMOS transistor, connected in parallel. The gate voltages applied to these two transistors are also set to be complementary signals.

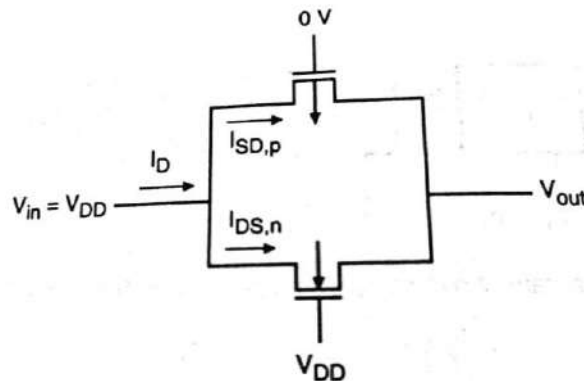
Symbols-



The CMOS transmission gate operates as a bidirectional switch between the nodes A and B which is controlled by signal C.

If the control signal C is

- (i) Logic high i.e, equal to V_{DD} , then both transistors are turned on and provide a low resistance current path between the nodes A and B.
- (ii) Logic low then both transistors will be off and the path between the nodes A and B will be an open circuit. This condition is called the high impedance state.



The substrate terminal of the NMOS transistor is connected to ground and the substrate terminal of the PMOS transistor is connected to V_{DD} .

C	A	B
0	0	High impedance State
0	1	High impedance State
1	0	0
1	1	1

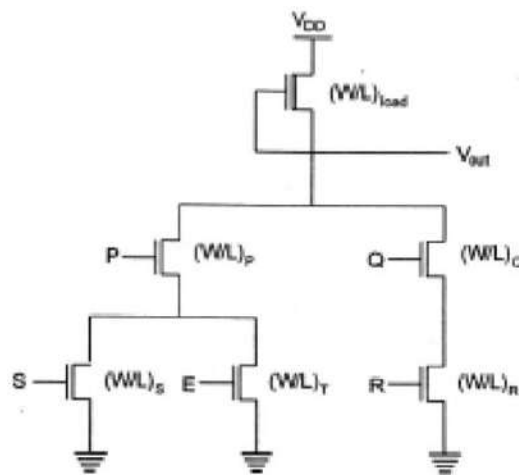
COMPLEX LOGIC CIRCUITS-

NMOS Depletion Load Complex Logic Gate

To realize complex functions of multiple input variables, the basic circuit structures and design principles developed for NOR and NAND can be extended to complex logic gates. The ability to realize complex logic functions, using a small number of transistors is one of the most attractive features of nMOS and CMOS logic circuits. Consider the following Boolean function as an example.

$$Z = (P(S+T) + QR)'$$

The nMOS depletion-load complex logic gate used to realize this function is shown in figure. In this figure, the left nMOS driver branch of three driver transistors is used to perform the logic function $P(S + T)$, while the right-hand side branch performs the function QR . By connecting the two branches in parallel, and by placing the load transistor between the output node and the supply voltage V_{DD} , we obtain the given complex function. Each input variable is assigned to only one driver.



Inspection of the circuit topology gives simple design principles of the pull-down network

- OR operations are performed by parallel-connected drivers.
- AND operations are performed by series-connected drivers.
- Inversion is provided by the nature of MOS circuit operation.

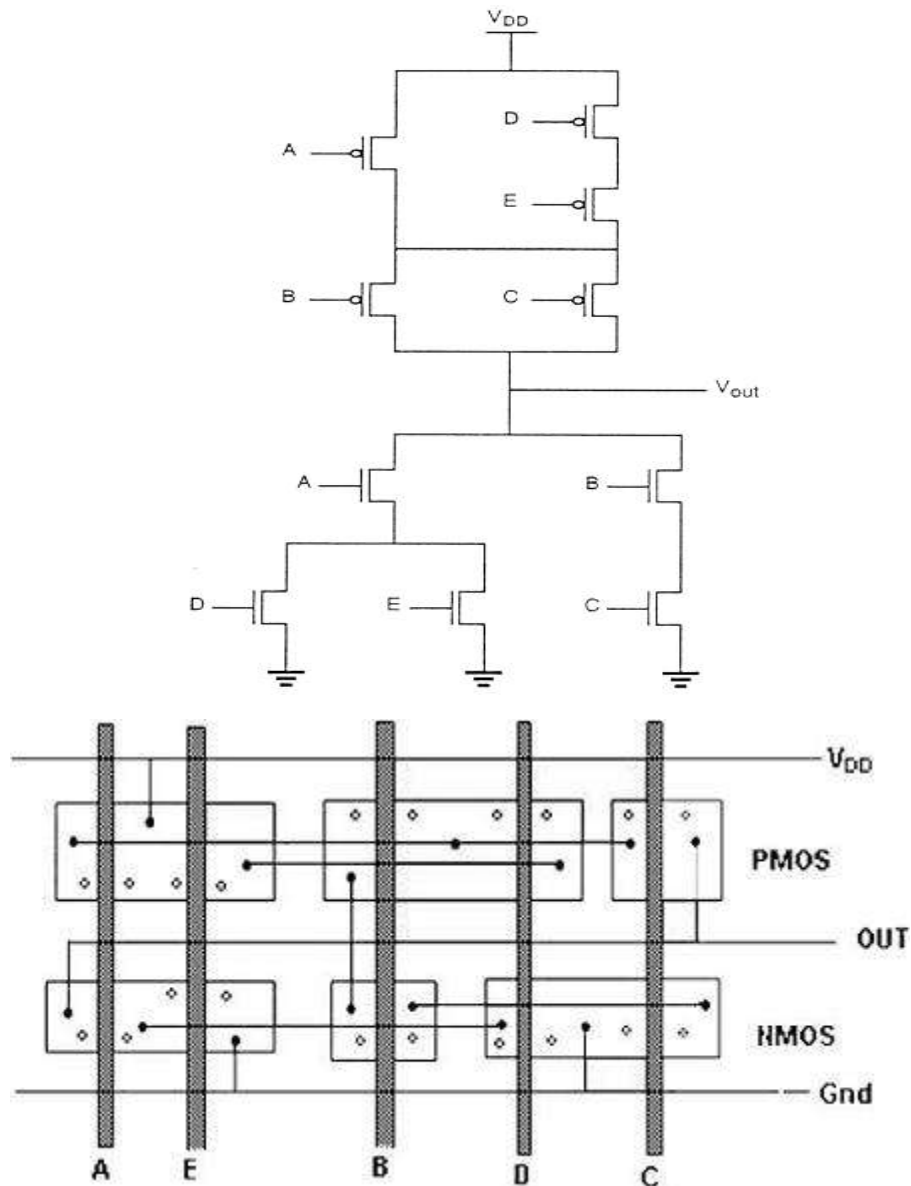
Complex CMOS Logic Gates-

The realization of the n-net, or pull-down network, is based on the same basic design principles examined for nMOS depletion-load complex logic gate. The pMOS pull-up network must be the dual network of the n-net.

It means all parallel connections in the nMOS network will correspond to a series connection in the pMOS network, and all series connection in the nMOS network correspond to a parallel connection in the pMOS network. The figure shows a simple construction of the dual p-net (pull-up) graph from the n-net (pull-down) graph.

Using an arbitrary ordering of the polysilicon gate columns-

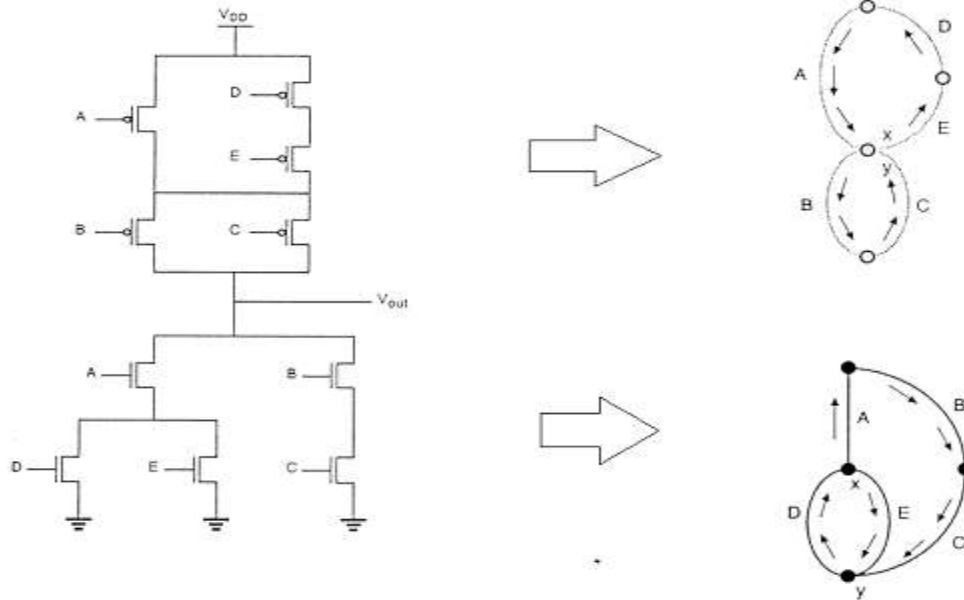
$$X = (A(D+E) + BC)'$$



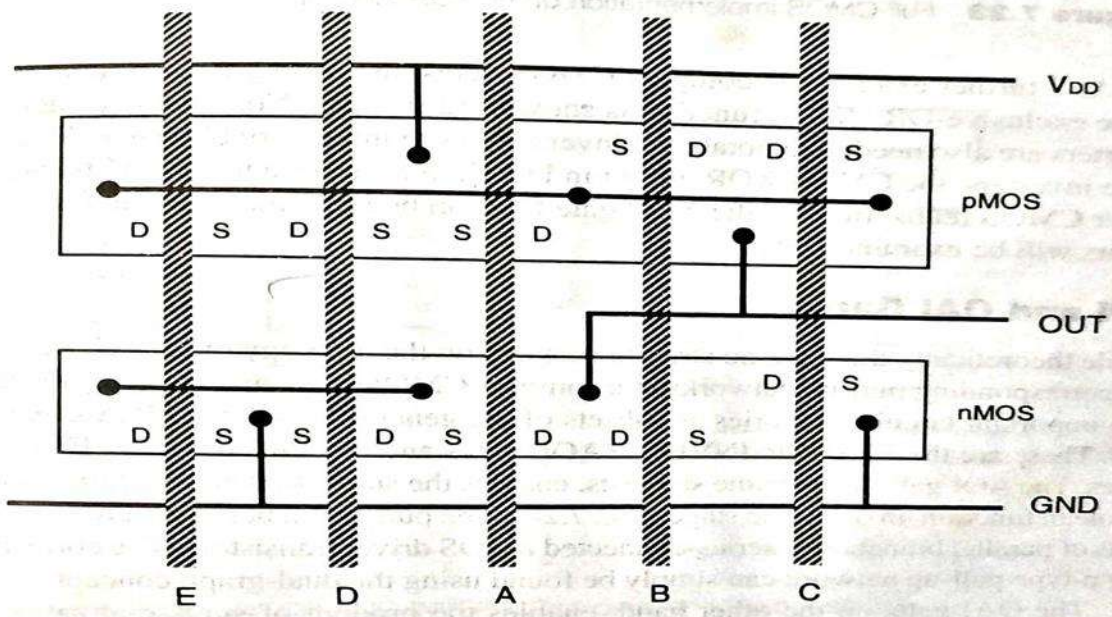
If we can minimize the number of diffusion area breaks both for NMOS and for PMOS transistors, the separation between the polysilicon gate columns can be made smaller, which will reduce the overall horizontal dimension and hence the circuit layout area. The number of diffusion breaks can be minimized by changing the ordering of the polysilicon columns.

A simple method for finding the optimum gate ordering is the Euler-path approach: find a Euler path in the pull down graph and a Euler path in the pull-up graph with identical ordering of input labels i.e, find a common Euler path for both graphs.

The Euler path is defined as an uninterrupted path that traverses each edge (branch) of the graph exactly once.

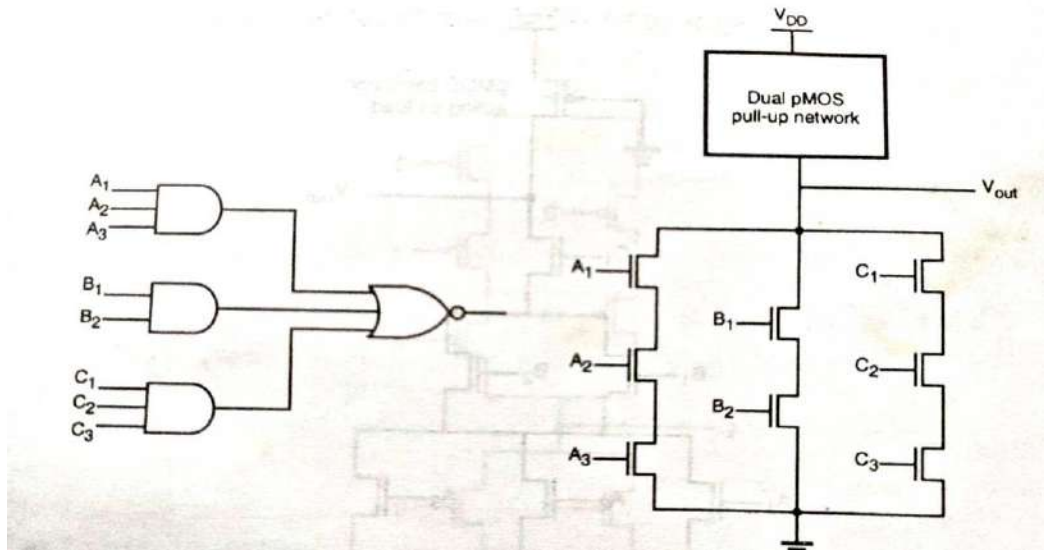


There is a common sequence (E-D-A-B-C) in both graphs i.e, a Euler path. The polysilicon gate columns can be arranged according to this sequence.

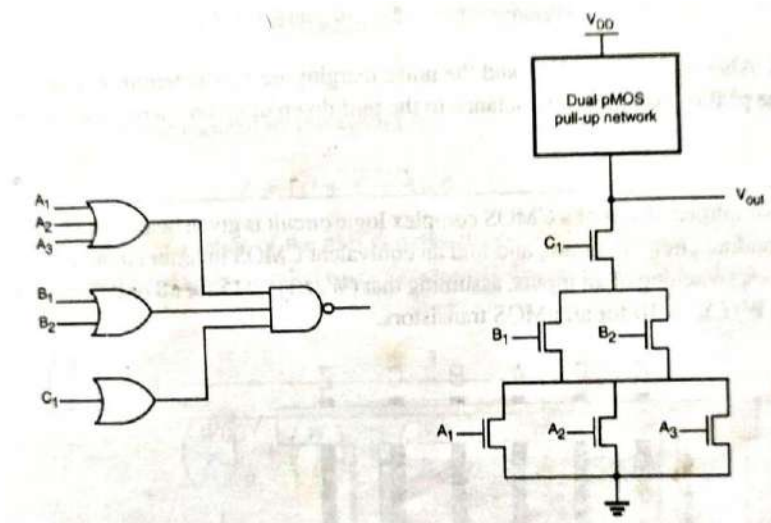


AOI and OAI gates-

- The AND-OR-INVERT (AOI) gate enables the sum of products realization of a Boolean function in one logic stage. The pull down network of the AOI gate consists of parallel branches of series connected NMOS driver transistors.

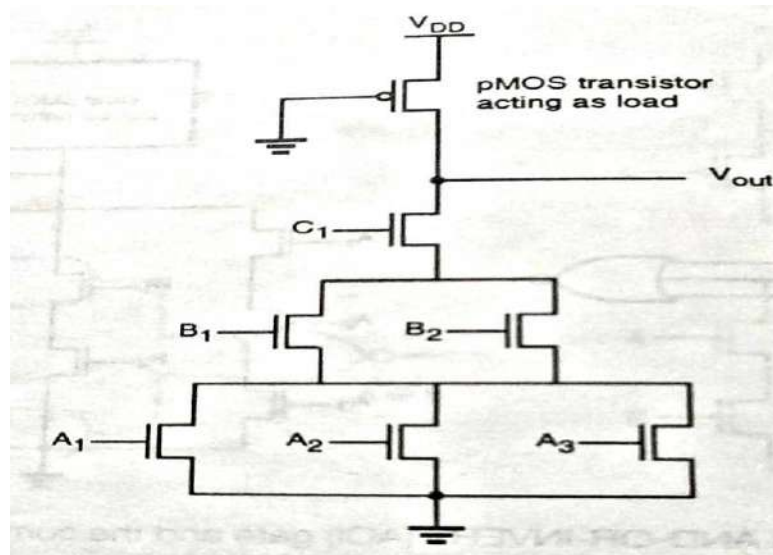


- The OAI gate, enables the product-of-sums realization of a Boolean function in one logic stage. The pull down network of the OAI gate consists of series branches of parallel connected NMOS driven transistors.



Pseudo-NMOS gates-

- The large area requirements of complex CMOS gates present a problem in high density designs, since two complementary transistors, one NMOS and one PMOS, are needed for every input.
- One possible approach to reduce the number of transistor is to use a single PMOS transistor, with its gate terminal connected to ground, as the load device.



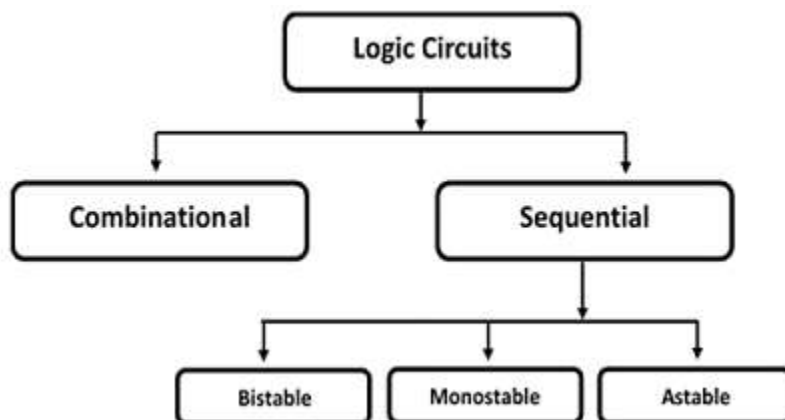
- With this simple pull up arrangement, the complex gate can be implemented with much fewer transistors.
- The disadvantages of using a pseudo NMOS gate instead of a full CMOS gate is the nonzero static power dissipation, since the always on PMOS load device conducts a steady state current when the output voltage is lower than V_{DD} .

CLASSIFICATION OF LOGIC CIRCUITS BASED ON THEIR TEMPORAL BEHAVIOUR-

Logic circuits are divided into two categories – (a) Combinational Circuits, and (b) Sequential Circuits.

In Combinational circuits, the output depends only on the condition of the latest inputs.

In Sequential circuits, the output depends not only on the latest inputs, but also on the condition of earlier inputs. Sequential circuits contain memory elements.



Sequential circuits are of three types –

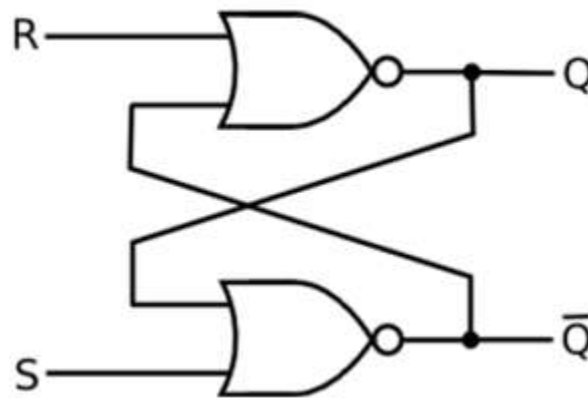
Bistable – Bistable circuits have two stable operating points and will be in either of the states. Example – Memory cells, latches, flip-flops and registers.

Monostable – Monostable circuits have only one stable operating point and even if they are temporarily perturbed to the opposite state, they will return in time to their stable operating point. Example: Timers, pulse generators.

Astable – Astable circuits have no stable operating point and oscillate between several states. Example – Ring oscillator.

SR LATCH CIRCUIT-

SR Latch based on NOR Gate-



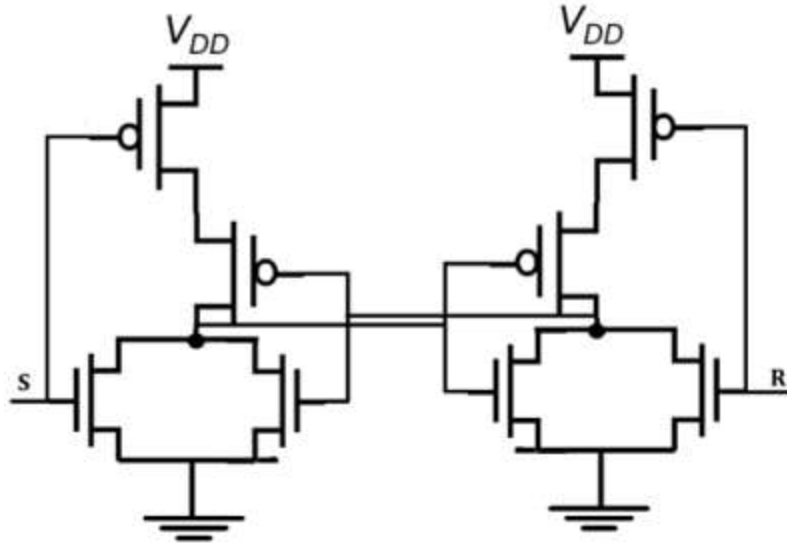
If the set input (S) is equal to logic "1" and the reset input is equal to logic "0." then the output Q will be forced to logic "1". While Q' is forced to logic "0". This means the SR latch will be set, irrespective of its previous state.

Similarly, if S is equal to "0" and R is equal to "1" then the output Q will be forced to "0" while Q' is forced to "1". This means the latch is reset, regardless of its previously held state. Finally, if both of the inputs S and R are equal to logic "1" then both output will be forced to logic "0" which conflicts with the complementarity of Q and Q'.

Therefore, this input combination is not allowed during normal operation. Truth table of NOR based SR Latch is given in table.

S	R	Q	Q'	Operation
0	0	Q	Q'	Hold
1	0	1	0	Set
0	1	0	1	Reset
1	1	0	0	Not allowed

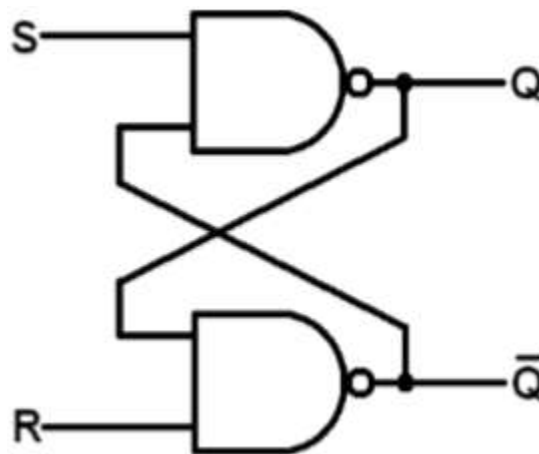
CMOS SR latch based on NOR gate is shown in the figure given below.



If the S is equal to V_{OH} and the R is equal to V_{OL} , both of the parallel-connected transistors M1 and M2 will be ON. The voltage on node Q' will assume a logic-low level of $V_{OL} = 0$.

At the same time, both M3 and M4 are turned off, which results in a logic-high voltage V_{OH} at node Q. If the R is equal to V_{OH} and the S is equal to V_{OL} , M1 and M2 turned off and M3 and M4 turned on.

SR Latch based on NAND Gate



Block diagram and gate level schematic of NAND based SR latch is shown in the figure. The small circles at the S and R input terminals represents that the circuit responds to active low input signals. The truth table of NAND based SR latch is given in table

S	R	Q	Q'	OPERATION
0	0	NC	NC	No change. Latch remained in present state.
1	0	1	0	Latch SET.

0	1	0	1	Latch RESET.
1	1	0	0	Invalid condition.

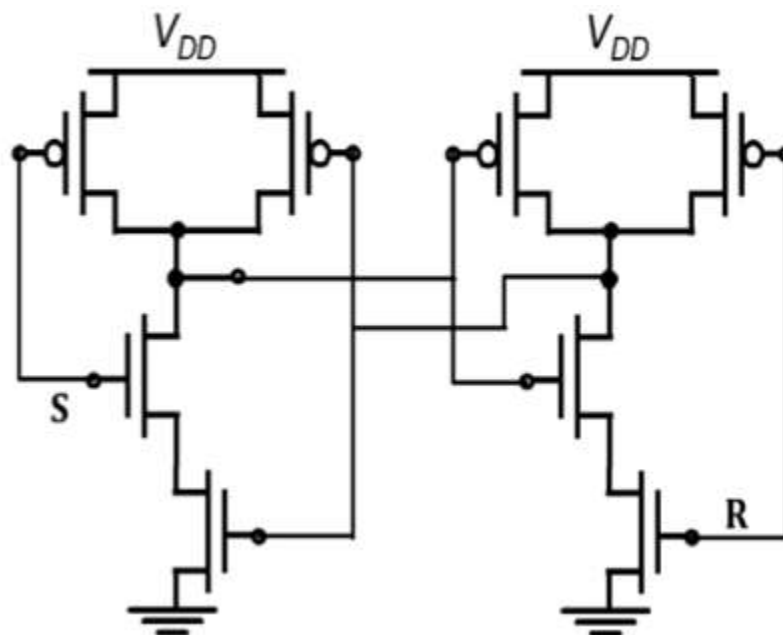
If S goes to 0 (while R = 1), Q goes high, pulling Q' low and the latch enters Set state

$$S = 0 \text{ then } Q = 1 \text{ (if } R = 1\text{)}$$

If R goes to 0 (while S = 1), Q goes high, pulling Q' low and the latch is Reset

$$R = 0 \text{ then } Q = 1 \text{ (if } S = 1\text{)}$$

Hold state requires both S and R to be high. If S = R = 0 then output is not allowed, as it would result in an indeterminate state. CMOS SR Latch based on NAND Gate is shown in figure.



Depletion-load nMOS SR Latch based on NAND Gate is shown in figure. The operation is similar to that of CMOS NAND SR latch. The CMOS circuit implementation has low static power dissipation and high noise margin.

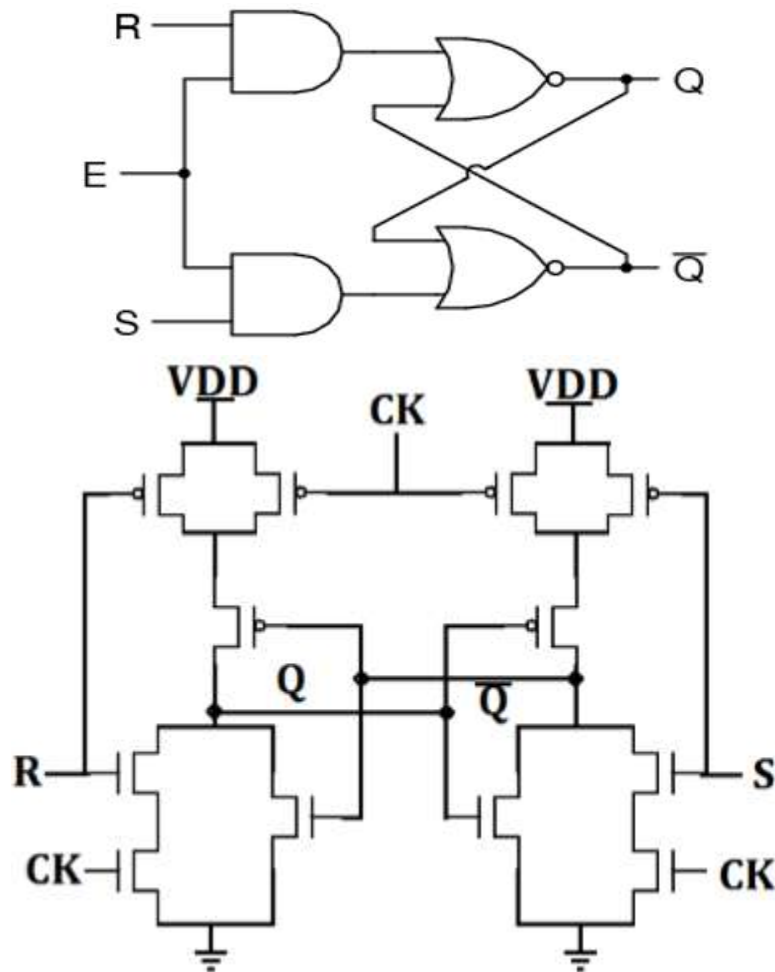
CLOCKED SR LATCH-

For synchronous operations the circuit response can be controlled by adding a gating clock signal to the circuit, so that the outputs will respond to the input levels only during the active period of a clock pulse.

If the clock (CK) is equal to logic "0", the input signals have no influence upon the circuit response. The outputs of the two AND gates will remain at logic "0", which forces SR latch to hold its current state regardless of the S and R input signals.

When the clock input goes to logic "1", the logic levels applied to the S and R inputs are permitted to reach the SR latch and possibly change its state.

With both inputs S and R at logic “1”, the occurrence of clock pulse causes both outputs to go momentarily to zero. When the clock pulse is removed i.e, when it becomes “0”, the state of the latch is undermined.



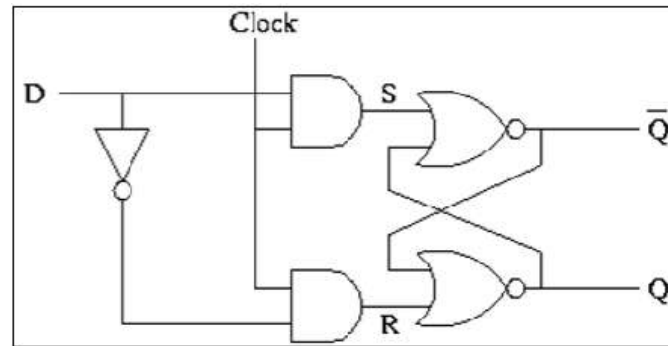
CMOS AOI implementation of clocked NOR based SR latch is shown in the figure. If this circuit is implemented with CMOS then it requires 12 transistors.

- When CLK is low, the latch retains its present state.
- When clock is high, the circuit becomes simply a NOR based CMOS latch which will respond to input S and R.

CMOS D LATCH-

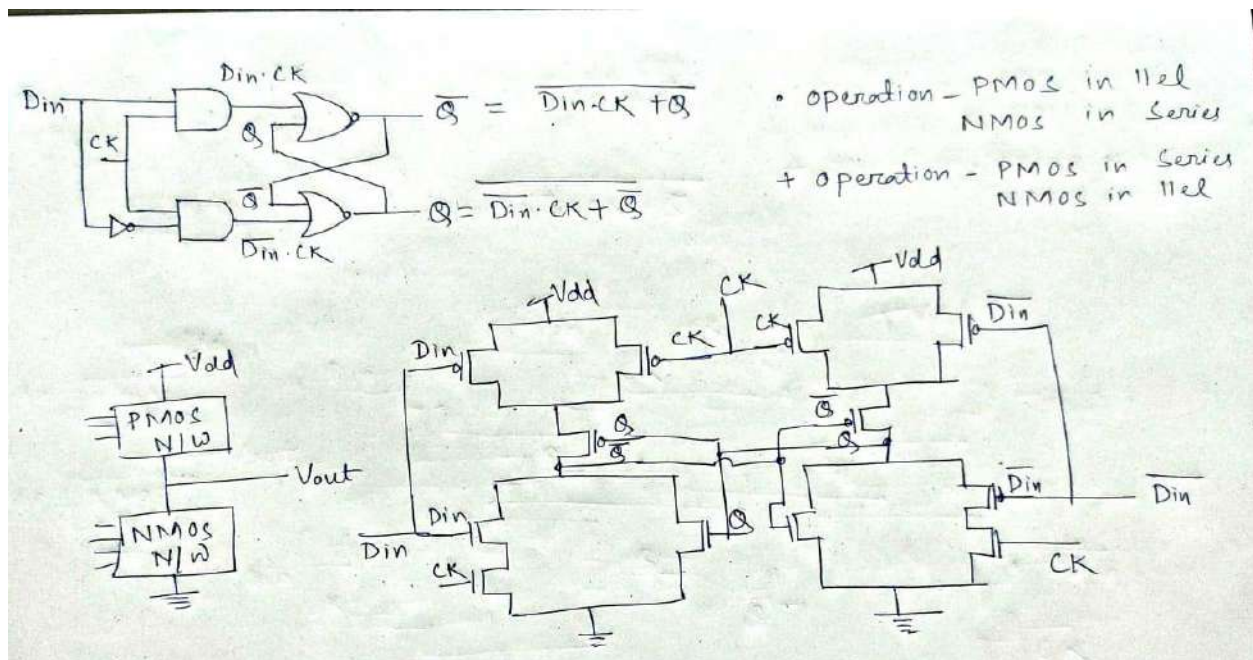
- The D latch is simply obtained by modifying the clocked NOR based SR latch circuit. Here, the circuit has a single input D, which is directly connected to the S input of the latch.
- The input variable D is also inverted and connected to the R input of the latch. The output Q assumes the value of the input D when the clock is active.

- When the clock signal goes to zero, the output will preserve its state. Thus the CK input acts as an enable signal which allows data to be accepted into the D latch.
- The D latch finds many applications mainly for temporary storage of data or as a delay element.



D latch using CMOS logic-

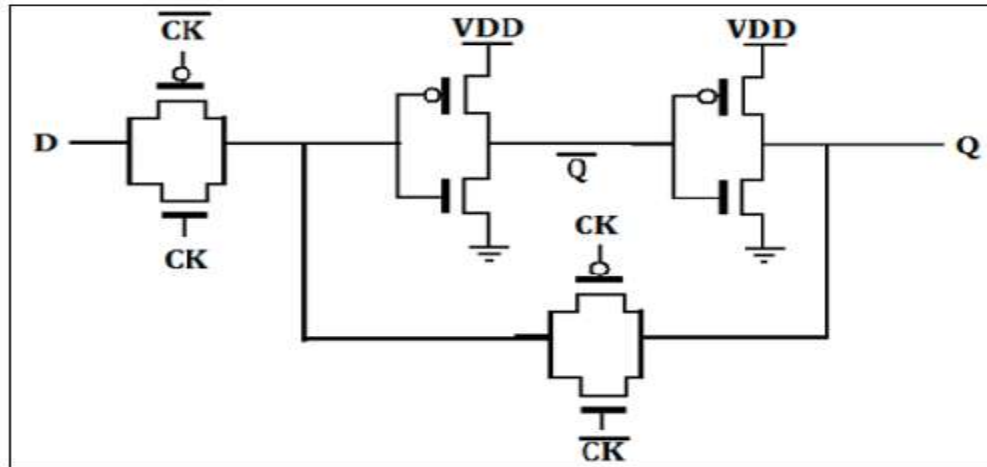
. If this circuit is implemented with CMOS then it requires 12 transistors.



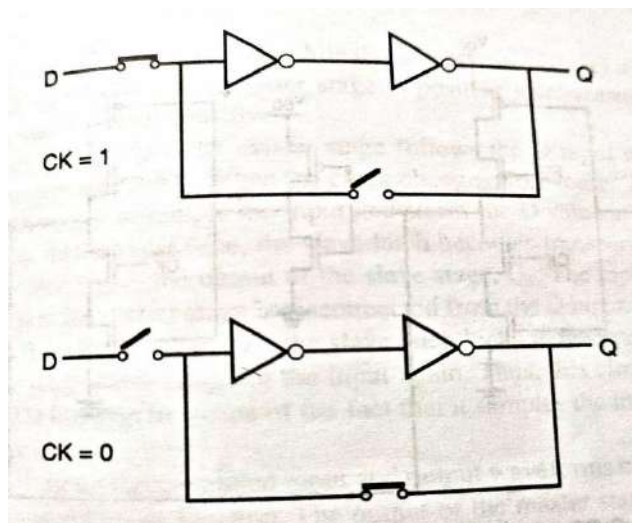
D latch using transmission gate-

The transmission gate at the input is activated by the CK signal, whereas the transmission gate in the inverter loop is activated by the inverse of the CK signal.

The input signal is accepted into the circuit when the clock is high and this information preserved as the state of the inverter loop when the clock is low.



The operation of the CMOS D latch circuit can be better visualized by replacing the CMOS transmission gates with simple switches.



BASIC PRINCIPLES OF DYNAMIC PASS TRANSISTOR CIRCUITS-

In static CMOS logic, logic function implemented using large no. of transistors and which may cause large time delay.

In a high performance digital implementations where reduction of circuit delay and silicon area is a major objective to achieve these dynamic logic circuits are used.

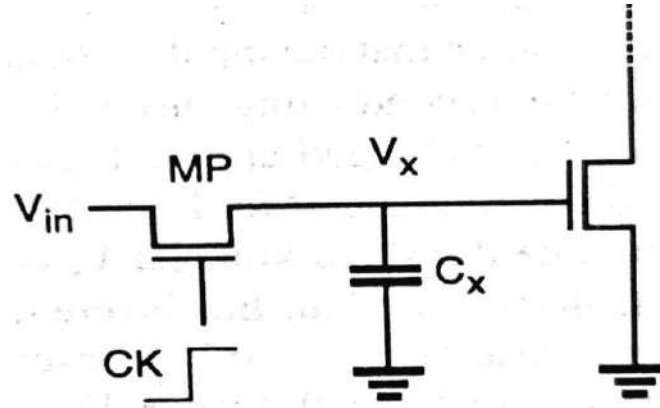
Here no. of transistor used decreases. The operation of all dynamic logic gates depends on temporary storage of charge in parasitic node capacitances.

Basic Principle

NMOS dynamic logic circuits, consisting of an NMOS pass transistor driving the gate of another NMOS transistor.

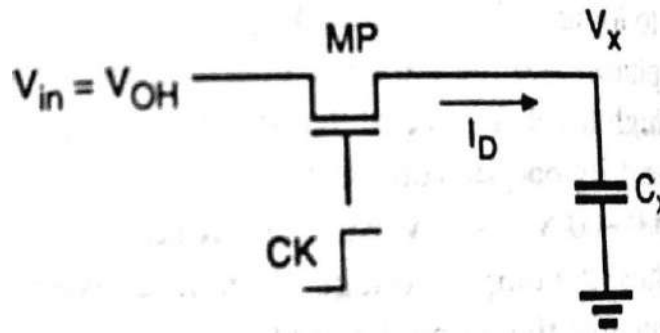
The pass transistor MP is driven by the periodic clock signal and acts as an access switch to either charge up or charge down the parasitic capacitance C_X , depending on the input signal V_{in} .

Thus, the two possible operations when the clock signal is active (CK = 1) are the logic “1” transfer and the logic “0” transfer.



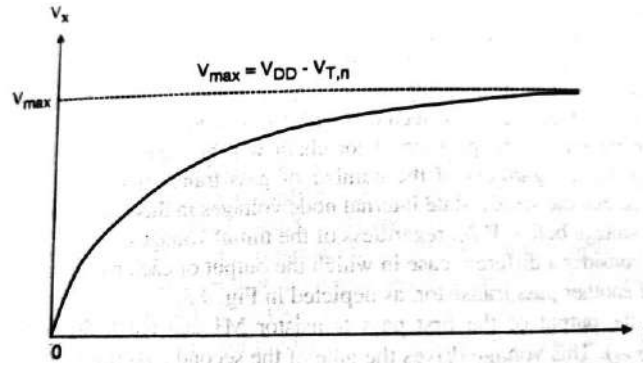
Logic “1” transfer-

Assume that the V_X node voltage is equal to 0 initially. A logic “1” level is applied to the input terminal, which corresponds to $V_{in} = V_{OH} = V_{DD}$. When the clock signal at the gate of the pass transistor becomes active, the pass transistor MP starts to conduct and that MP will operate in saturation.



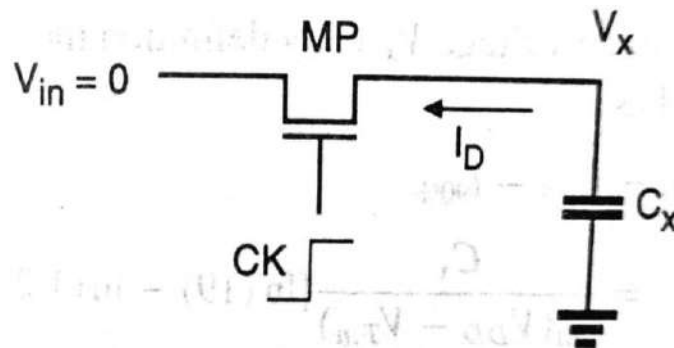
The voltage rises from its initial value of 0V and approaches a limit value for large t , but it cannot exceed its limit value of $V_{max} = V_{DD} - V_{T,n}$.

The pass transistor will turn off when $V_X = V_{max}$, since at this point, its gate to source voltage will be equal to its threshold voltage. Therefore the voltage at node X can never attain the full power supply voltage level of V_{DD} during the logic “1” transfer.

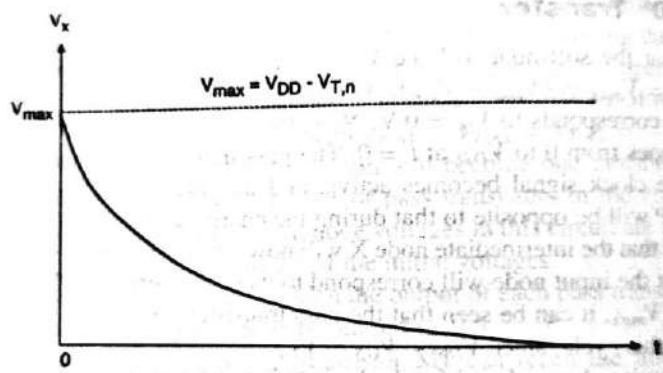


Logic “0” transfer-

Assume that the node voltage V_X is equal to a logic “1” level initially i.e, $V_X(t = 0) = V_{max} = (V_{DD} - V_{T,n})$. A logic “0” level is applied to the input terminal, which corresponds to $V_{in} = 0V$.



The pass transistor MP starts to conduct as soon as the clock signal becomes active and the direction of drain current flow through MP will be opposite to that during the charge up (logic “1” transfer).



RAM-

The read/write memory is commonly called Random Access Memory(RAM). Here the stored data is volatile i.e, the stored data is lost when the power supply voltage is turned off.

Based on the operation type of individual data storage cells, RAMs are classified into two categories-

1) Dynamic RAMs (DRAM)

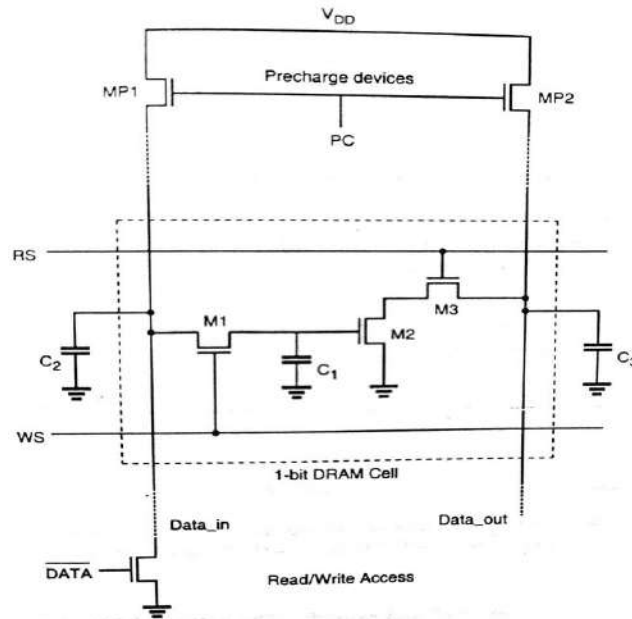
- The DRAM cell consists of a capacitor to store binary information, 1 or 0 and a transistor to access the capacitor.
- Cell information is degraded mostly due to a junction leakage current at the storage node. Therefore the cell data must be read and rewritten periodically (refresh operation) even when memory arrays are not accessed.
- Due to advantage of low cost and high density, DRAM is widely used for the main memory in personal and mainframe computers and engineering workstations

2) Static RAMs (SRAM)

- SRAM cell consists of a latch, therefore the cell data is kept as long as the power is turned on and refresh operation is not required.
- SRAM is mainly used for the cache memory in microprocessors, mainframe computers, engineering workstations due to high speed and low power consumption.

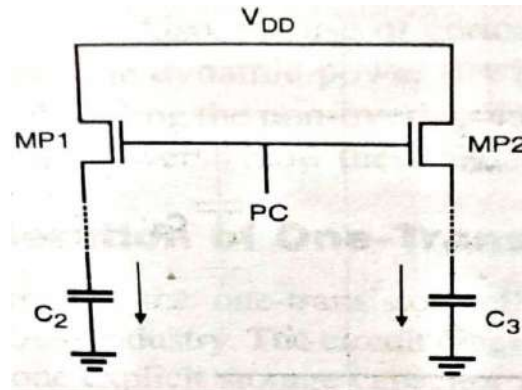
DYNAMIC RAM-

The binary information is stored in the form of charge in the parasitic node capacitance C_1 . The storage transistor M_2 is turned on or off depending on the charge stored in C_1 , and the pass transistors M_1 and M_3 act as access switches for data read and write operations.

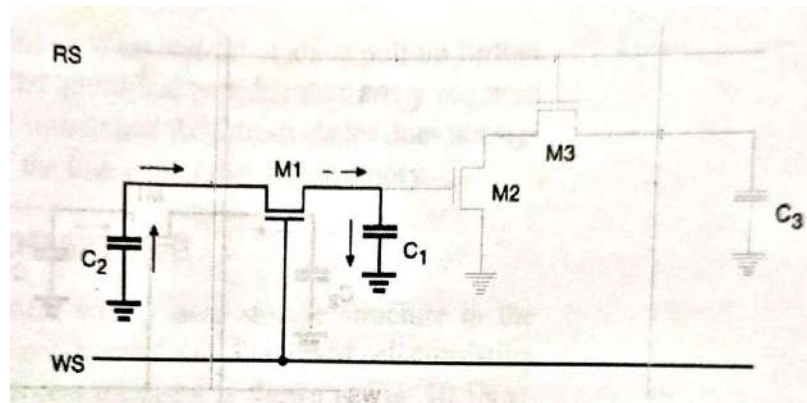


- The operation of the three transistor DRAM cell and the peripheral circuitry is based on a two phase non- overlapping clock scheme.
 - 1) The precharge events are driven by ϕ_1 .
 - 2) The “read” and “write” events are driven by ϕ_2 .

- Every “data read” and “data write” operation is preceded by a precharge cycle, which is initiated with the precharge signal PC going high.
- During the precharge cycle, the column pull up transistors are activated and the corresponding column capacitances C2 and C3 are charged up to logic high level.

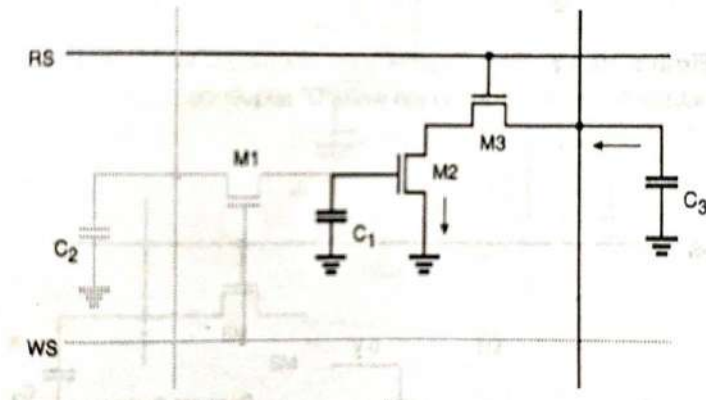


Write “1”-



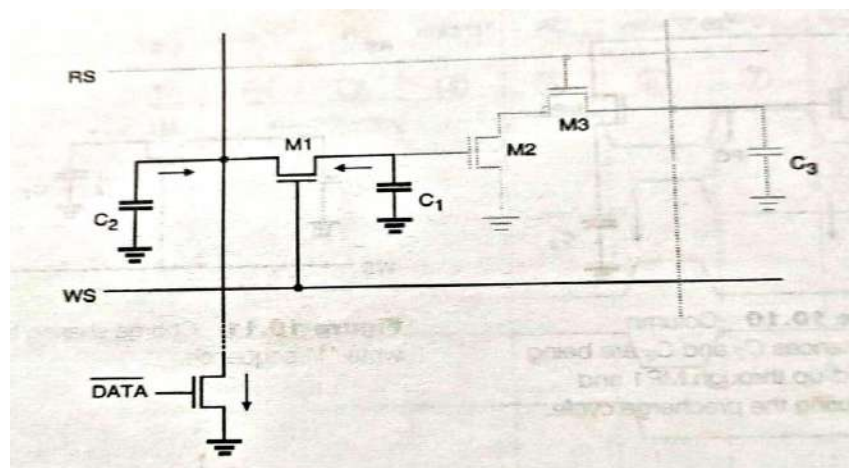
- The inverse data input is at the logic low level, because the data to be written onto the DRAM cell is logic “1”.
- The “write select” signal WS is pulled high during the active phase of ϕ_2 .
- The transistor M1 is turned on. With M1 conducting, the charge on C2 is shared with C1.
- Since the capacitance C2 is very large compared to C1, the storage node capacitance C1 attains approximately the same logic high level as the column capacitance C2 at the end of the charge sharing process.

Read “1”-



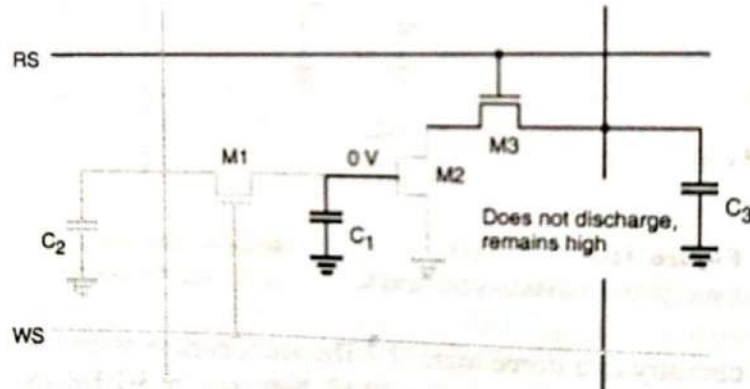
- With the storage node capacitance C_1 charged up to a logic high level, transistor M_2 is conducting.
- In order to read this stored "1", the "read select" signal RS pulled high during the active phase of ϕ_2 , following a precharge cycle.
- As the transistor M_3 turns on, M_2 and M_3 create a conducting path between the column capacitance C_3 and the ground.
- The capacitance C_3 discharges through M_2 and M_3 , and the falling column voltage is interpreted as a stored logic "1".

Write "0"-



- The inverse data input is at the logic high level, because the data to be written onto the DRAM cell is a logic "0".
- The "write select" signal WS is pulled high during the active phase of ϕ_2 , following a precharge cycle.
- As a result, the transistor M_1 is turned on. The voltage level on C_2 , as well as that on the storage node C_1 , is pulled to logic "0" through M_1 .
- At the end of the write "0" sequence, the storage capacitance C_1 contains a very low charge and the transistor M_2 is turned off since its gate voltage is approximately equal to zero.

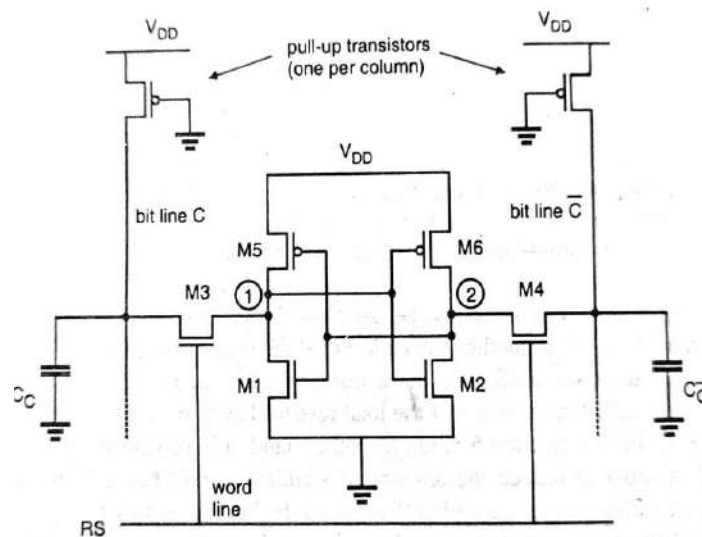
Read "0"-



- In order to read this stored “0”, the read select signal RS pulled high during the active phase ϕ_2 , following a precharge cycle.
- The transistor M3 turns on, but since M2 is off, there is no conducting path between the C3 and ground. So, C3 does not discharge and the logic high level on the D_{out} column is interpreted as a stored “0” bit.

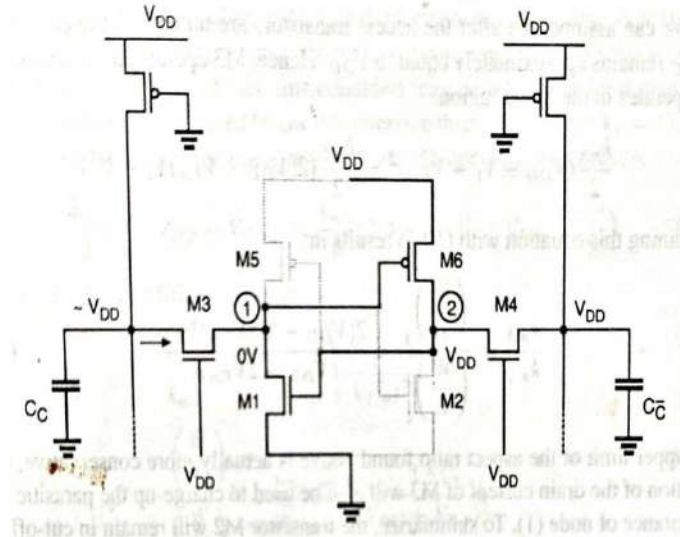
STATIC RAM (SRAM)-

A low power SRAM cell designed simply by using cross coupled CMOS inverters. The memory cell consists of a simple CMOS latch (two inverters connected back to back), and two complementary access transistors (M3 and M4).



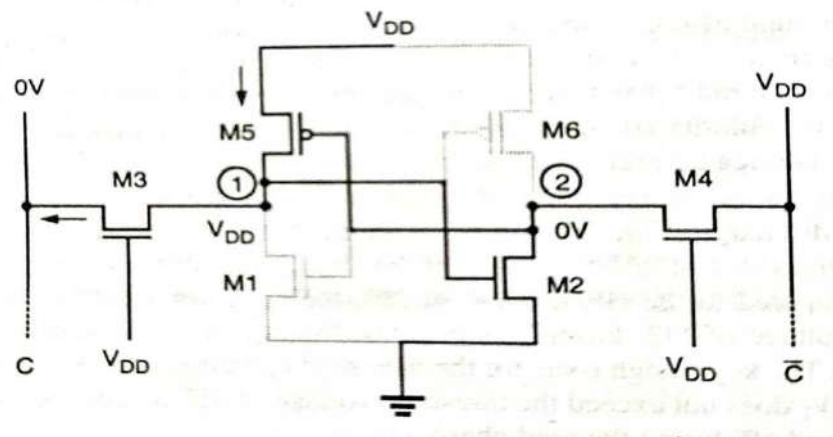
The cell will preserve one of its two possible stable states as long as the power supply is available. The access transistors are turned on whenever a word line is activated for read or write operation, connecting the cell to the complementary bit line columns.

Read “0” operation-



- Assuming that a logic “0” is stored in the cell. Here the transistors M2 and M5= off and M1 and M6= On (operate in linear mode).
- The internal node voltages are $V_1 = 0V$ and $V_2 = V_{DD}$ before M3 and M4 are turned on.
- The voltage level of column C' will not show any significant variation since no current flow through M4.
- On the other half of the cell, M3 and M1 will conduct a non-zero current and the voltage level of column C will begin to drop slightly.
- The capacitance C_c is very large, therefore the amount of decrease in the column voltage is limited to a few hundred millivolts during read phase.

Write “0” operation-



- Assuming that a logic “1” is stored in the SRAM cell initially. Here the transistors M1 and M6= off and M2 and M5= On (operate in linear mode).
- The internal node voltages are $V_1 = V_{DD}$ and $V_2 = 0V$ before M3 and M4 are turned on.

- The column voltage V_c is forced to logic “0” level by the data write circuitry. Once the pass transistors M3 and M4 are turned on, we expect that the node voltage V_2 remains below the threshold voltage of M1.
- To change the stored information i.e, to force V_1 to $0V$ and V_2 to V_{DD} , the node voltage V_1 must be reduced below the threshold voltage of M2. so that M2 turns off.
- Similarly read “1” and write “0” operation can be done.

Basic Requirements-

The two basic requirements which dictate the (W/L) ratios are-

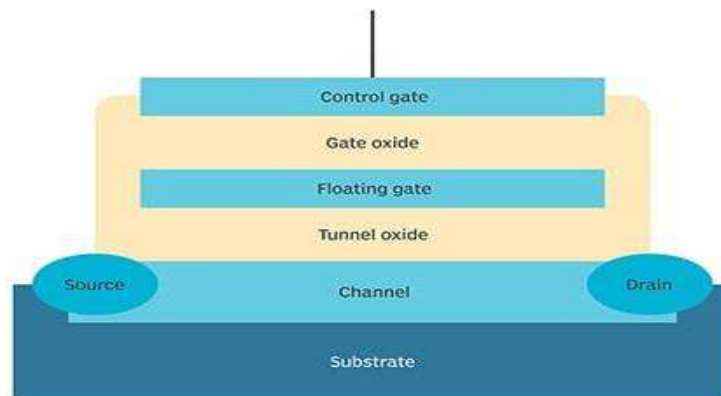
- (a) The data read operation should not destroy the stored information in the SRAM cell.
- (b) The cell should allow modification of the stored information during the data write phase.

Advantages-

- 1) The static power dissipation is very small.
- 2) High noise immunity due to larger noise margins and the ability to operate at lower power supply voltages.

FLASH MEMORY-

Flash memory is a non- volatile memory chip used for storage. Flash memory is a type of Electronically Erasable Programmable Read Only Memory (EEPROM).



In flash memory, each memory cell looks like standard MOSFET except that the transistor has two gates instead of one.

The cells can be seen as an electrical switch in which current flows between two terminals and is controlled by a floating gate and a control gate.

The control gate is similar to the gate in the MOS transistors, but below this there is the floating gate insulated all around by an oxide layer.

The Floating gate is electrically isolated by its insulating layer, electrons placed on it are trapped. This makes flash memory non-volatile.

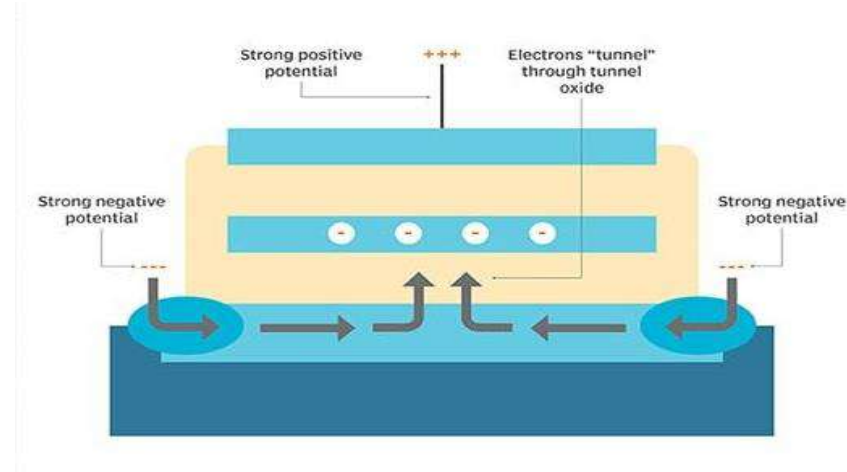
It works by adding or removing electrons to and from a floating gate. A bit "0" or "1" state depends upon whether or not the floating gate is charged or uncharged.

When electrons are present on the floating gate, current cannot flow through the transistor and the bit state is "0".

When electrons are removed from the floating gate, current is allowed to flow and the bit state is "1".

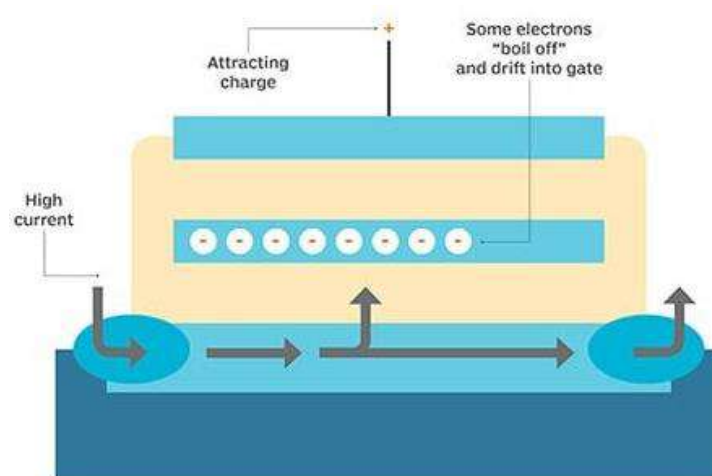
Two processes are used to add electrons in the floating gate:

1) Fowler Nordheim tunneling –



- It requires a strong electric field between negatively charged source and the positively charged control gate to draw electrons into the floating gate.
- The electrons move from the source through the thin oxide layer to the floating gate, where they are trapped between the oxide insulation layers.

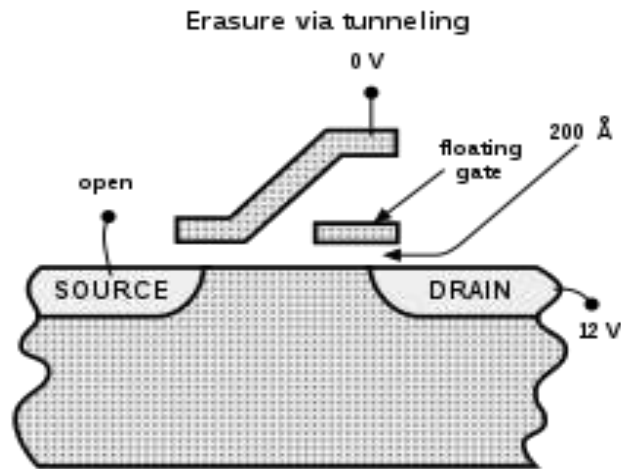
2) Hot electron injection-



- It uses a high current in the channel to give electrons sufficient energy to break through the oxide layer.

- A positive charge on the control gate attracts the electrons from the channel into the floating gate, where they become trapped.

Fowler-Nordheim tunneling is also used to remove electrons from the floating gate. A strong negative charge on the control gate forces electrons through the oxide layer into the channel, where the electrons are drawn to the strong positive charge at the source and the drain



Types of flash memory-

- 1) NOR flash memory
 - 2) NAND flash memory
- In both, memory cells are arranged differently. In a NAND memory chip, all floating gate MOSFETs are organized in series. Here bit line is pulled low only if all the word lines are pulled high.
 - In a NOR flash, at least one memory cell must conduct in order to pull down the bit line, because they are connected in parallel to ground.
 - NOR flash uses more space than NAND to save the same amount of information, since two flash cells share the same ground potential in this configuration. Therefore NAND is cheaper.
 - NOR memory needs less time to read a bit because of its direct access to individual cells.

UNIT-5

SYSTEM DESIGN METHOD & SYSTHESIS

DESIGN LANGUAGE-

Design languages are of two types. i.e, software programming languages (SPL) and hardware description languages (HDL). At one time, designers were either software or hardware designers. The design teams were clearly distinguished by their separate roles. Now a days designers are involved in both software and hardware design and need skills in both areas.

Software programming language allow a software designer to create executable software applications that will operate on a suitable processor. The target processor will be one of three type's microprocessor, microcontroller or digital signal processor.

Hardware Description Language (HDL) is a specialized computer language used to describe the structure and behavior of electronic circuits and most commonly digital logic circuits. A Hardware Description Language enables a precise formal description of an electronic circuit that allows for the automated analysis and simulation of an electronic circuit.

EDA TOOLS-

Electronic Design Automation (EDA) is a category of software tools for designing electronic systems such as printed circuit boards and integrated circuits. The tools work together in a design flow that chip designers use to design and analyze entire semiconductor chips. EDA is also referred to as electronic computer aided design (ECAD).

Some of the EDA tools are:

- 1) Cadence Virtuoso
- 2) Synopsys
- 3) Mentor Graphics
- 4) Xilinx
- 5) Tanner
- 6) Electric
- 7) Silvaco
- 8) Glade
- 9) Alliance

Some of these tools are open source and available for free. Some are licensed based for which you have to pay.

In the industrial environment, Cadence Virtuoso, Synopsys and Mentor Graphics are mostly used. To use these software's we have to purchase the license as they are not open source.

For learning purposes, we can use open source software tools like Electric, Alliance, Glade etc. we don't need to pay for them. We can download them free of cost.

VHDL-

VHDL stands for Very High Speed Integrated Circuits Hardware Description Language (VHSIC Hardware Description Language). It is a Hardware Description Language means it describes the behavior of a digital circuit and also it can be used to implement a digital circuit hardware.

It can be used for digital circuit synthesis as well as simulation. It is used to build digital system using Programmable Logic Device like CPLD or FPGA. VHDL program is used to implement digital circuit inside CPLD/ FPGA or it can be used to fabricate Application Specific Integrated Circuit.

VHDL PROGRAM STRUCTURE:

- All the VHDL programs consist of at least two components: Entity and Architecture. It may have additional components like configuration, package declaration, body etc. as per requirements.
- Let's take a Example-

```
library IEEE;
```

```
use IEEE.STD_LOGIC_1164.ALL;
```

```
entity and1 is
```

```
    Port ( a, b : in  STD_LOGIC;
```

```
          y : out  STD_LOGIC);
```

```
end and1;
```

```
architecture Behavioral of and1 is
```

```
begin
```

```
y<= a and b;
```

```
end Behavioral;
```

Library Declaration-

The library contains all the codes that is used frequently. It will allow us to reuse them again and again. Also this can be shared with other designs. It starts with keyword library followed by library name. There are three libraries usually used in all VHDL codes.

- IEEE- Specifies multilevel logic system.
- Std- Resource library for VHDL design environment.
- Work- Used for saving our project work and program file (.vhd).

But in program code, we need to declare only the IEEE library because the other two libraries are default libraries. To add library packages 'USE' keyword is used with library name, library packages and package parts.

In the IEEE library, the package is std_logic_1164 and to add all its part, we can write

```
library IEEE;
```

```
use IEEE.STD_LOGIC_1164.ALL;
```

Entity Declaration-

Entity defines input-output connections of the digital circuit with which it can interact with other circuit. It declares the no. of inputs given to the circuit and the no. of outputs taken out from the circuit. Also it declares any intermediate signals that are used within the circuit.

Entity declaration starts with the keyword ENTITY. The user has to give desire name to entity. Inside entity, input-output pins of a circuit are declared using keyword port. The entity declaration ends with keyword END followed by entity name.

Entity and1 is

```
Port (a, b: in STD_LOGIC;  
      y: out STD_LOGIC);
```

End and1;

Architecture-

Architecture declares the functionalities of the digital circuit. It gives internal details of an entity that means how input-output are interconnected.

The architecture declaration starts with keyword ARCHITECTURE followed by architecture name and entity name. The BEGIN keyword indicates the starting of the architecture body. The architecture body ends with keyword END followed by architecture name.

Architecture Behavioral of and1 is

Begin

```
y<= a and b;
```

End Behavioral;

XILINX PACKAGES-

During assigning packages, power requirement of a user need to be considered. For each device, suitable packages are chosen to handle its design and gate utilization. Sometimes without any external heat management, primary or internal heat removal casing works well due to proper choice of a package.

Day by day, the need arises for customers to utilize an FPGA device beyond typical design parameters. For these situations, only primary package not able to handle the heat removal without help of external heat management. Heat has to be removed from a device to ensure that the device is maintain within maximum temperature limits. If heat buildup becomes excessive, the device temperature might exceed its limits.

In addition to performance considerations, there is also the need to satisfy system reliability objectives by operating at a lower temperature. Failure mechanisms and failure rate of devices have an exponential dependence on the device's operating temperature. Thus the control of the package and extension device temperature is essential to ensure product reliability.

Electronic packages provide electrical interconnections between the IC & the board and efficient removal of heat generated by the device. Feature sizes are constantly shrinking, resulting in

increased number of transistors being packed into the device. Electronic packages must be flexible to address high pin counts, reduced pitch and form factor requirements.

Xilinx provides a wide range of leaded and array packaging solutions for advanced silicon products. Packages from Xilinx are designed, optimized and characterized to support the long term mechanical reliability requirements as well as to support the cutting edge electrical and thermal performance requirements for our high speed advanced FPGA products.

Modern high speed logic devices consume an appreciable amount of electrical energy. This energy invariably turns into heat. Higher device integration drives technologies to produce smaller device geometry and interconnections. With chip sizes getting smaller and circuit densities at their highest levels, the amount of heat generated on these fast switching CMOS circuits can be very significant.

CONCEPT OF FPGA WITH STANDARD CELL BASED DESIGN-

The cost of designing traditional standard cell based design is increasing every year. In addition to this development costs are increasing due to design complexity. Issues such as power requirement, signal integrity and manufacturing defects can add significant risk and time to market delays.

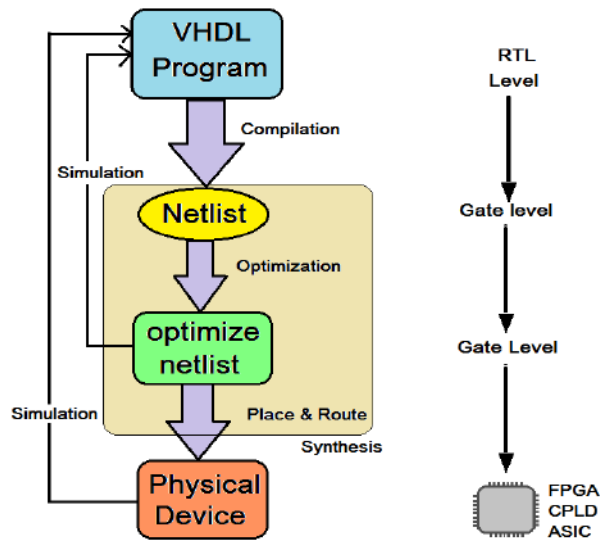
FPGAs offer a competitive and viable option to traditional standard cell ASIC development by reducing the risk of high costs and time to market delays etc. With the availability of multimillion gate FPGA architectures and support for various third party EDA tools, we can use a design flow similar to that of traditional standard cell ASIC devices to create system on a programmable chip designs in FPGAs.

With the device sizes and architectures that are available today, FPGAs can effectively implement systems that were once possible only in traditional standard cell ASICs. Because of their programmable capability FPGAs reduce the time to bring up a system as well as minimize the financial risk involved with new designs.

Cyclone series FPGAs provide a low cost alternative for applications that currently use low to moderate density traditional standard cell ASICs. Cyclone series FPGAs suitable for many applications like displays, wireless communication, video and image processing.

Stratix series FPGAs provide a good alternative to more complex traditional standard cell ASICs. These are high performance, high end FPGAs that have resources such as large internal memory, fast external memory interfaces, on chip Trans receivers etc.

VHDL FOR DESIGN SYNTHESIS USING CPLD OR FPGA-



1. VHDL design flow starts with writing the VHDL program. Various manufacturing companies like XILINX, Altera, etc. provide their own software development tools like XILINX ISE, Altera Quartus, etc. to edit, compile, and simulate VHDL code. In this VHDL code, the circuit is described in RTL (Resister Transfer Level)
2. This VHDL code is compiled, and it generates Netlist at Gate level. The compiler converts high-level VHDL code in RTL to Gate Level
3. This Netlist is further optimized to get optimized Netlist again at Gate Level. Optimization is done for better speed and less space. The simulation of design is done at this stage
4. Finally, a physical device is implemented on CPLD / FPGA, or final MASK is prepared for ASIC from this optimize Netlist by place and route software (fitter). once again the final device can be simulated and verified.

RASPBERRY PI-

Raspberry pi is the name of a series of single board computers made by the raspberry pi foundation, a UK charity that aims to educate people in computing and create easier access to computing education.

The Raspberry Pi launched in 2012 and there have been several versions released since then. The original Pi had a single- core 700 MHz CPU and just 256 MB RAM and the latest model has a quad-core 1.4 GHz CPU with 1 GB RAM.

All over the world, people use Raspberry Pi to learn programming skills, build hardware projects, do some automation and even use them in industrial applications. The Raspberry Pi is a very cheap computer that runs Linux, but it also provides a set of general purpose input/output pins that allow us to control electronic components for physical computing and explore the Internet Of Things (IOT).

There have been three generations of Raspberry Pi: Pi1, Pi2 and Pi3 and there has been a Model A and a Model B of most generations. Model A is a cheaper variant and tends to have reduced RAM and ports like USB and Ethernet. The Pi zero is a spinoff of the original generation, made even smaller and cheaper. The Raspberry Pi operates in the open source ecosystem. It runs Linux and its main supported operating system, Raspbian is open source software.

UNIT-6

INTRODUCTION TO EMBEDDED SYSTEM

SYSTEM:

- A System is a way of working organizing or doing one or many tasks according to a fixed plan, program or set of rules.
- A system is also an arrangement in which all its units assemble & work together according to the plan or program.

EMBEDDED SYSTEM:

- An embedded system is a system that has embedded software & hardware, which makes it a system dedicated for an application or specific part of an application or product or a part of a larger system.
- **Embedded system=programming in electronics.**

List of Embedded System:

Embedded system is found in a variety of common electronic devices such as:-

1. Consumer Electronics-

- Cell phones, pagers, digital cameras, video cassettes recorders, portable video games, calculators & personal digital assistants.

2. Home Appliances: -

- Microwave ovens, answering machines, thermostat, home security, washing machine, & lighting system.

3. Office Automation:-

- Printers, fax machine, photocopying machines, scanners, copier, biometric, surveillance cameras etc.

4. Business: -

- Cash register, alarm system, card reader, product scanner, curb side check in automated teller machine (ATM)

5. Automobiles:-

- Transmission control , cruise control, fuel injection, anti-lock brakes & reactive suspension
- Air bags, anti-lock braking system (ABS), engine control, door lock, GPS system, vehicular ad-hoc network (VANET)

6. Communication:-

- Mobile phone, network switches, WiFi, hotspots, telephone, MODEM etc.

Characteristics of Embedded System:-

Embedded system have several common characteristics

1. Single functional: -

- An embedded system usually executes only one program, repeatedly.

For Example: - a pager is always a pager

- It performs specialized operation & does the same job repeatedly.
- The Embedded system should perform the single given task throughout the life. This feature makes it dedicated & performs the accurately on time. A user of the system can't change the feature or functionality.

2. Tightly Constraint:-

- The circuit size should be small enough to fit on a single chip and must perform fast enough to process data in real time & consume minimum power to extend battery-life.

3. Reactive& Real time:-

- It should continuously react to the changes in the system environment and must compute certain results in real time without any delay
- A reactive system is reacting on a given input. Like in an oven when we press the button to start cooking, it takes input & start acting. This type of system is the reactive system
- But what happens if the oven responds in a random interval like some time it starts in 30 sec & sometime in 5 minutes. The point is there should be some time limit to start action. This is called **deadline**

Example of Embedded system:

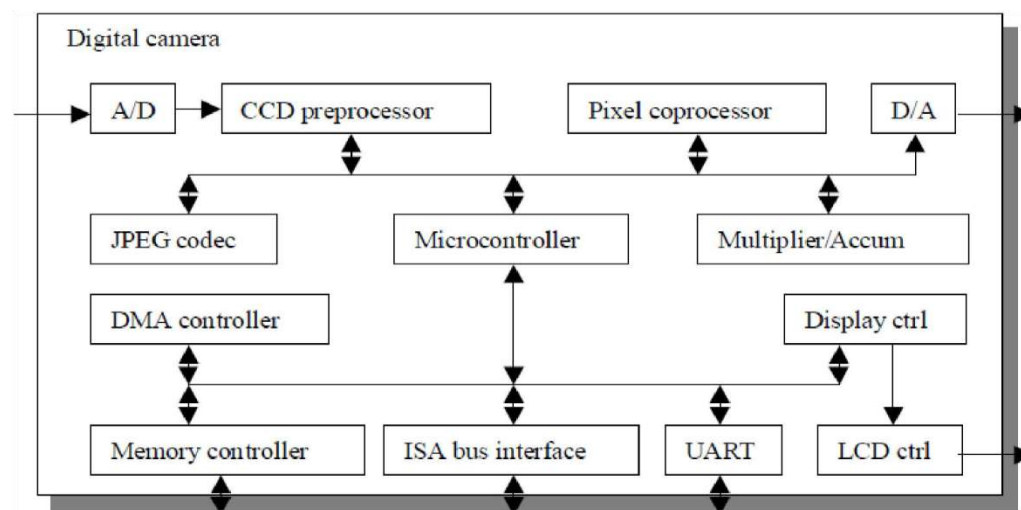
A DIGITAL CAMERA:- IMPORTANT

- The A2D and D2A circuits convert analog images to digital and digital to analog respectively.
- The CCD processor is a charge-coupled device pre-processor
- The JPEG codec compresses and decompresses an image using the JPEG2 compression standard, enabling compact storage in the limited memory of the camera.
- The pixel coprocessor aids in rapidly displaying images.

- The memory controller controls access to a memory chip also found in the camera, while the DMA controller enables direct memory access without requiring the use of the microcontroller.
- The UART enables communication with a PC's serial port for uploading video frames, while the ISA bus interface enables a faster connection with a PC's ISA bus.
- The LCD ctrl and Display ctrl circuit control the display of images on the camera's liquid-crystal display device.
- A multiplier/Accum circuit assists with certain digital signal processing.
- The heart of the system is a **microcontroller**, which is a processor that controls the activities of all the other circuit. Each device as a processor designed for a particular task, while the microcontroller is a more general processor designed for general tasks.

➤ **This example illustrates some of the embedded system characteristics described above.**

- It performs a single function repeatedly. This system always acts as a digital camera, where in it captures. Compresses and stores frames, decompresses and display frames, and uploads frames.
- It is tightly constrained. The system must be low cost since consumer must be able to afford such a camera it must be small so that it fits within a standard- sized camera. It must be fast so that it can process numerous images in millisecond. It must consume little power so that the camera's battery will last a long time.
- This particular system does not possess a high degree of the characteristics of being reactive and real time, as it only needs to responds to the pressing of buttons by a user, Which even for an avid photographer is still quite slow with respect to processor speeds.



EMBEDDED SYSTEM TECHNOLOGIES:-

- Technology as a manner of accomplishing a task, especially using technical process, methods or knowledge.
- There are three technologies in the embedded system design:
 1. Processor technologies
 2. IC technologies
 3. Design technologies

PROCESSOR TECHNOLOGY:-

- Processor technology involves the architecture of the computation engine used to implement a system's desired functionality.
- The term processor often linked to programmable software processors may also be used in association with several other non-programmable, digital systems.
- These processors vary in their specialization towards a particular application (for e.g. Mobile phones, radio, computer) and by doing so exhibit a variety of design metric.
- An embedded processor can be classified into 3 different forms on the basis of functionality.
 - General purpose processor
 - Special purpose processor
 - Application specific processor

GENERAL PURPOSE PROCESSORS--SOFTWARE:

- The general –purpose processor is designed to serve several applications with the idea of being able to sell the maximum number of devices.
- One feature of such a processor is a program memory-the designer does not know what program will run on the processor, so the program cannot be inserted with a digital circuit.
- Another feature is a general data path this should have the capacity to handle a variety of computations-thus it will have large register file with additional general purpose arithmetic logic unit (ALU).
- An embedded system simply uses a general-purpose processor, by programming the processor's memory to carry out the required functionality.

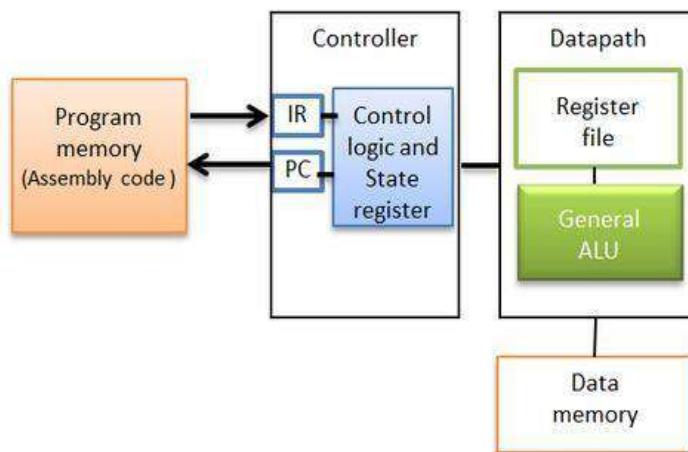
 **Using a general-purpose processor in an embedded system may result in several design-merit advantages.**

1. Design time and NRE (non-recurring engineering)→

- One time cost to design, develop, manufacture.
- Cost is low, because the designer has to only write a program and any digital design is not necessary.
- 2. **Flexibility**→ is high, because changing functionality requires only changing the program.
- 3. **Units cost** may be relatively low in small quantities, since the processor manufacture sells large quantities to customers.
- 4. **Performance** may be fast for computation-intensive applications, if using a fast processor, due to advanced architecture features and leading edge IC technology.

✚ **There are also some design-merit drawbacks.**

1. **Unit cost**→ may be too high for large quantities.
2. **Performance**→ may be slow for certain applications.
3. **Size and power**→ may be large due to unnecessary processor hardware.

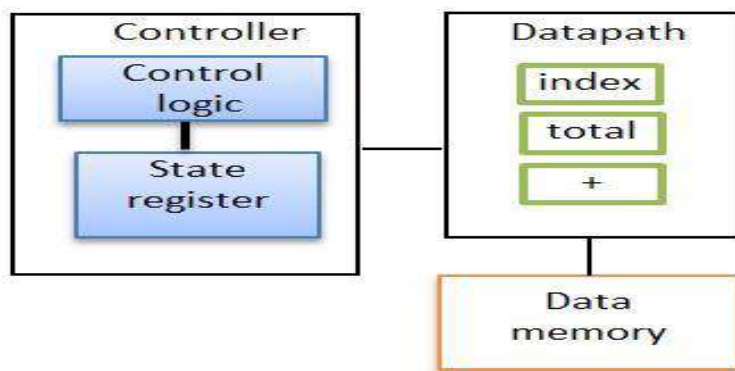


- Diagram shows a simple architecture of a general-purpose processor implementing the array summing functionality.
- The functionality is stored in a program memory.
- The controller fetches the current instructions, as indicated by the program counter (PC) into the instruction register (IR).
- It then configures the data path for these instructions and executes the instruction.
- Finally, it determines the appropriate next instruction address, sets the PC to this address, and fetches again.

SINGLE PURPOSE PROCESSOR--HARDWARE:

- A single-purpose processor is a digital circuit designed to execute exactly one program.
- **For example:** -consider the digital camera. All of the components other than the microcontroller are single-purpose processor. The JPEG codec, for example executes a single program that compresses and decompresses video frames.

- An embedded system creates a single-purpose processor by designing a custom digital circuit.
- Using a single-purpose processor in an embedded system result in several design metric benefits and drawbacks, which are essentially the inverse of those for general purpose processors.
- Performance may be fast, size and power may be small, and unit-cost may be low for large quantities, while design time and NRE cost may be high, flexibility is low, unit cost may be high for small quantities and performance may not match general purpose processor for some applications.



The architecture of such a single-purpose processor

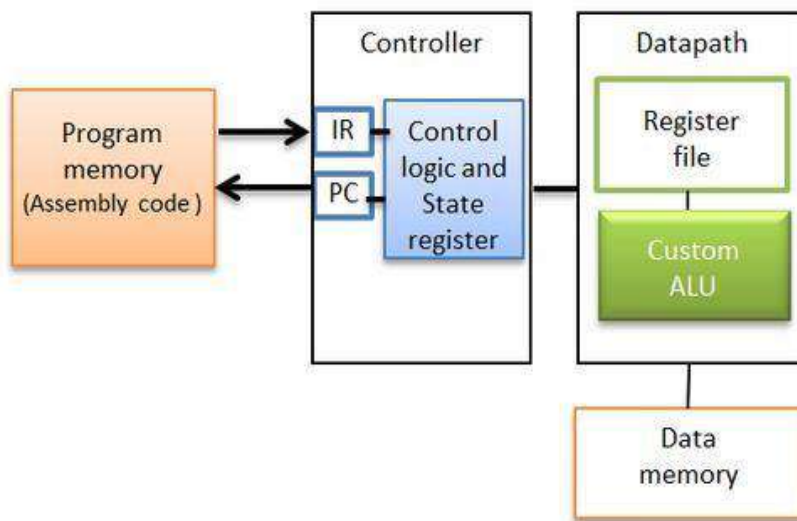
- For example, since the example counts from 1 to N, we add an index register.
- The index register will be loaded with N, and will then count down to zero ('0'), at which time it will assert a status line read by the controller.
- The example has only one other value, we add only one register labeled total to the data path.
- Since the example's only arithmetic operation is addition, we add a single adder to the data path.
- Since the processor only executes this one program, we hardware the program directly into the control logic.

APPLICATION SPECIFIC PROCESSORS:-

- An application-specific instruction-set processor (or ASIP) can serve as a compromise between the other processor.
- An ASIP is designed for a particular class of applications with common characteristics, such as digital-signal processing, telecommunications, embedded control, etc.

- An ASIP in an embedded system can provide the benefit of flexibility while still achieving good performance, power and size.
- Such processors can require large NRE cost to build the processor itself.

The Block diagram of an application specific processor is given below. You can see there is no program memory in this. It is designed for particular types of input.



MICROCONTROLLERS:-

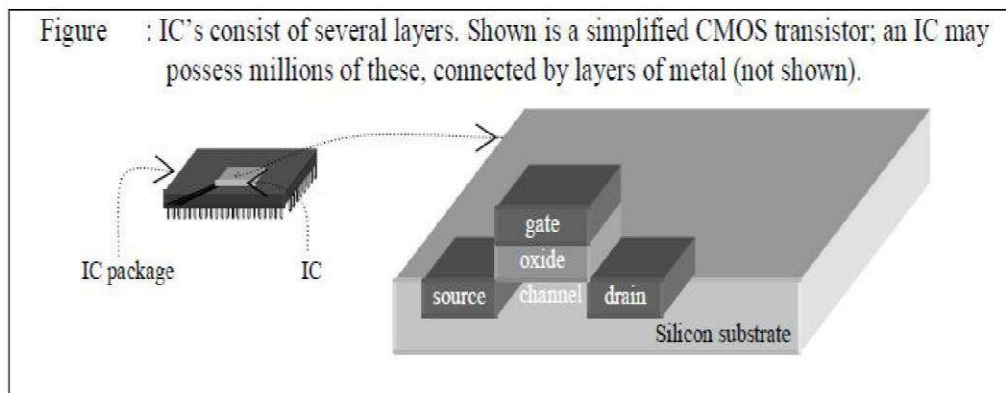
- Microcontroller is a microprocessor that has been optimized for embedded a control applications.
- Such applications typically monitor and set numerous single bit control signals but do not perform large amount of data computations. Thus microcontrollers tend to have simple data paths that excel bit-level operations and reading and writing external bits.
- Furthermore, they tend to incorporate on the microprocessor chip several peripheral components common in control applications like serial communication peripherals, timers, counters, pulse width modulators and analog to digital converters. Such incorporation of peripherals enables single chip implementations and hence smaller and lower cost product.

DIGITAL SIGNAL PROCESSING (DSP):-

- Digital-signal processors (DSPs) are a common class of ASIP.
- A DSP is a processor designed to perform common operations on digital signals, which are the digital encodings of analog signals like video and audio. These operations carry out common signal processing tasks like signal filtering, transformation, or combination.
- Such operations are usually math-intensive, including operations like multiply and add or shift and add.
- To support such operations, a DSP may have special purpose datapath components such a multiply-accumulate unit, which can perform a computation like $T = T + M[i]*k$ using only one instruction.
- The use of an ASIP, while partially customized to the desired functionality, there is some inefficiency since the processor also contains features to support reprogramming.
- The datapath may be customized. It may have an auto-incrementing register, a path that allows the add of a register plus a memory location in one instruction, fewer registers, and a simpler controller.

IC TECHNOLOGY:-

- Every processor must eventually be implemented on an IC.
- An IC (Integrated Circuit), often called a “chip,” is a semiconductor device consisting of a set of connected transistors and other devices.
- A number of different processes exist to build semiconductors, the most popular of which is CMOS (Complementary Metal Oxide Semiconductor).
- Semiconductors consist of numerous layers as shown in the figure given below.



- The bottom layers form the transistors. The middle layers form logic gates. The top layers connect these gates with wires. These layers can be created by depositing photo-sensitive chemicals on the chip surface and then shining light through masks to change regions of the

chemicals. A set of masks is often called a layout. The narrowest line that we can create on a chip is called the feature size.

Full Custom / VLSI:-

- In a full-custom IC technology, we optimize all layers for our particular embedded system's digital implementation.
- Such optimization includes placing the transistors to minimize interconnection lengths, sizing the transistors to optimize signal transmissions and routing wires among the transistors.
- Once all the masks are completed, then we send the mask specifications to a fabrication plant that builds the actual ICs.
- Full-custom IC design, often referred to as VLSI (Very Large Scale Integration) design, has very high NRE cost and long turnaround times (typically months) before the IC becomes available, but can yield excellent performance with small size and power.
- It is usually used only in high-volume or extremely performance-critical applications.

SEMICUSTOM ASIC (GATE ARRAY AND STANDARD CELL):

- In an ASIC (Application-Specific IC) technology, the lower layers are fully or partially built, leaving us to finish the upper layers.
- In a gate array technology, the masks for the transistor and gate levels are already built (i.e., the IC already consists of arrays of gates).
- The remaining task is to connect these gates to achieve our particular implementation.
- In a standard cell technology, logic-level cells (such as an AND gate or an AND-ORINVERT combination) have their mask portions pre-designed, usually by hand.
- Thus, the remaining task is to arrange these portions into complete masks for the gate level, and then to connect the cells.
- ASICs are by far the most popular IC technology, as they provide for good performance and size, with much less NRE cost than full-custom IC's.

PLD:

- In a PLD (Programmable Logic Device) technology, layers implement a programmable circuit, where programming has a lower-level meaning than a software program.
- The programming that takes place may consist of creating or destroying connections between wires that connect gates, either by blowing a fuse, or setting a bit in a programmable switch.

- Small devices, called programmers, connected to a desktop computer can typically perform such programming.
- PLD's of two types, simple and complex. One type of simple PLD is a PLA (Programmable Logic Array), which consists of a programmable array of AND gates and a programmable array of OR gates.
- Another type is a PAL (Programmable Array Logic), which uses just one programmable array to reduce the number of expensive programmable components.
- One type of complex PLD, growing very rapidly in popularity over the past decade, is the FPGA (Field Programmable Gate Array), which offers more general connectivity among blocks of logic, rather than just arrays of logic as with PLAs and PALs, and is thus able to implement far more complex designs. PLDs offer very low NRE cost and almost instant IC availability.
- They are typically bigger than ASICs, may have higher unit cost, may consume more power, and may be slower (especially FPGAs). They still provide reasonable performance, though, so are especially well suited to rapid prototyping.